ADC32RF72 Dual Channel 1.5GSPS 16-bit RF Sampling ADC

1 Features

- 16-bit, dual channel 1.5GSPS ADC
- Noise spectral density: -163.7dBFS/Hz
- Thermal Noise: 75.6dBFS
- Noise figure: 14.4dB
- Single core (non-interleaved) ADC architecture
- Aperture jitter: 40fs
- Buffered analog inputs
- Input fullscale: 1.44Vpp (4.1dBm)
- Full power input bandwidth (-3dB): 1.8GHz
- Ultra-low close-in residual phase noise:
  - −140dBc/Hz at 10kHz offset at 1GHz
- Spectral performance (f_{IN} = 1GHz, -1dBFS):
  - SNR_{flat}: 72.1dBFS
  - HD2,3: 68dBc
  - Non HD2,3: 93dBFS
- 192-tap/ch programmable FIR equalizer filter
- 12-bit Fractional delay filter
- Digital down-converters (DDCs)
  - Up to 8 DDC
  - Complex output: /2, /3, /4, /5 to /32768 decimation
  - 48-bit NCO phase coherent frequency hopping
  - Fast frequency hopping: < 1µs
- JESD204B/C serial data interface
  - Maximum lane rate: 24.75Gbps
- Code error rate (CER): 1E-15 errors/sample
- Power consumption: 1.5W/channel (1.5GSPS)

2 Applications

- Phased array radar
- Wafer Inspection
- Spectrum analyzer
- Software defined radio (SDR)
- Electronic warfare
- High-speed digitizer
- Cable infrastructure
- Communications infrastructure

3 Description

The ADC32RF72 is a 16-bit, 1.5GSPS (non-interleaved), dual channel analog to digital converter (ADC). The device is designed for the highest signal-to-noise ratio (SNR) and delivers a noise spectral density of −163.7dBFS/Hz. Using internal averaging modes, the NSD can be improved to as low as -166.2dBFS/Hz. The buffered analog inputs support a programmable internal termination impedance of 50, 100, 200Ω with a full power input bandwidth of 1.8GHz (−3dB). The device lets the user select one input from IN1/2/3 in addition to IN0.

The device includes several digital processing features such as a 192-tap/ch programmable FIR filter for equalization, a 12-bit fractional delay filter as well as multiple digital down converters (DDCs). There are eight DDCs supporting decimation factors of /2, /3 and /5 up to /32768. The 48-bit NCOs support phase coherent frequency hopping.

The ADC32RF72 supports the JESD204B/C serial data interface with interface rates up to 24.75Gbps. The power efficient ADC architecture consumes 1.5W/ch at 1.5GSPS and provides power scaling with lower sampling rates.

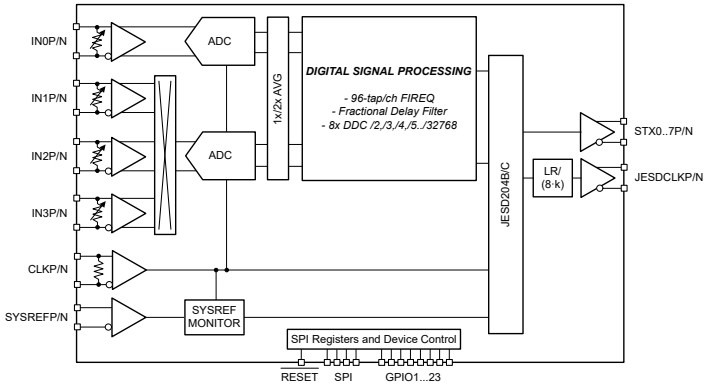
Package Information

PART NUMBER	PACKAGE(1)	PACKAGE SIZE(2)
ADC32RF72	FCCSP	13.8mm x 13.8mm

(1) For more information, see Section 11.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.

Device Comparison

PART NUMBER	# OF CHANNELS
ADC32RF72	2
ADC34RF72	4



Block Diagram

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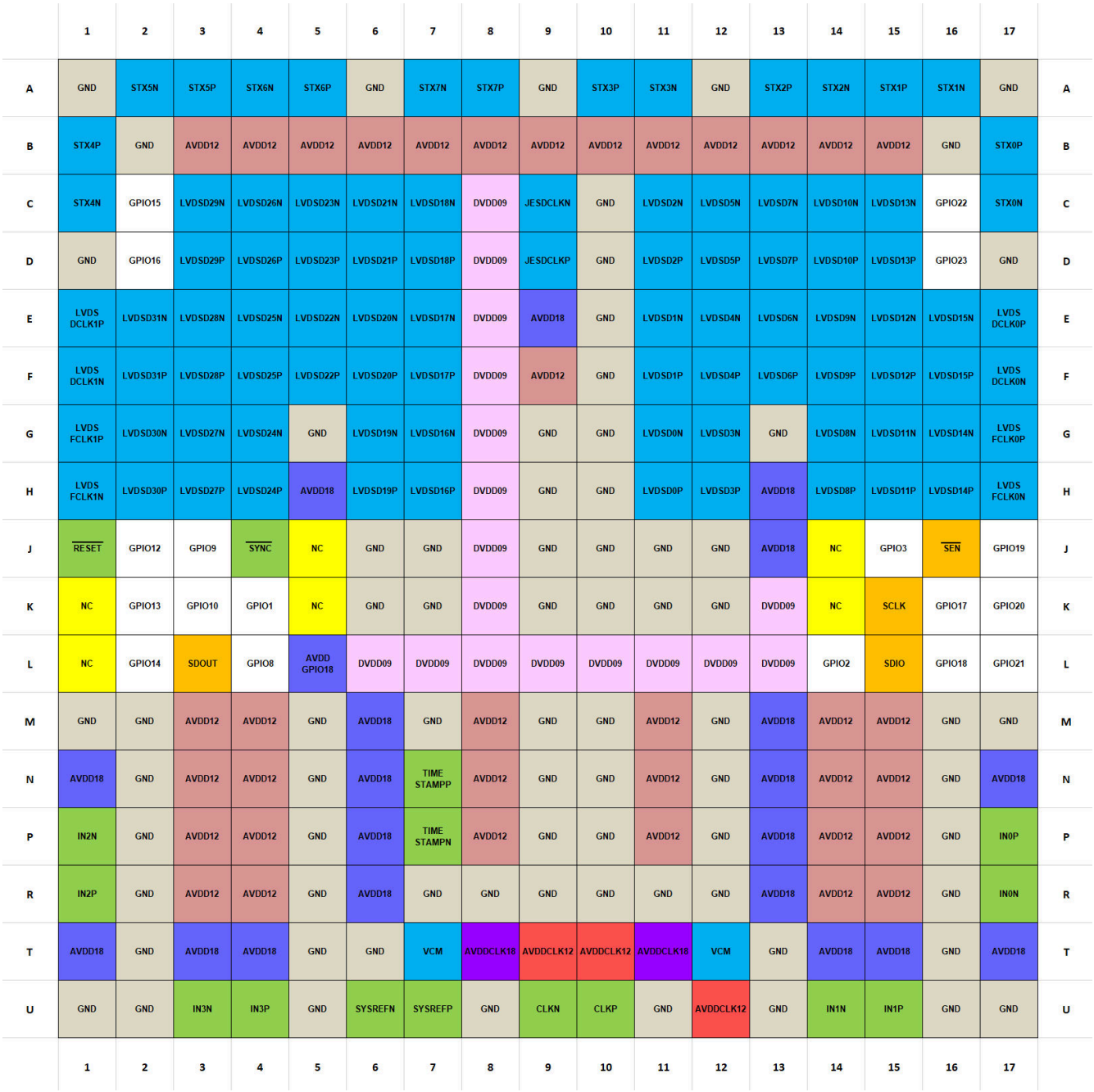
4 Pin Configuration and Functions



	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	
A	GND	STX5N	STX5P	STX6N	STX6P	GND	STX7N	STX7P	GND	STX3P	STX3N	GND	STX2P	STX2N	STX1P	STX1N	GND	A
B	STX4P	GND	AVDD12	AVDD12	AVDD12	AVDD12	AVDD12	AVDD12	AVDD12	AVDD12	AVDD12	AVDD12	AVDD12	AVDD12	AVDD12	GND	STX0P	B
C	STX4N	GPIO15	LVDSD29N	LVDSD26N	LVDSD23N	LVDSD21N	LVDSD18N	DVDD09	JESDCLKN	GND	LVDSD2N	LVDSD5N	LVDSD7N	LVDSD10N	LVDSD13N	GPIO22	STX0N	C
D	GND	GPIO16	LVDSD29P	LVDSD26P	LVDSD23P	LVDSD21P	LVDSD18P	DVDD09	JESDCLKP	GND	LVDSD2P	LVDSD5P	LVDSD7P	LVDSD10P	LVDSD13P	GPIO23	GND	D
E	LVDS DCLK1P	LVDSD31N	LVDSD28N	LVDSD25N	LVDSD22N	LVDSD20N	LVDSD17N	DVDD09	AVDD18	GND	LVDSD1N	LVDSD4N	LVDSD6N	LVDSD9N	LVDSD12N	LVDSD15N	LVDS DCLK0P	E
F	LVDS DCLK1N	LVDSD31P	LVDSD28P	LVDSD25P	LVDSD22P	LVDSD20P	LVDSD17P	DVDD09	AVDD12	GND	LVDSD1P	LVDSD4P	LVDSD6P	LVDSD9P	LVDSD12P	LVDSD15P	LVDS DCLK0N	F
G	LVDS FCLK1P	LVDSD30N	LVDSD27N	LVDSD24N	GND	LVDSD19N	LVDSD16N	DVDD09	GND	GND	LVDSD0N	LVDSD3N	GND	LVDSD8N	LVDSD11N	LVDSD14N	LVDS FCLK0P	G
H	LVDS FCLK1N	LVDSD30P	LVDSD27P	LVDSD24P	AVDD18	LVDSD19P	LVDSD16P	DVDD09	GND	GND	LVDSD0P	LVDSD3P	AVDD18	LVDSD8P	LVDSD11P	LVDSD14P	LVDS FCLK0N	H
J	$\overline{\text{RESET}}$	GPIO12	GPIO9	$\overline{\text{SYNC}}$	NC	GND	GND	DVDD09	GND	GND	GND	GND	AVDD18	NC	GPIO3	$\overline{\text{SEN}}$	GPIO19	J
K	NC	GPIO13	GPIO10	GPIO1	NC	GND	GND	DVDD09	GND	GND	GND	GND	DVDD09	NC	SCLK	GPIO17	GPIO20	K
L	NC	GPIO14	SDOUT	GPIO8	AVDD GPIO18	DVDD09	DVDD09	DVDD09	DVDD09	DVDD09	DVDD09	DVDD09	DVDD09	GPIO2	SDIO	GPIO18	GPIO21	L
M	GND	GND	AVDD12	AVDD12	GND	AVDD18	GND	AVDD12	GND	GND	AVDD12	GND	AVDD18	AVDD12	AVDD12	GND	GND	M
N	AVDD18	GND	AVDD12	AVDD12	GND	AVDD18	TIME STAMPP	AVDD12	GND	GND	AVDD12	GND	AVDD18	AVDD12	AVDD12	GND	AVDD18	N
P	IN2N	GND	AVDD12	AVDD12	GND	AVDD18	TIME STAMPN	AVDD12	GND	GND	AVDD12	GND	AVDD18	AVDD12	AVDD12	GND	IN0P	P
R	IN2P	GND	AVDD12	AVDD12	GND	AVDD18	GND	GND	GND	GND	GND	GND	AVDD18	AVDD12	AVDD12	GND	IN0N	R
T	AVDD18	GND	AVDD18	AVDD18	GND	GND	VCM	AVDDCLK18	AVDDCLK12	AVDDCLK12	AVDDCLK18	VCM	GND	AVDD18	AVDD18	GND	AVDD18	T
U	GND	GND	IN3N	IN3P	GND	SYSREFN	SYSREFP	GND	CLKN	CLKP	GND	AVDDCLK12	GND	IN1N	IN1P	GND	GND	U
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	

Figure 4-1. 289-Ball Flip Chip BGA (Top View)

Table 4-1. Pin Functions

PIN		TYPE (1)	DESCRIPTION
NAME	NO.		
AVDD12	B3,B4,B5,B6,B7,B8,B9, B10,B11,B12,B13,B14,B15,F9, M3,M4,M8,M11,M14, M15,N3,N4,N8,N11,N14, N15,P3,P4,P8,P11,P14, P15,R3,R4,R14,R15	P	Analog 1.2V supply. Low noise LDO recommended.

Table 4-1. Pin Functions (continued)

PIN		TYPE (1)	DESCRIPTION
NAME	NO.		
AVDDCLK12	T9, T10, U12	P	Clock power supply, 1.2V. Low noise LDO recommended
AVDD18	E9,H5,H13,J13,M6,M13, N1,N6,N13,N17,P6,P13, R6,R13,T1,T3,T4,T14,T15, T17	P	Analog 1.8V supply. Low noise LDO recommended
AVDDCLK18	T8, T11	P	Clock power supply, 1.8V. Low noise LDO recommended
AVDDGPIO18	L5	P	1.8V power supply for GPIO pins.
CLKN, CLKP	U9, U10	I	Differential clock input. Internal differential 100Ω termination and self bias to common mode voltage of 0.7V. Must be AC coupled externally.
DVDD09	C8, D8, E8, F8,G8, H8, J8, K8, K13, L6,L7, L8, L9, L10, L11, L12, L13	P	Digital power supply, 0.9V. Switching DC/DC regulator is recommended.
GND	A1,A6,A9,A12,A17,B2,B16, C10,D1,D10,D17,E10,F10,G5, G9,G10,G13,H9,H10, J6,J7,J9,J10,J11,J12,K6, K7,K9,K10,K11,K12,M1, M2,M5,M7,M9, M10,M12, M16,M17,N2,N5,N9,N10, N12,N16,P2,P5,P9,P10, P12,P16,R2,R5,R7,R8, R9,R10,R11,R12,R16,T2, T5,T6,T13,T16,U1,U2, U5,U8,U11,U13,U16,U17	G	Ground, 0V
GPIO1, GPIO2, GPIO3	K4, L14, J15	I/O	The GPIO pins can be assigned different functions using SPI writes. See Section 7.5.1.
GPIO8, GPIO9, GPIO10	L4, J3, K3,	I/O	
GPIO12 to GPIO23	J2, K2, L2, C2, D2, K16,L16, J17, K17, L17, C16, D16	I/O	
IN0N, IN0P	R17, P17	I	Differential analog input, ch 0. Internal programmable 50, 100 and 200Ω termination.
IN1N, INIP	U14, U15	I	Differential analog input, ch 1. Internal programmable 50, 100 and 200Ω termination.
IN2N, IN2P	P1, R1	I	Differential analog input, ch 2. Internal programmable 50, 100 and 200Ω termination.
IN3N, IN3P	U3, U4	I	Differential analog input, ch 3. Internal programmable 50, 100 and 200Ω termination.
JESDCLKN, JESDCLKP	C9, D9	O	Differential JESD output clock. LVDS logic levels. Can be configured to serdes lane rate divided by (8x k). By default this feature is powered down and pins can be left floating. This output clock is derived directly from the internal SerDes PLL and does not provide deterministic latency.
LVDSDCLK0N, LVDSDCLK0P	F17, E17	O	Differential LVDS bit clock output. Not yet supported in software. Leave as 'No Connect'
LVDSDCLK1N, LVDSDCLK1P	F1, E1	O	
LVDSFCLK0N, LVDSFCLK0P	H17, G17	O	Differential LVDS frame clock output. Not yet supported in software. Leave as 'No Connect'
LVDSFCLK1N, LVDSFCLK1P	H1, G1	O	

Table 4-1. Pin Functions (continued)

PIN		TYPE (1)	DESCRIPTION
NAME	NO.		
LVDSD0N, LVDSD0P	G11, H11	O	
LVDSD1N, LVDSD1P	E11, F11	O	
LVDSD2N, LVDSD2P	C11, D11	O	
LVDSD3N, LVDSD3P	G12, H12	O	
LVDSD4N, LVDSD4P	E12, F12	O	
LVDSD5N, LVDSD5P	C12, D12	O	
LVDSD6N, LVDSD6P	E13, F13	O	
LVDSD7N, LVDSD7P	C13, D13	O	
LVDSD8N, LVDSD8P	G14, H14	O	
LVDSD9N, LVDSD9P	E14, F14	O	
LVDSD10N, LVDSD10P	C14, D14	O	
LVDSD11N, LVDSD11P	G15, H15	O	
LVDSD12N, LVDSD12P	E15, F15	O	
LVDSD13N, LVDSD13P	C15, D15	O	
LVDSD14N, LVDSD14P	G16, H16	O	LVDS output interface Not yet supported in software. Leave as 'No Connect'
LVDSD15N, LVDSD15P	E16, F16	O	
LVDSD16N, LVDSD16P	G7, H7	O	
LVDSD17N, LVDSD17P	E7, F7	O	
LVDSD18N, LVDSD18P	C7, D7	O	
LVDSD19N, LVDSD19P	G6, H6	O	
LVDSD20N, LVDSD20P	E6, F6	O	
LVDSD21N, LVDSD21P	C6, D6	O	
LVDSD22N, LVDSD22P	E5, F5	O	
LVDSD23N, LVDSD23P	C5, D5	O	
LVDSD24N, LVDSD24P	G4, H4	O	
LVDSD25N, LVDSD25P	E4, F4	O	
LVDSD26N, LVDSD26P	C4, D4	O	
LVDSD27N, LVDSD27P	G3, H3	O	
LVDSD28N, LVDSD28P	E3, F3	O	

Table 4-1. Pin Functions (continued)

PIN		TYPE (1)	DESCRIPTION
NAME	NO.		
LVDSD29N, LVDSD29P	C3, D3	O	LVDS output interface Not yet supported in software. Leave as 'No Connect'
LVDSD30N, LVDSD30P	G2, H2	O	
LVDSD31N, LVDSD31P	E2, F2	O	
NC	J5,J14,K1,K5,K14,L1	-	Do not connect
$\overline{\text{RESET}}$	J1	I	Hardware reset. Active low. This pin has an internal 10kΩ pullup resistor to AVDD18.
SCLK	K15	I	Serial interface clock input. This pin has an internal 10kΩ pulldown resistor.
SDIO	L15	I/O	Serial interface data input/output. This pin has an internal 10kΩ pulldown resistor.
SDOUT	L3	O	Serial interface data output.
$\overline{\text{SEN}}$	J16	I	Serial interface enable. Active low. This pin has an internal 10kΩ pullup resistor to AVDD18.
STX0N, STX0P	C17, B17	O	Differential, high-speed serial JESD204B/C output data interface, lane 0
STX1N, STX1P	A16, A15	O	Differential, high-speed serial JESD204B/C output data interface, lane 1
STX2N, STX2P	A14, A13	O	Differential, high-speed serial JESD204B/C output data interface, lane 2
STX3N, STX3P	A11, A10	O	Differential, high-speed serial JESD204B/C output data interface, lane 3
STX4N, STX4P	C1, B1	O	Differential, high-speed serial JESD204B/C output data interface, lane 4
STX5N, STX5P	A2, A3	O	Differential, high-speed serial JESD204B/C output data interface, lane 5
STX6N, STX6P	A4, A5	O	Differential, high-speed serial JESD204B/C output data interface, lane 6
STX7N, STX7P	A7, A8	O	Differential, high-speed serial JESD204B/C output data interface, lane 7
$\overline{\text{SYNC}}$	J4	I	JESD active low SYNC input. When SYNC is low and the device is configured, the device sends K characters on the JESD lanes.
SYSREFN, SYSREFP	U6, U7	I	Differential SYSREF input (100Ω differential termination, self biased to 1.2V). AC and DC coupling is supported.
TIMESTAMPN, TIMESTAMPP	P7, N7	I	Not yet supported in software. Can be connected to GND.
VCM	T7, T12	O	Common mode voltage reference output. The two pins are internally shorted together.

(1) I = Input, O = Output, I/O = Input or Output, G = Ground, P = Power.

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Supply voltage range, AVDD18		–0.5	2.1	V
Supply voltage range, AVDD12		–0.3	1.4	
Supply voltage range, AVDDCLK18		–0.5	2.1	
Supply voltage range, AVDDCLK12		–0.3	1.4	
Supply voltage range, DVDD09		–0.3	1.2	
Supply voltage range, AVDDGPIO18		–0.5	2.1	
Voltage applied to input pins	IN0P/N, IN1P/N, IN2P/N, IN3P/N	–0.5	2.1	
	CLKP/N	–0.3	1.4	
	SYSREFP/N, TIMESTAMPP/N	–0.3	2.1	
	GPIO1..23, $\overline{\text{RESET}}$, SCLK, $\overline{\text{SEN}}$, SDIO, $\overline{\text{SYNC}}$	–0.5	2.1	
Junction temperature, T_J			125	℃
Storage temperature, T_{stg}		–65	150	

(1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	1000	V
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002(2)	150	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
AVDD18	1.8 V analog supply		1.75	1.8	1.85	V
AVDD12	1.2 V analog supply		1.175	1.2	1.225	
AVDDCLK18	1.8 V clock supply		1.75	1.8	1.85	
AVDDCLK12	1.2 V clock supply		1.175	1.2	1.225	
DVDD09	0.9 V digital supply		0.875	0.9	0.925	
AVDDGPIO18	1.8 V GPIO Power Supply		1.75	1.8	1.85	
T_A	Operating free-air temperature		–40		105	℃
T_J	Operating junction temperature				110(1)	

(1) Prolonged use above this junction temperature can increase the device failure-in-time (FIT) rate.

5.4 Thermal Information

THERMAL METRIC(1)		ADC32RF72 ANH (BGA) 289 Balls	UNIT
$R_{\Theta JA}$	Junction-to-ambient thermal resistance	15.4	°C/W
$R_{\Theta JC(top)}$	Junction-to-case (top) thermal resistance	0.5	°C/W
$R_{\Theta JB}$	Junction-to-board thermal resistance	4.2	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.1	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	4.1	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application note.

5.5 Electrical Characteristics - Power Consumption

Maximum and minimum values are specified over the operating free-air temperature range and nominal supply voltages. Typical values are specified at T_A = 25°C, ADC sampling rate = 1.5 GSPS, DDC Bypass mode, 50% clock duty cycle, nominal supply voltages and –1-dBFS differential input, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{AVDD18}	Supply current, 1.8V analog supply	Bypass mode LMFS = 4-2-1-1		315	350	mA
I_{AVDD12}	Supply current, 1.2V analog supply			915	1100	
$I_{AVDDCLK18}$	Supply current, 1.8V clock supply			50	75	
$I_{AVDDCLK12}$	Supply current, 1.2V clock supply			50	75	
I_{DVDD09}	Supply current, 0.9V digital supply			1450	1800	
$I_{AVDDGPIO18}$	Supply current, 1.8V GPIO supply			5		
P_{DIS}	Power dissipation			3.1		W
POWER DOWN MODES						
P_{DIS}	Fast power down mode power consumption	Fast wake up time		2.0		W
P_{DIS}	Global power down mode power consumption			0.4		

5.6 Electrical Characteristics - DC Specifications

Maximum and minimum values are specified over the operating free-air temperature range and nominal supply voltages. Typical values are specified at T_A = 25°C, ADC sampling rate = 1.5 GSPS, DDC Bypass mode, 50% clock duty cycle, nominal supply voltages and –1-dBFS differential input, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DC ACCURACY						
	No missing codes		16			bits
DNL	Differential nonlinearity	F_{IN} = 10 MHz		0.3		LSB
INL	Integral nonlinearity	F_{IN} = 10 MHz		2.5		LSB
V_{OS_ERR}	Offset error			0.9		%FSR
$GAIN_{ERR}$	Gain error			1.0		%FSR
$GAIN_{Matching}$	Gain matching across channels			0.1		dB
ADC ANALOG INPUTS (IN0P/N, IN1P/N, IN2P/N, IN3P/N)						
FS	Input full scale	Differential		1.4375		Vpp
V_{ICM}	Input common model voltage		1.25	1.35	1.45	V
Z_{IN}	Differential input impedance	Differential at 100 MHz		100		Ω
V_{OCM}	Output common mode voltage			1.35		V
BW	Analog Input Bandwidth (-3dB)			1.8		GHz
CMRR	Common mode rejection ratio	F_{IN} = 100 MHz		30		dB
CLOCK INPUT (CLKP/N)						
Input clock frequency			500		1500	MHz
V_{ID}	Differential input voltage		0.6	2.0	2.8	Vpp
V_{ICM}	Input common mode voltage			0.7		V
Z_{IN}	Differential input impedance	Differential at 1.5 GHz		100		Ω
Clock duty cycle			30	50	70	%
SYSREF INPUT (SYSREFP/N)						
V_{ID}	Differential input voltage		350	450	800	mVpp
V_{ICM}	Input common mode voltage		1.05	1.2	1.325	V
Digital Inputs (GPIO1..23, $\overline{\text{RESET}}$, SCLK, $\overline{\text{SEN}}$, SDIO, $\overline{\text{SYNC}}$)						
V_{IH}	High level input voltage		1.15			V
V_{IL}	Low level input voltage				0.65	V
I_{IH}	High level input current		-250		250	µA
I_{IL}	Low level input current		-250		250	µA
C_I	Input capacitance			2		pF
DIGITAL OUTPUT (SDIO, SDOUT)						
V_{OH}	High level output voltage	I_{LOAD} = -400 µA	AVDDG PIO18– 0.1	AVDDG PIO18		V
V_{OL}	Low level output voltage	I_{LOAD} = 400 µA			0.1	V
CML SERDES OUTPUTS: STX[0..7]P/N						
V_{OD}	SerDes transmitter output amplitude	differential peak-peak		950		mVpp
V_{OCM}	SerDes transmitter output common mode			450		mV
Z_{TX}	SerDes transmitter single ended termination impedance			50		Ω
	Transmitter short-circuit current	Transmitter pins shorted to any voltage between –0.25 V and 1.45 V	–100		100	mA

5.7 Electrical Characteristics - AC Specifications

Maximum and minimum values are specified over the operating free-air temperature range and nominal supply voltages. Typical values are specified at T_A = 25°C, ADC sampling rate = 1.5 GSPS, 100Ω termination, DDC Bypass mode, 50% clock duty cycle, nominal supply voltages and –1-dBFS differential input, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN(2)	TYP	MAX	UNIT
AC ACCURACY						
NSD_{flat}	Noise Spectral Density	f_{IN} = 600MHz, A_{IN} = -20dBFS		–163.7		dBFS/Hz
NF	Noise Figure (100Ω termination)	f_{IN} = 600MHz, A_{IN} = -20dBFS		14.4		dB
SNR	Signal to noise ratio	f_{IN} = 100MHz		73.0		dBFS
SNR_{flat} (1)	Signal to noise ratio measured from 100MHz to FS/2 within the Nyquist zone	f_{IN} = 100MHz	72.0	75.3		dBFS
		f_{IN} = 600MHz		73.4		
		f_{IN} = 600MHz, A_{IN} = -20dBFS		75.5		
		f_{IN} = 900MHz		72.1		
		f_{IN} = 1.4GHz		69.0		
$SINAD_{flat}$ (1)	Signal to noise and distortion ratio	f_{IN} = 100MHz		74.3		dBFS
ENOB	Effective number of bits	f_{IN} = 100MHz		11.8		Bits
THD	Total Harmonic Distortion (First five harmonics)	f_{IN} = 100MHz		82		dBc
		f_{IN} = 600MHz		74		
		f_{IN} = 900MHz		68		
		f_{IN} = 1.4GHz		57		
HD2	Second Harmonic Distortion	f_{IN} = 100MHz	74	88		dBc
		f_{IN} = 600MHz		77		
		f_{IN} = 900MHz		74		
		f_{IN} = 1.4GHz		64		
HD3	Third Harmonic Distortion	f_{IN} = 100MHz	74	83		dBc
		f_{IN} = 600MHz		77		
		f_{IN} = 900MHz		68		
		f_{IN} = 1.4GHz		58		
Non HD2,3	Spur free dynamic range (excluding HD2 and HD3)	f_{IN} = 100MHz	80	95		dBFS
		f_{IN} = 600MHz		90		
		f_{IN} = 900MHz		93		
		f_{IN} = 1.4GHz		79		
IMD3	Two tone inter-modulation distortion	f_1 = 100MHz, f_2 = 200MHz, A_{IN} = -7dBFS/tone		89		dBFS
		f_1 = 0.9GHz, f_2 = 1.0GHz, A_{IN} = -7dBFS/tone		76		

(1) For detailed description of SNR_{flat} and NSD_{flat} see Section 6.
(2) SNR_{flat}, HD3 and Non HD23 minimum values are specified by final test; HD2 is specified by bench characterization.

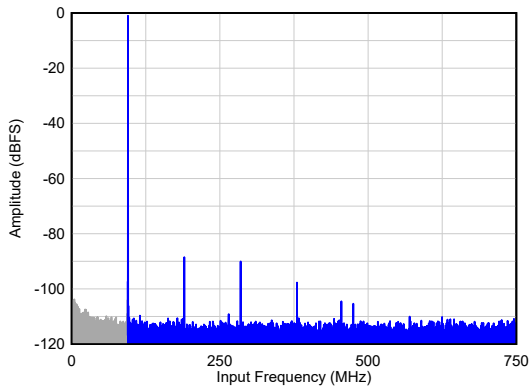
5.8 Timing Requirements

Maximum and minimum values are specified over the operating free-air temperature range and nominal supply voltages. Typical values are specified at T_A = 25°C, ADC sampling rate = 1.5 GSPS, DDC Bypass mode, 50% clock duty cycle, nominal supply voltages and –1-dBFS differential input, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	NOM	MAX	UNIT
ADC Timing Specifications						
T_{AD}	Aperture Delay			0.15		ns
	Aperture Delay variation			0.05		ns
T_A	Aperture Jitter			40		fs
CER	Code error rate			1e-15		errors/ sample
	Wake up time	time to valid data (SNR within 2dB of data sheet values) after coming out of fast power down (JESD stays active)			5	µs
LATENCY: t_{PD} + t_{ADC}						
t_{PD}	Propagation delay			1		ns
t_{ADC}	ADC latency from sampling instant to JESD output	DDC bypass, LMFS = 8411		524		ADC clock cycles
SERIAL PROGRAMMING INTERFACE (SCLK, SEN, SDIO) - Input						
$f_{CLK(SCLK)}$	Serial clock frequency		1		50	MHz
$t_{S(SEN)}$	SEN to rising edge of SCLK		10			ns
$t_{H(SEN)}$	SEN from rising edge of SCLK		10			ns
$t_{SU(SDIO)}$	SDIO to rising edge of SCLK		10			ns
$t_{H(SDIO)}$	SDIO from rising edge of SCLK		10			ns
SERIAL PROGRAMMING INTERFACE (SDIO, SDOUT) - Output						
$t_{(OZD)}$	SDIO tri-state to driven				10	ns
$t_{(ODZ)}$	SDIO data to tri-state				14	ns
$t_{(OD)}$	SDIO valid from falling edge of SCLK				10	ns
Timing: SYSREFP/N						
$t_{s(SYSREF)}$	Setup time, SYSREFP/N valid to rising edge of CLKP/N			50		ps
$t_{h(SYSREF)}$	Hold time, SYSREFP/N valid to rising edge of CLKP/N			50		ps
CML SerDes Outputs: STX[0..7]P/N						
f_{Serdes}	SerDes bit rate		4.0		24.75	Gbps
R_J	Random jitter			0.45		ps
D_J	Deterministic jitter			12.5		ps
T_J	Total jitter, peak-peak			19.7		ps

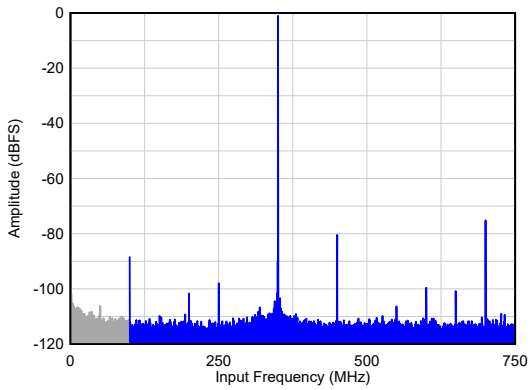
5.9 Typical Characteristics

Typical values are at T_A = 25°C, ADC sampling rate = 1.5GSPS, 50% clock duty cycle, nominal supplies and –1dBFS differential input, 100Ω termination, unless otherwise noted



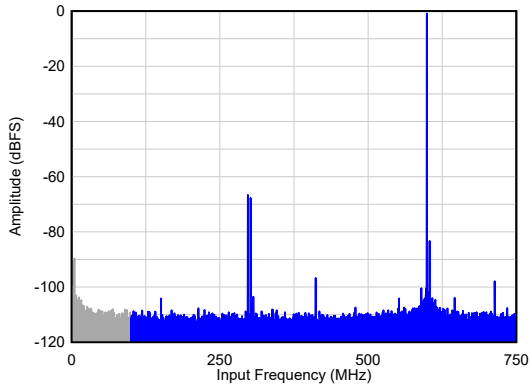
SNR_{flat} = 74.6dBFS

Figure 5-1. Single Tone FFT at F_{IN} = 100MHz



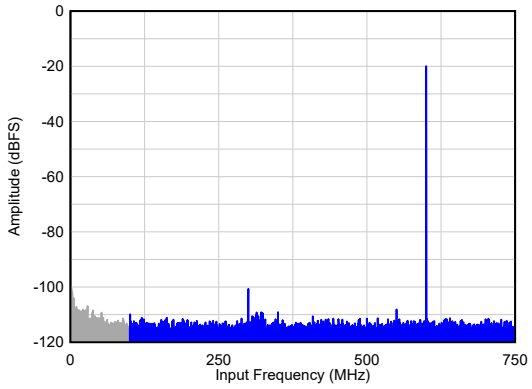
SNR_{flat} = 73.7dBFS

Figure 5-2. Single Tone FFT at F_{IN} = 300MHz



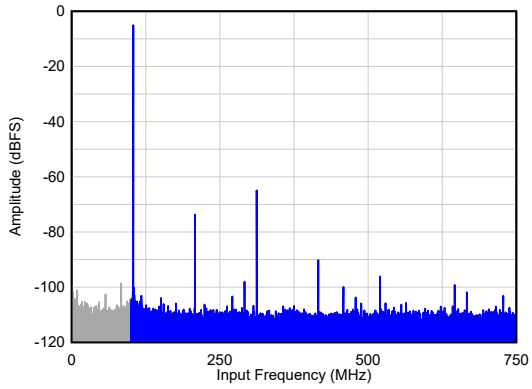
SNR_{flat} = 71.5dBFS

Figure 5-3. Single Tone FFT at F_{IN} = 900MHz



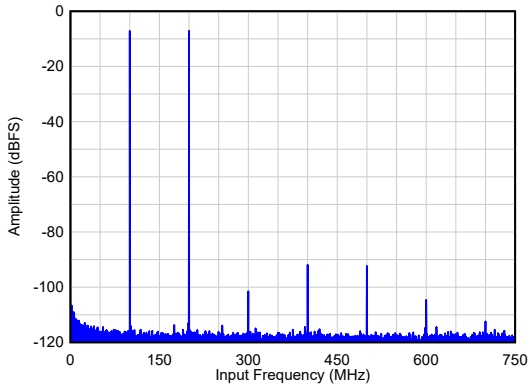
SNR_{flat} = 74.6dBFS, A_{IN} = -20dBFS

Figure 5-4. Single Tone FFT at F_{IN} = 900MHz



SNR_{flat} = 67.8dBFS

Figure 5-5. Single Tone FFT at F_{IN} = 1400MHz

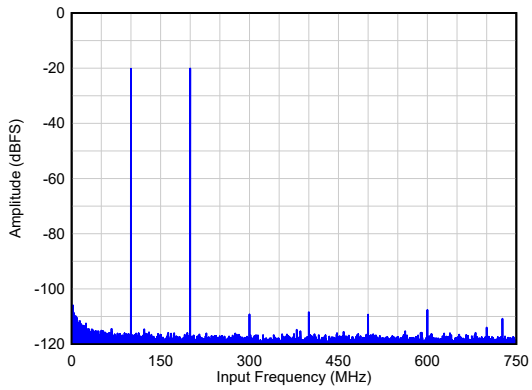


A_{IN} = -7dBFS/tone

Figure 5-6. Two Tone FFT at F_{IN} = 100/200MHz

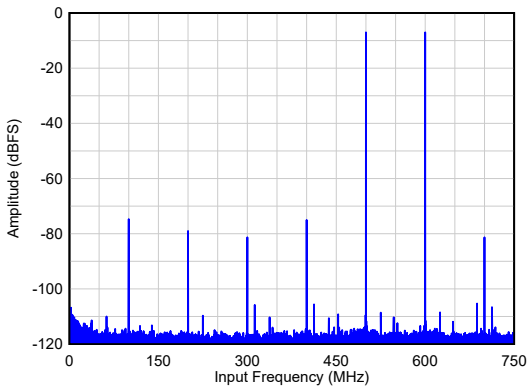
5.9 Typical Characteristics (continued)

Typical values are at T_A = 25°C, ADC sampling rate = 1.5GSPS, 50% clock duty cycle, nominal supplies and –1dBFS differential input, 100Ω termination, unless otherwise noted



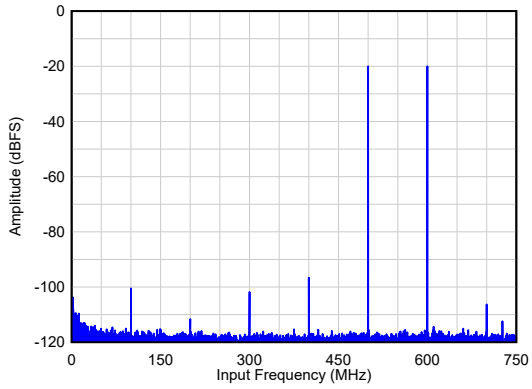
A_{IN} = -20dBFS/tone

Figure 5-7. Two Tone FFT at F_{IN} = 100/200MHz



A_{IN} = -7dBFS/tone

Figure 5-8. Two Tone FFT at F_{IN} = 900/1000MHz



A_{IN} = -20dBFS/tone

Figure 5-9. Two Tone FFT at F_{IN} = 900/1000MHz

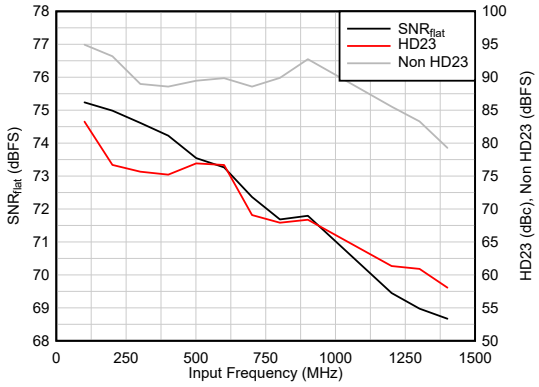
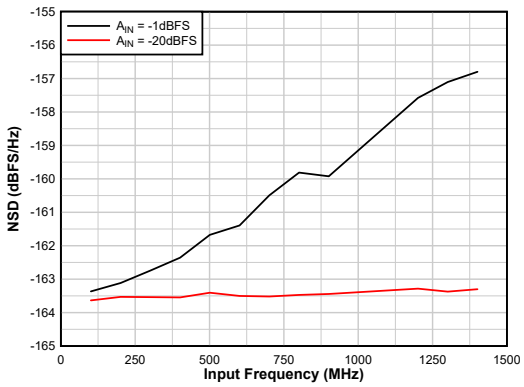
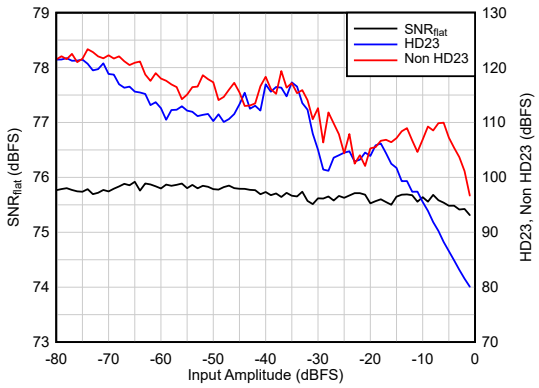


Figure 5-10. AC Performance vs F_{IN}



Termination = 50ohm

Figure 5-11. NSD Performance vs F_{IN}

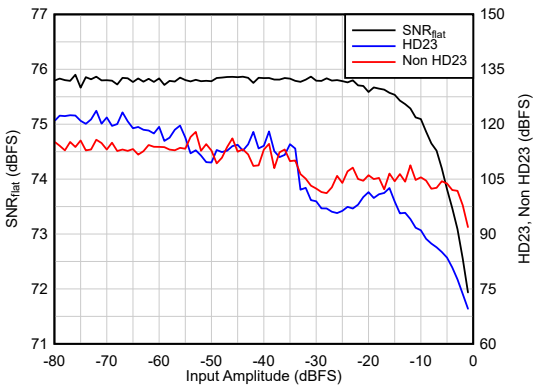


F_{IN} = 100MHz

Figure 5-12. AC Performance vs A_{IN}

5.9 Typical Characteristics (continued)

Typical values are at T_A = 25°C, ADC sampling rate = 1.5GSPS, 50% clock duty cycle, nominal supplies and –1dBFS differential input, 100Ω termination, unless otherwise noted



F_{IN} = 900MHz

Figure 5-13. AC Performance vs A_{IN}

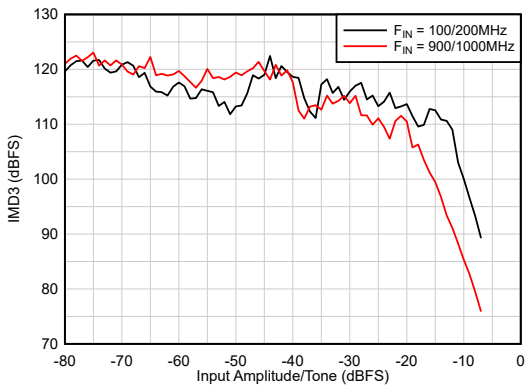
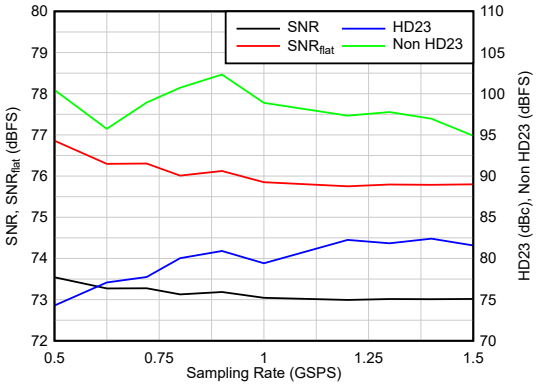


Figure 5-14. IMD3 Performance vs A_{IN}



F_{IN} = 100MHz

Figure 5-15. AC Performance vs F_S

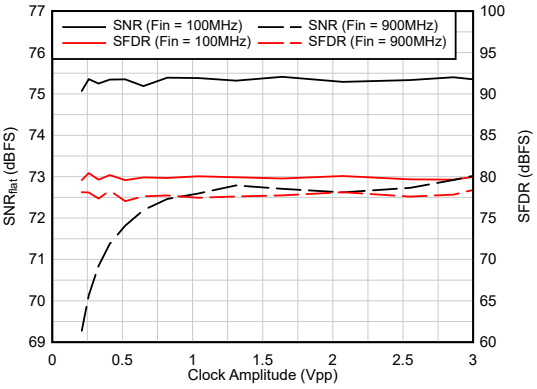


Figure 5-16. AC Performance vs Clock Amplitude

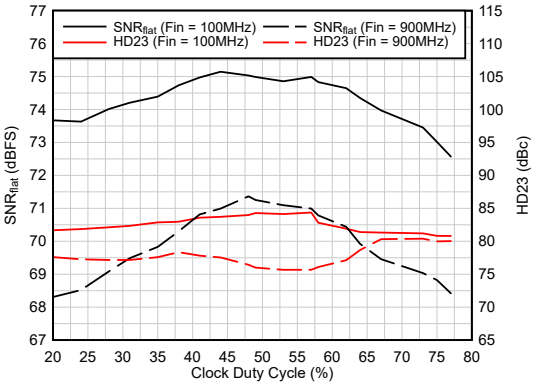


Figure 5-17. AC Performance vs Clock Duty Cycle

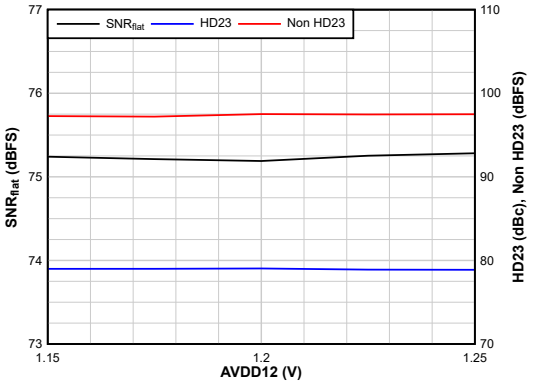


Figure 5-18. AC Performance vs AVDD12 Supply

5.9 Typical Characteristics (continued)

Typical values are at T_A = 25°C, ADC sampling rate = 1.5GSPS, 50% clock duty cycle, nominal supplies and –1dBFS differential input, 100Ω termination, unless otherwise noted

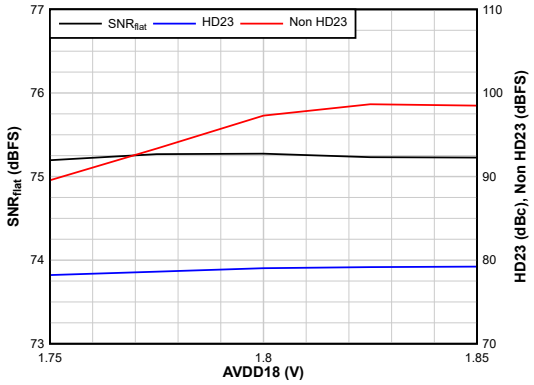


Figure 5-19. AC Performance vs AVDD18 Supply

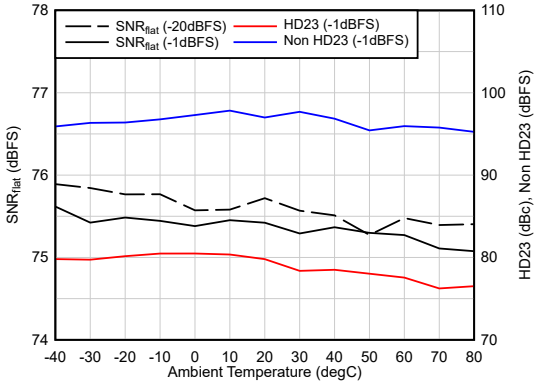
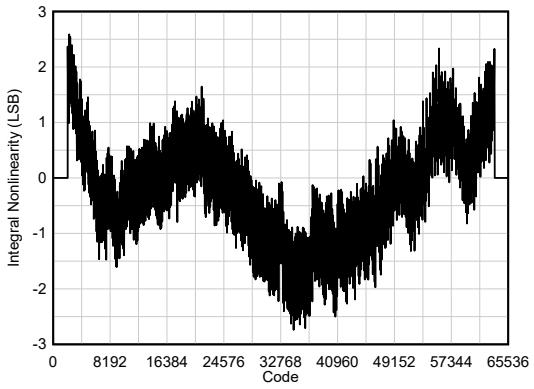
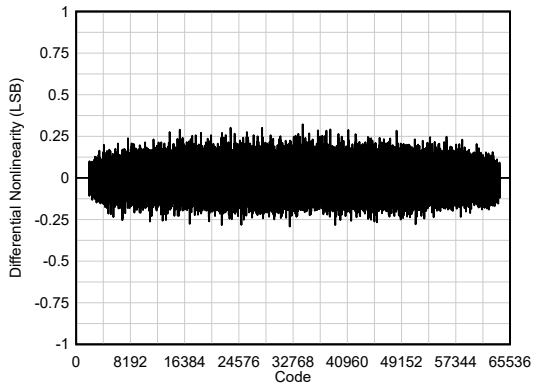


Figure 5-20. AC Performance vs Temperature



F_{IN} = 100MHz

Figure 5-21. INL vs Code



F_{IN} = 100MHz

Figure 5-22. DNL vs Code

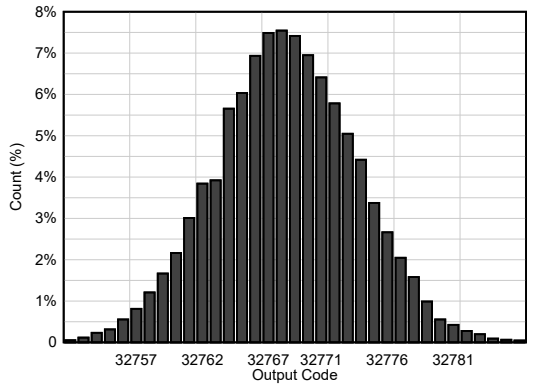


Figure 5-23. Idle Channel Histogram

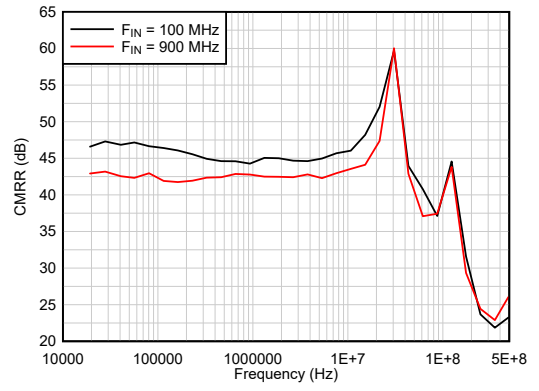


Figure 5-24. CMRR

5.9 Typical Characteristics (continued)

Typical values are at T_A = 25°C, ADC sampling rate = 1.5GSPS, 50% clock duty cycle, nominal supplies and –1dBFS differential input, 100Ω termination, unless otherwise noted

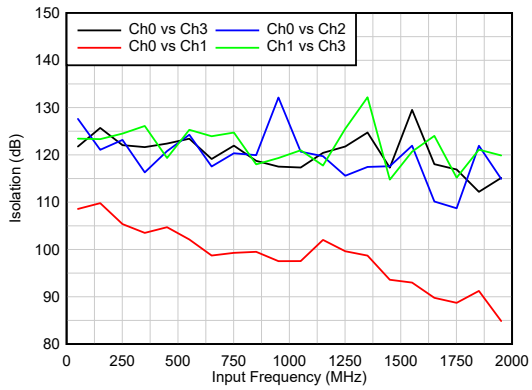
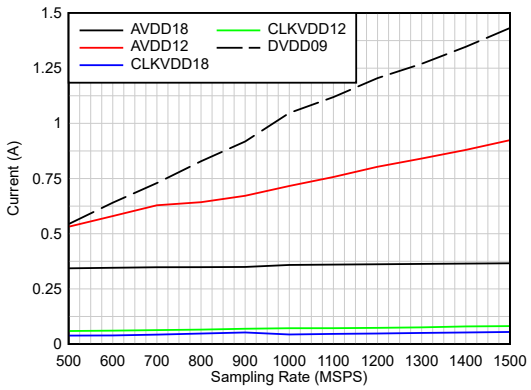
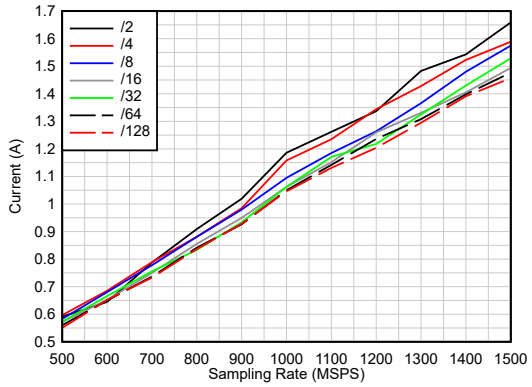


Figure 5-25. Channel Isolation



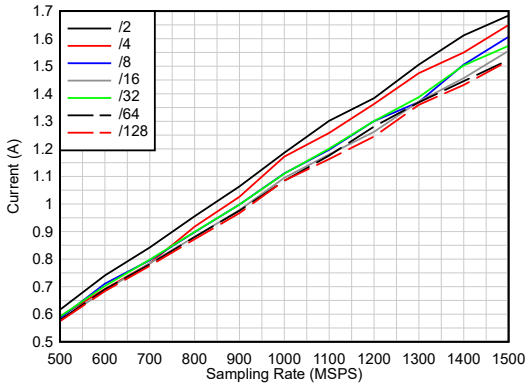
LMFS = 4-2-1-1

Figure 5-26. Currents vs Sampling Rate



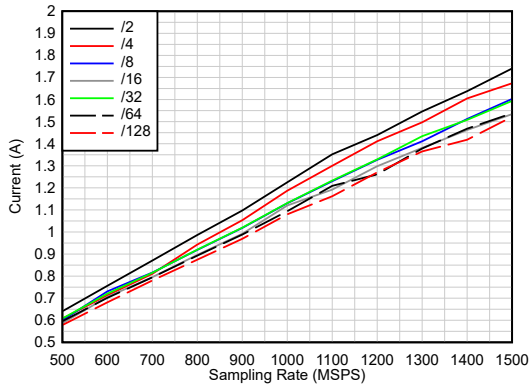
Dual band, LMFS = 8-4-1-1

Figure 5-27. DVDD09 current vs Decimation



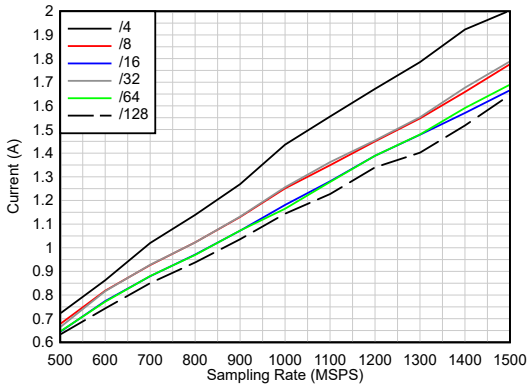
Dual band, LMFS = 4-4-2-1

Figure 5-28. DVDD09 current vs Decimation



Quad band, LMFS = 8-8-2-1

Figure 5-29. DVDD09 current vs Decimation

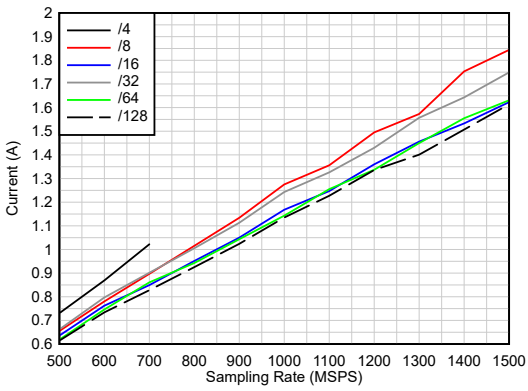


Quad band, LMFS = 4-8-4-1

Figure 5-30. DVDD09 current vs Decimation

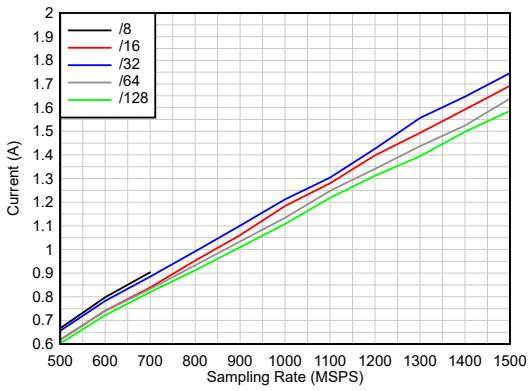
5.9 Typical Characteristics (continued)

Typical values are at T_A = 25°C, ADC sampling rate = 1.5GSPS, 50% clock duty cycle, nominal supplies and –1dBFS differential input, 100Ω termination, unless otherwise noted



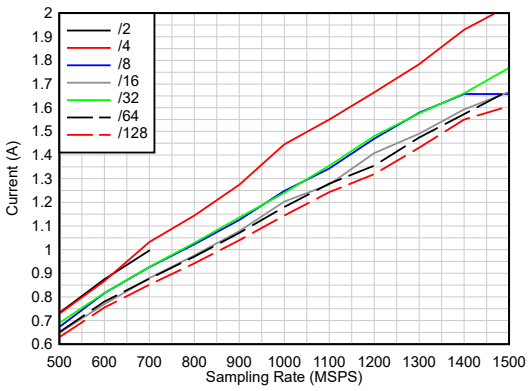
Quad band, LMFS = 2-8-8-1

Figure 5-31. DVDD09 current vs Decimation



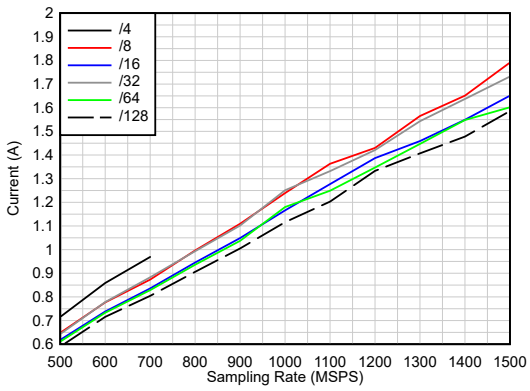
Quad band, LMFS = 1-8-16-1

Figure 5-32. DVDD09 current vs Decimation



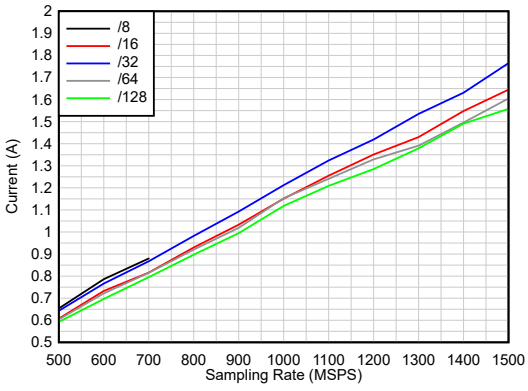
Octal band, LMFS = 8-16-4-1

Figure 5-33. DVDD09 current vs Decimation



Octal band, LMFS = 4-16-8-1

Figure 5-34. DVDD09 current vs Decimation



Octal band, LMFS = 2-16-16-1

Figure 5-35. DVDD09 current vs Decimation

6 Parameter Measurement Information

The ADC32RF72 has 1/f noise with a corner frequency of approximately 100MHz. To better illustrate the true noise floor for high performance and RF sampling applications, the ADC noise performance is specified in the following two ways.

SNR: Measured across the full Nyquist zone including 1/f noise

SNR_{flat}, NSD_{flat}: Measured in the flat noise region from 100MHz to FS/2 (750MHz)

Reducing the measurement bandwidth by 100MHz (starting at 100MHz instead of 0Hz) improves the SNR by approximately 0.6dB (10log(750MHz/650MHz) = 10log(0.06) = 0.62dB) assuming flat, uniform noise across the Nyquist zone.

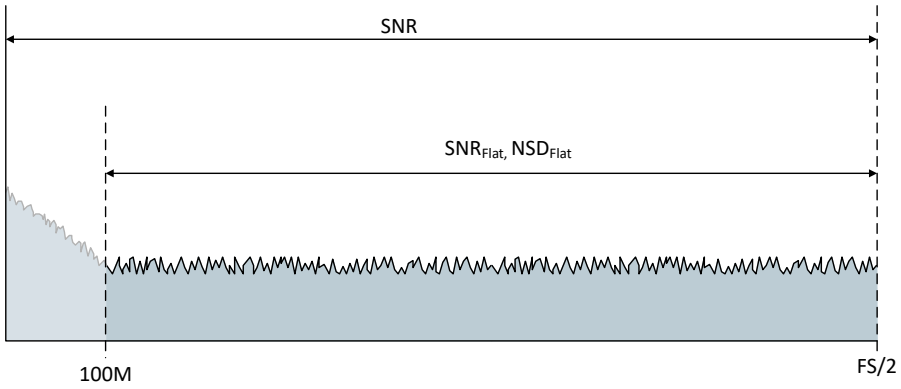


Figure 6-1. SNR (DC to FS/2) vs SNR_{flat} (100MHz to FS/2)

Assuming NSD_{flat} = -163.7dBFS/Hz

SNR_{flat} calculates to:

-(-163.7dBFS/Hz + 10log(650MHz)) = -(-163.7 + 88.1)dBFS = 75.6dBFS (1)

The 1/f noise is approximately 76.4dBFS. The 1/f noise measurement is shown in Figure 6-2 with a resolution bandwidth of approximately 6MHz. The SNR for full Nyquist zone including 1/f noise calculates to:

$SNR_{1/f}$ + SNR_{flat} = (2)

$$SNR_{1/f} + SNR_{flat} = 10log\sqrt{\left(10^{\frac{-SNR_{1/f}}{20}}\right)^2 + \left(10^{\frac{-SNR_{flat}}{20}}\right)^2} = 10log\sqrt{\left(10^{\frac{-76.4}{20}}\right)^2 + \left(10^{\frac{-75.6}{20}}\right)^2} = 73dBFS$$

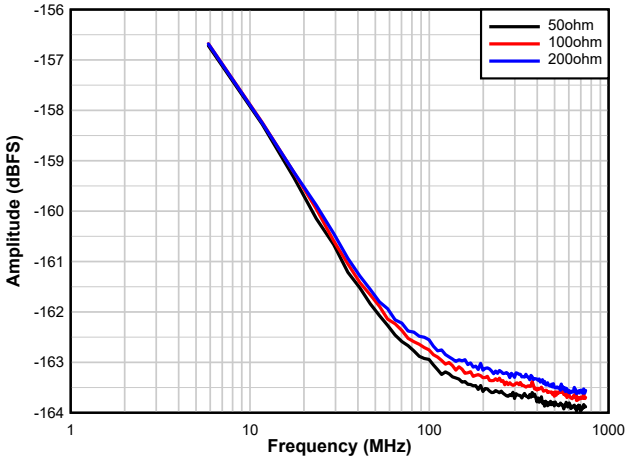


Figure 6-2. 1/f Noise Measurement

7 Detailed Description

7.1 Overview

The ADC32RF72 is a 16-bit, 1.5GSPS (non-interleaved), dual channel analog to digital converter (ADC). The design maximizes signal-to-noise ratio (SNR) and delivers a noise spectral density of -163.7dBFS/Hz. When providing the input signal to 2 ADC inputs, the NSD can be improved to as low as -166.2dBFS/Hz using internal digital averaging. The device lets the user select ADC0 and any of the 3 remaining ADC channels - two ADC channels (ADC0/1) on the same side of the package for 2x averaging or on the opposite side (ADC0/2) of the package for best isolation.

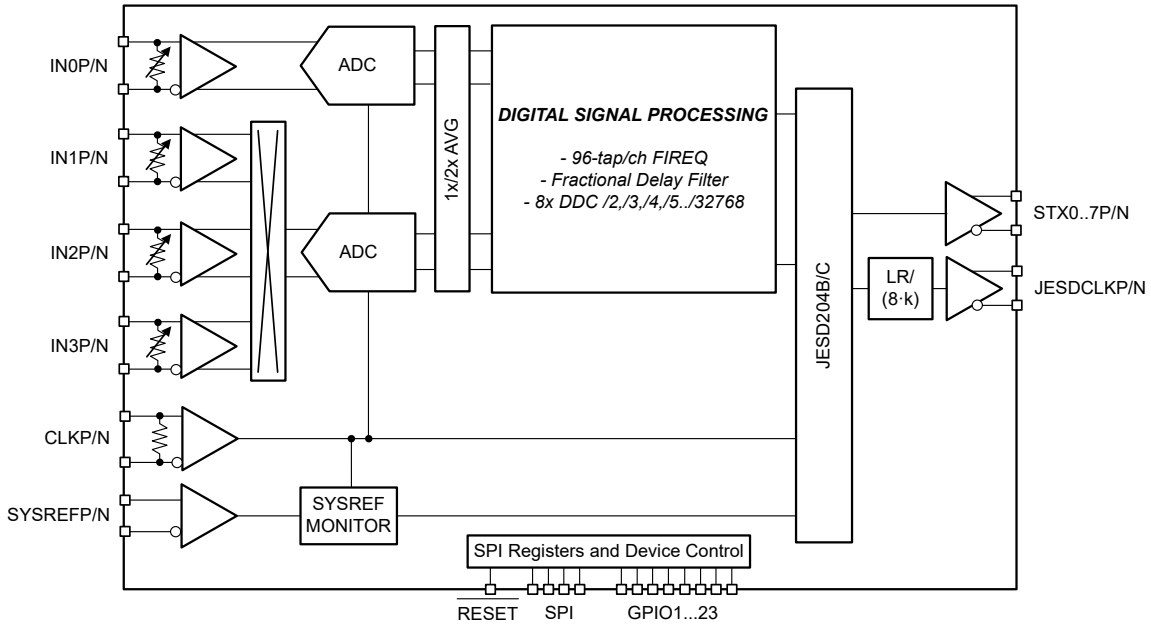
The analog signal input is buffered and supports a programmable internal termination impedance of 50Ω, 100Ω and 200Ω. The full power input bandwidth is 1.8GHz (-3dB) and the device supports direct RF sampling with input frequencies in from DC through L-band. The ADC32RF72 is designed for low residual phase noise to support high performance radar applications.

The device includes several digital processing features such as a 192-tap/ch programmable FIR filter for equalization, a 12-bit fractional delay filter as well as multiple digital down converters (DDCs). There are eight digital down converters supporting decimation factors of /2, /3 and /5. The 48-bit NCOs support phase coherent frequency hopping. Using the GPIO pins for NCO frequency control, frequency hopping can be achieved in less than 1µs. The digital down converters provide support for a wide range of instantaneous bandwidth (IBW) requirements, from wide band mode with /2 complex decimation to narrow bandwidth channels with complex decimation of /32768. The final /2 decimation stage features programmable filter coefficients.

The device supports the JESD204B/C serial data interface using 64b/66b and 8b/10b encoding with subclass 1 deterministic latency using data rates up to 24.75Gbps. Using both interface options, the ADC32RF7xcan output both full spectrum (DDC bypass) and decimated data. Furthermore, the SerDes PLL (lane rate /(8x k)) can be output to the FPGA to simplify system clocking.

The device requires 3 different power rails: 1.8V, 1.2V and 0.9V.

7.2 Functional Block Diagram



Block Diagram

7.3 Feature Description

7.3.1 Analog Inputs

The analog inputs of the ADC32RF72 have internal buffers which isolate the sampling capacitor from the external input circuitry. The analog inputs have a programmable, differential split termination with internal biasing as shown in Figure 7-1. The differential termination can be selected to differential 50Ω, 100Ω or 200Ω via SPI register write. Both AC-coupling and DC-coupling of the analog inputs is supported.

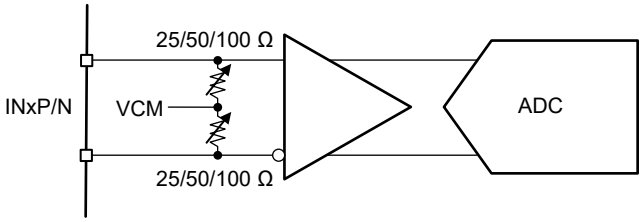


Figure 7-1. Analog input (internal) circuitry

The following parameters can be programmed:

Table 7-1. Input Termination Programming (x = 0,1,2,3)

System Parameter Name	Size (bits)	Default	Reset	Description
ADC{x}_INPUT_TERM_SEL	2	0	R/W	Select ADC{x} input termination setting 0: 50Ω differential 1: 100Ω differential 2: 200Ω differential

7.3.1.1 Input Bandwidth

The input bandwidth (-3dB) with internal 50Ω, 100Ω and 200Ω differential termination is shown in Figure 7-2 along with the S11 responses (Figure 7-2). With 100Ω termination the input bandwidth is approximately 1.8GHz (-3dB). Figure 7-4 shows the frequency response with 100Ω termination using the external matching network shown in Figure 7-5.

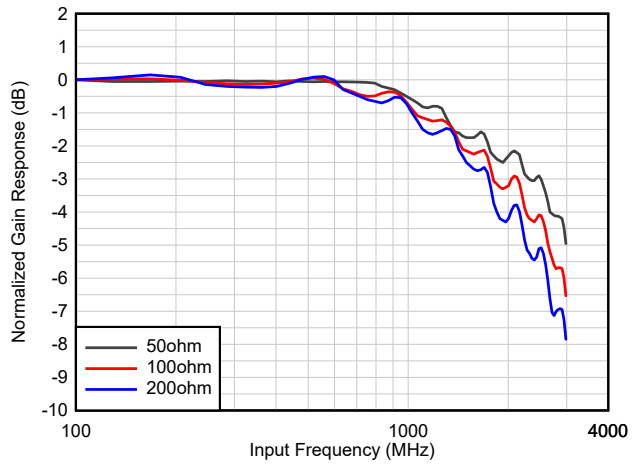


Figure 7-2. Input Bandwidth Plot (6dB pad)

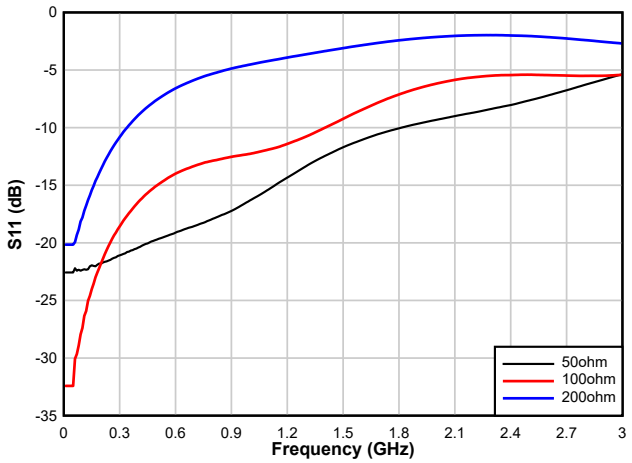


Figure 7-3. S11 vs Frequency (each normalized to input termination)

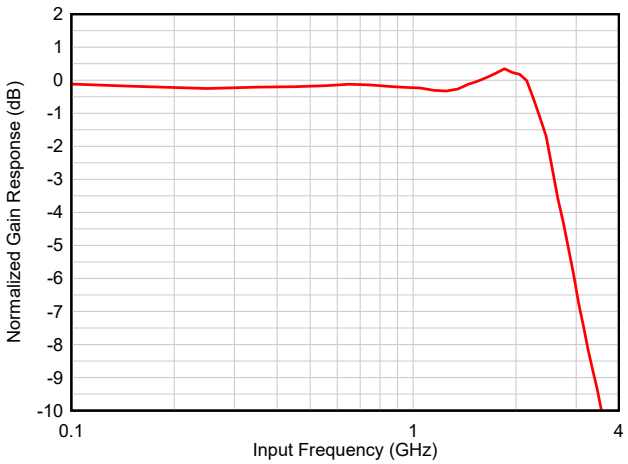


Figure 7-4. Input Bandwidth Plot

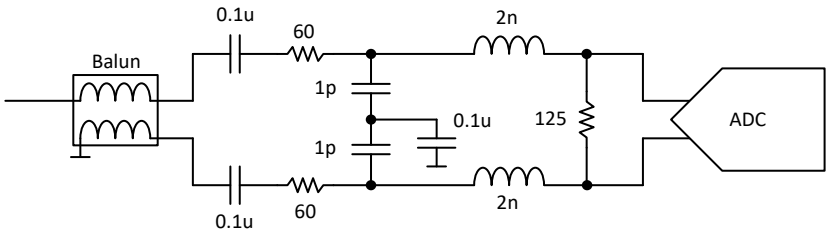
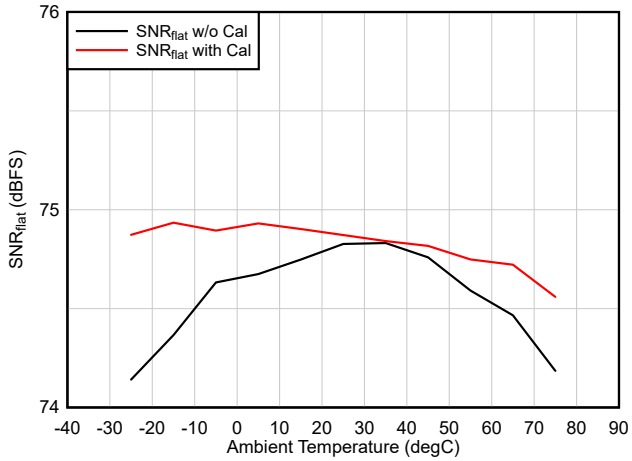


Figure 7-5. External Matching Network

7.3.1.2 Background Calibration

The ADC32RF72 uses internal background calibration to maintain a high AC performance over temperature. The calibration is performed periodically and does not require any user control or input signal, and so on. During calibration, small changes to the signal offset are observed (approximately 30LSB). This calibration can be frozen to avoid any disturbance during measurements using SPI writes or GPIO control.



F_{IN} = 100MHz, A_{IN} = -1dBFS, Calibration at 25°C

Figure 7-6. SNR_{flat} vs Temperature vs Calibration

7.3.2 ADC Channel Selection and Power Down Modes

There are 4 different ADC channels (Ch0...3) available however channel 0 always has to be enabled. The user can select any of the remaining 3 via the channel enable control shown below in the system parameters. This is a static configuration that needs to be set at power up.

The device supports three different power down modes that can be controlled via GPIO pins or SPI register writes:

- Fast Power Down: individual channel power down with shorter wake up time but higher power consumption. JESD interface stays active.
- Power Down: individual channel power down. JESD interface can be adjusted and power down unused lanes.
- Global Power Down: power down of entire chip for lowest power consumption (enabled via function call).

Table 7-2. Power Down Modes Comparison

Power Down Mode	Wake Up Time	Power Consumption (typ)	Comment
Fast Power Down	~ 5 us	~ 2.0W	JESD interface stays active
Global Power Down	depends on JESD interface	~ 0.4W	JESD interface powered down

The power down modes can be can be programmed using the following parameters:

Table 7-3. Power Down Modes Programming

System Parameter Name	Size	Default	Access	Description
ADC_EN_BITMAP	4	3	R/W	Select two out of the 4 ADCs. 3: Channel 0 and 1 are active. 5: Channel 0 and 2 are active. 9: Channel 0 and 3 are active.
ADC_CH_PDN_VAL	4	0	R/W	Individual ADC channel power down setting. Each ADC gets one bit. If the bit is set, the corresponding channel is powered down. ADC_CH_PDN_SRC_SEL needs to be set to 1 for this setting to take effect. Bit 0: ADC0 power down control. Bit 1: ADC1 power down control. Bit 2: ADC2 power down control. Bit 3: ADC3 power down control.
ADC_CH_PDN_SRC_SEL	1	0	R/W	Select if channel power down signal is coming from a GPIO or SPI. 0: Channel power down is from GPIO. 1: Channel power down is coming from ADC_CH_PDN_VAL.
ADC_CH_PDN_MODE	1	0	R/W	Select the channel power down mode. 0: Normal PDN (least power consumption for each channel). 1: Fast PDN (faster power up time but higher power consumption).

7.3.3 Sampling Clock Input

The clock input has internal 100Ω differential termination with self biasing to VCM = 0.7V, enabling external AC coupling (see Figure 7-7).

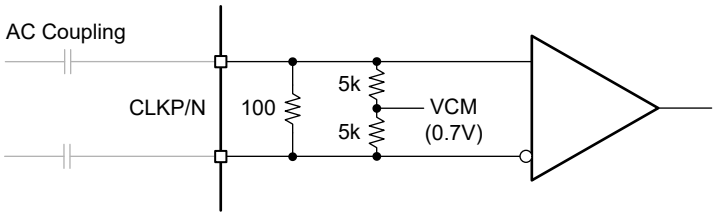


Figure 7-7. Internal Sampling Clock Circuitry

The internal sampling clock path is designed for ultra-low residual phase noise contribution. The sampling clock circuitry requires a dedicated low noise power supply for best performance. The internal aperture clock phase noise is also sensitive to clock amplitude. For best performance, the clock amplitude must be larger than 1Vpp.

Table 7-4. Internal Aperture Clock Noise at 1GHz

Frequency Offset (MHz)	Phase Noise (dBc/Hz)	Amplitude Noise (dBc/Hz)
0.001	−130	−139
0.01	−140	−149
0.1	−150	−155
1	−155	−159

The following parameters can be programmed:

Table 7-5. Clock Register Programming

System Parameter Name	Size	Default	Reset	Description
ADC_CLK_FREQ_HZ	33	0	R/W	33-bit unsigned number that represent the sampling clock frequency in Hz.

7.3.4 SYSREF

The SYSREF input signal is used for multi-chip synchronization and resets the internal LMFC counter. The device must be armed in anticipation of a SYSREF signal; the device is sensitive to the first SYSREF edge after the device is armed.

The internal SYSREF capture includes a programmable analog delay t_d, a SYSREF monitor as well as a programmable digital integer clock cycle delay z^{-n} as shown in Figure 7-8.

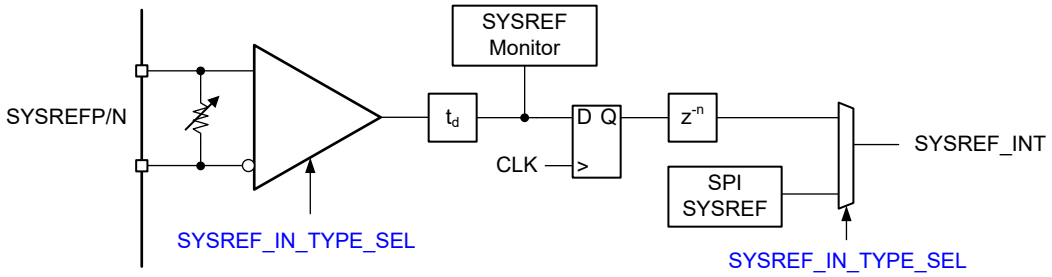


Figure 7-8. SYSREF Input Internal Path

The SYSREF input signal can be AC or DC coupled (selected via SPI register option) as shown in Figure 7-9. The SYSREF input has internal 100Ω termination for DC coupling and internal biasing when using AC coupling.

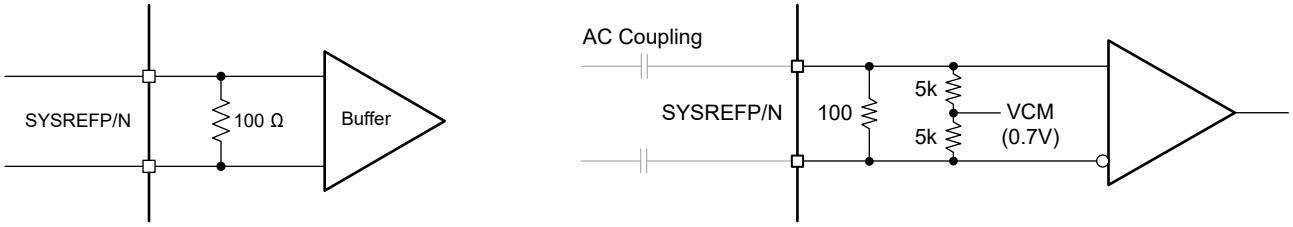


Figure 7-9. SYSREF Input Circuitry and Edge Alignment (Left Side: DC Coupling, Right Side: AC Coupling)

The following parameters can be programmed:

Table 7-6. SYSREF Configuration Programming

System Parameter Name	Size	Default	Reset	Description
SYSREF_IN_TYPE_SEL	2	0	R/W	Select input SYSREF type: 0: DC coupled LVDS SYSREF input. 1: AC coupled SYSREF input. 2: not used. 3: Internally generated SYSREF using SPI write.
SYSREF_DIG_DEL	8	0	R/W	Digital SYSREF internal delay (z^{-n}) in clock cycles of CLK. 0...255: Number of device clock cycles delay that is applied to digital SYSREF before use.

7.3.4.1 SYSREF Monitor

The SYSREF monitor compares the incoming SYSREF signal to the ADC sampling clock by latching the incoming SYSREF signal with copies of the sampling clock that have an analog delay. The latched outputs are processed internally through the SYSREF processing block and the final output is provided to the user. The latched flop outputs are used to check if there exists enough margin between the CLK and SYSREF rising edges (set up and hold times). If a set up and hold violation is detected, a programmable delay t_d can be used to adjust the SYSREF delay such that there is adequate margin between CLK and SYSREF for SYSREF to be latched properly.

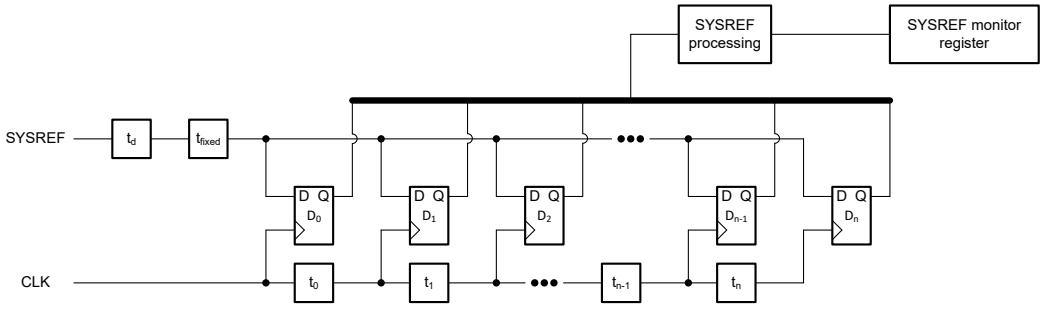


Figure 7-10. SYSREF Detection Circuitry

The following parameters can be programmed:

Table 7-7. SYSREF Configuration Programming

System Parameter Name	Size	Default	Access	Description
SYSREF_MONITOR_NUM_POLLS	8	1	R/W	Sets the number of SYSREF rising edges to be detected before SYSREF_MONITOR_OUT is updated. Higher values of SYSREF_MONITOR_NUM_POLLS can be used to gauge the SYSREF edge spread since each flop output is ORed with all of the previous outputs until SYSREF_MONITOR_NUM_POLLS SYSREF rising edges are seen. 1...255: Number of SYSREF rising edges to be seen before SYSREF_MONITOR_OUT is updated.
SYSREF_MONITOR_TD_COARSE	4	0	R/W	Sets the number of coarse delays (45ps) in the t_d block.
SYSREF_MONITOR_TD_FINE	4	0	R/W	Sets the fine delay in the t_d block. td_fine = (floor(SYSREF_MONITOR_TD_FINE/2)*15ps) + ((SYSREF_MONITOR_TD_FINE%2)*4ps)
SYSREF_MONITOR_OUT	8	0	R	SYSREF monitor output. Bit 0 corresponds to the earliest CLK edge and bit 7 corresponds to the latest CLK edge. The SYSREF_MONITOR_OUT can only be in one of the following states and can be interpreted as follows: State 0: One or more zeros followed by one or more ones. A rising of SYSREF transition is in the SYSREF monitor window and set up and hold violation is detected. SYSREF_LAT must be delayed until all zeros or all ones are observed. State 1: all zeros. CLK is leading SYSREF_LAT and SYSREF_LAT is latched properly by the next CLK rising edge. State 2: all ones CLK is lagging SYSREF_LAT and SYSREF_LAT is latched properly by the current CLK rising edge.

7.3.5 Digital Signal Processor (DSP) Features

The device includes several different digital features in the digital signal processing block:

- 12-bit fractional delay with one sampling clock cycle range and a delay step size equal to $1/(2^{12} * t_{CLK})$
- Programmable FIR filter for equalization with up to 96-taps per channel
- Multiple digital down converters (DDCs) supporting decimation factors of /2, /3 and /5 up to /32768
- Additional programmable FIR filter for equalization post decimation

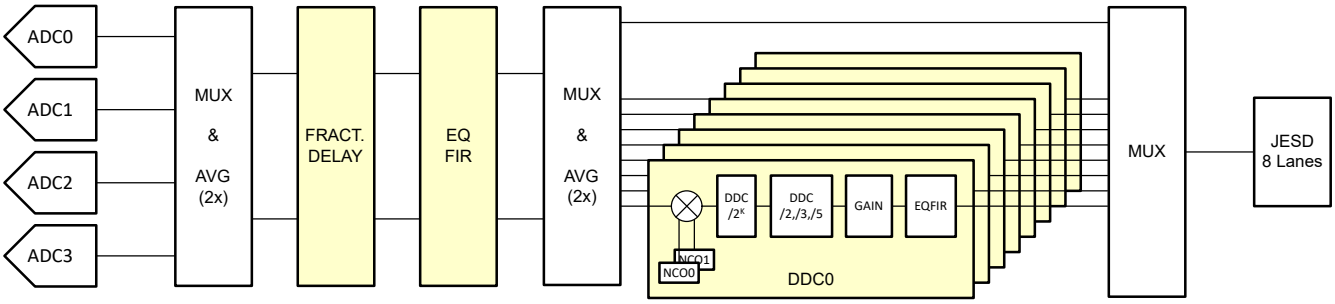


Figure 7-11. Digital signal processing chain

7.3.5.1 DSP Input Mux

There are 4 digital multiplexers at the input of the DSP blocks as shown in Figure 7-12. The bus is referred to adc_out[3:0] where each index refers to the unique output stream of a particular ADC, meaning, the ADC0 output is adc_out[0] and so on. The output of each DSP_IN mux corresponds to a single DSP input data stream for the DSP blocks. The aggregate set of DSP input data streams is referred to as dsp_in[3:0]. dsp_in[0] corresponds to the 0th DSP input data stream. Each DSP input data stream can be sourced from one of the following:

- One of two adc_out streams (adc_out[0] and any one of the others). This is denoted by C(2,1).
- The average of two adc_out streams.

Note

The nomenclature C(n,k) represents the possible combinations of choosing k items from a set containing n distinct items.
For example, assuming we have a set adc_out={adc0,adc1,adc2,adc3}, there are 6 distinct ways to select two items from the set which can be seen here: C(adc_out,2)={{ADC0,ADC1},{ADC0,ADC2},{ADC0,ADC3},{ADC1,ADC2},{ADC1,ADC3},{ADC2,ADC3}}

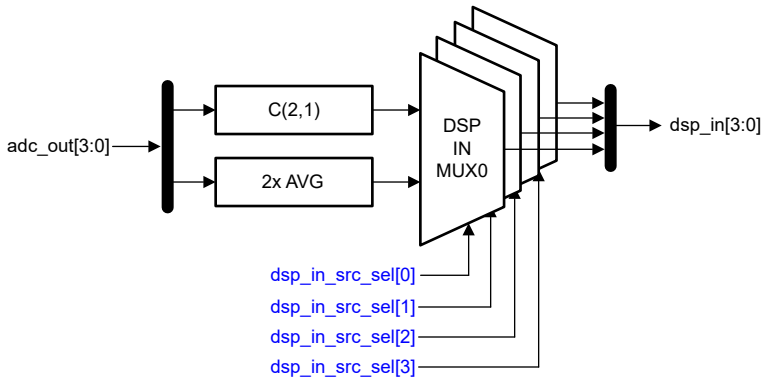


Figure 7-12. DSP Input Mux Overview

The following parameters can be programmed:

Table 7-8. DSP Input Mux Configuration Programming (x = 0,1,2,3)

System Parameter Name	Size	Default	Access	Description
DSP_IN_SRC_SEL{x}	4	0,1,2,3	R/W	Select the input data source for the dsp_in[0..3] input stream to the DSP blocks. 0: ADC0 data. 1: ADC1 data. 2: ADC2 data. 3: ADC3 data. 4: 2x average of ADC0 and ADC1. 5: 2x average of ADC0 and ADC2. 6: 2x average of ADC0 and ADC3. 7: 2x average of ADC1 and ADC2. 8: 2x average of ADC1 and ADC3. 9: 2x average of ADC2 and ADC3. Others: not used

7.3.5.2 Fractional Delay

The device includes an optional programmable 12-bit fractional digital delay after the DSP input mux (see Figure 7-13). There are two independent digital fractional delay blocks - FDF0 and FDF1. Each FDF block is connected to two input streams (dsp_in[1:0] or dsp_in[3:2]) where each input stream has a programmable fractional delay value, t_{d00} and t_{d01} for dsp_in[1:0] and t_{d10} and t_{d11} for dsp_in[3:2]. The FDF blocks output a total of four data streams (fdf_out[3:0]) where each output stream corresponds to a distinct fractionally delayed input stream.

The fractional delay is a *true time delay* implementation with a linear phase across frequencies. The fractional delay calculates to:

Fractional Delay [sampling clock period] = Delay / 4096x T_S (sampling period).

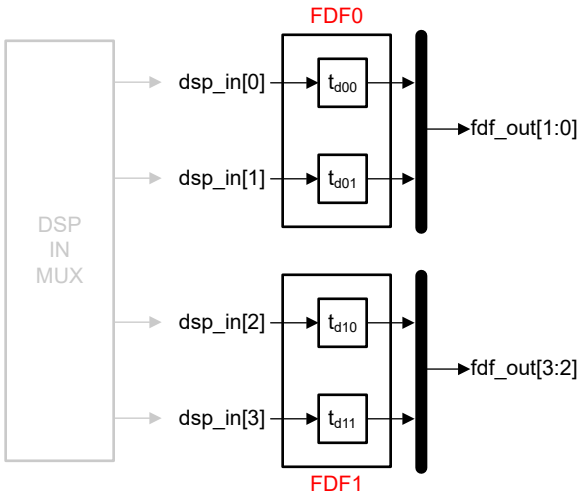


Figure 7-13. Fractional Delay Feature

As an example, a setting of 2048 equals ½ a clock cycle delay as shown in Figure 7-14. The magnitude error is less than −80dB (vs desired delay).

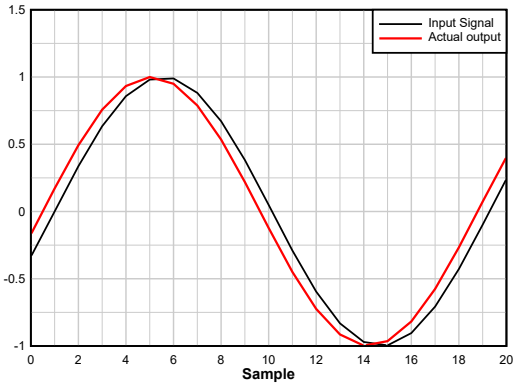


Figure 7-14. Fractional delay = ½ clock cycle (delay setting = 2048)

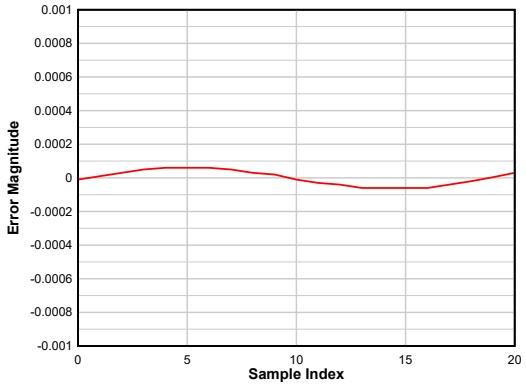


Figure 7-15. Error magnitude (desired vs actual waveform)

The fractional delay is configured via SPI register writes and the programmed delay is internally translated into filter coefficients. The filter response is shown in Figure 7-16 and Figure 7-17. The passband is approximately 85% of the Nyquist zone. Reprogramming the fractional delay can take up to 2µs to update the filter coefficients.

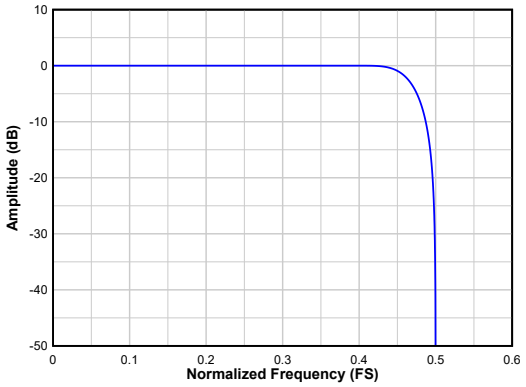


Figure 7-16. Filter response of the fractional delay FIR

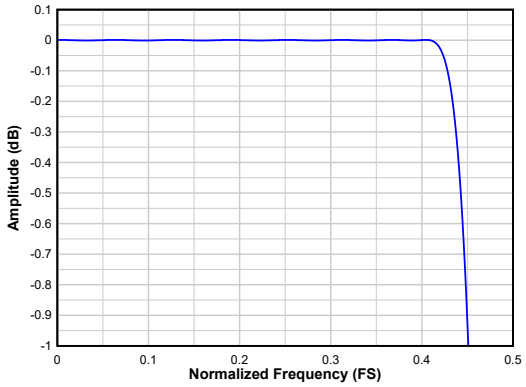


Figure 7-17. Filter response of the fractional delay FIR (zoom)

The fractional delay can be can be programmed using the following parameters:

Table 7-9. Fractional Delay Configuration Programming

System Parameter Name	Size	Default	Access	Description
FDF0_DELAY_VAL_0_LSB	8	0	R/W	Bits [7:0] of the fractional delay value for 0th input data stream to FDF0.
FDF0_DELAY_VAL_0_MSB	4	0	R/W	Bits [11:8] of the fractional delay value for 0th input data stream to FDF0.
FDF0_DELAY_VAL_1_LSB	8	0	R/W	Bits [7:0] of the fractional delay value for 1st input data stream to FDF0.
FDF0_DELAY_VAL_1_MSB	4	0	R/W	Bits [11:8] of the fractional delay value for 1st input data stream to FDF0.
FDF1_DELAY_VAL_0_LSB	8	0	R/W	Bits [7:0] of the fractional delay value for 0th input data stream to FDF1.
FDF1_DELAY_VAL_0_MSB	4	0	R/W	Bits [11:8] of the fractional delay value for 0th input data stream to FDF1.
FDF1_DELAY_VAL_1_LSB	8	0	R/W	Bits [7:0] of the fractional delay value for 1st input data stream to FDF1.
FDF1_DELAY_VAL_1_MSB	4	0	R/W	Bits [11:8] of the fractional delay value for 1st input data stream to FDF1.

7.3.5.3 Programmable FIR Filter for Equalization

The ADC32RF7x includes an integrated programmable FIR filter block referred to as an equalizer (EQ). As illustrated in Figure 7-18, there are two EQ blocks (EQ0 and EQ1) which are located at the output of the fractional delay filters (FDF0/1). Each EQ block can source the input data stream from either dsp_in directly or from the preceding FDF block. There are a total of four output data streams (eq_out[3:0]) where each output stream corresponds to a distinct filtered input stream.

Each of the two equalizers (EQ0/EQ1) include up to 192-taps (16-bit) shared across two input streams.

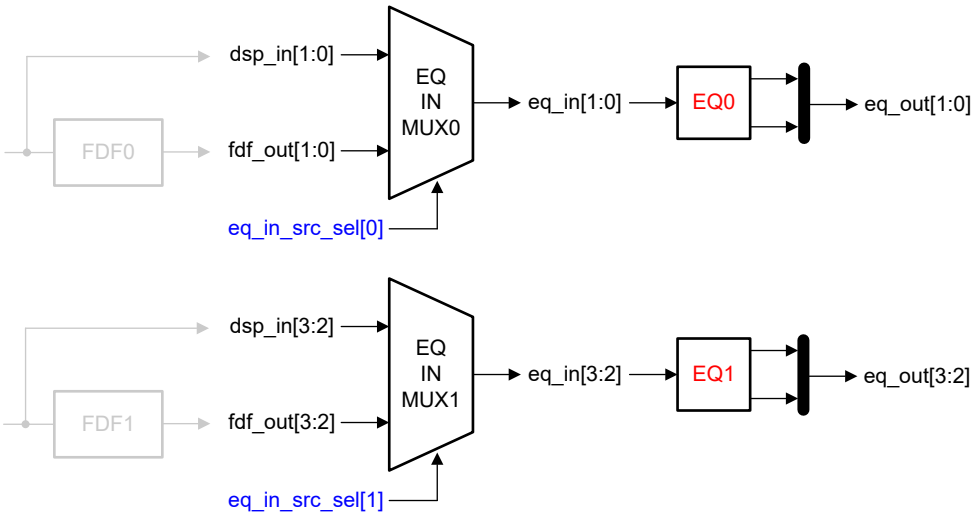


Figure 7-18. FIR Equalizer Configurations

Each EQ supports several different configurations with up to 192-taps per EQFIR as shown in Figure 7-19.

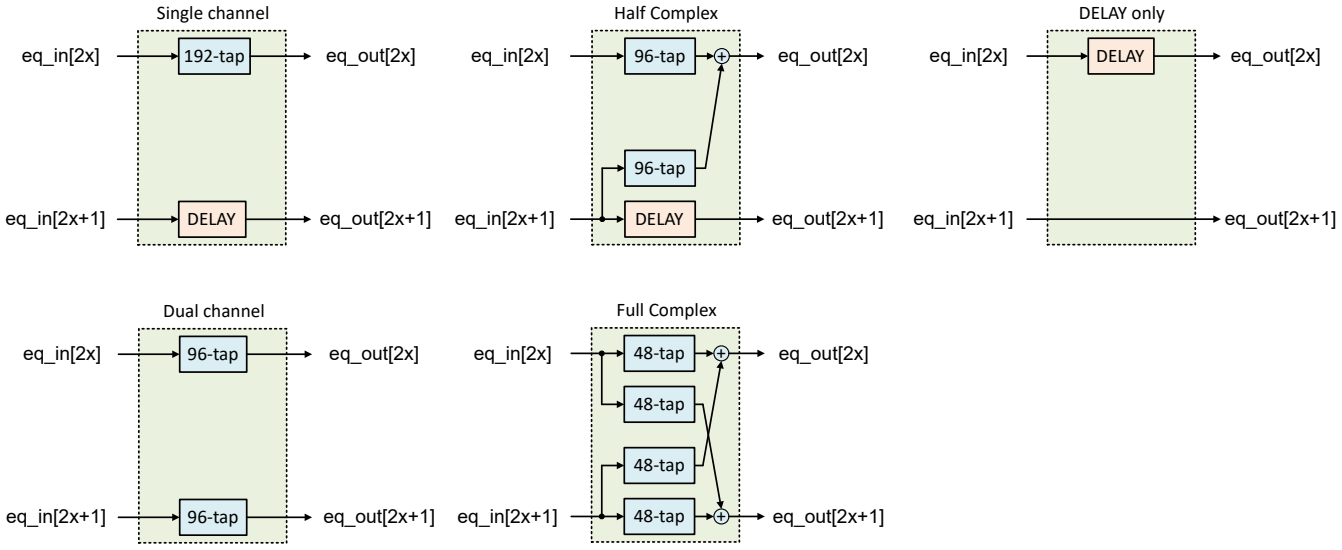


Figure 7-19. FIR Equalizer Configurations for EQ0 (x=0) and EQ1 (x=1)

The power consumption scales linearly with sampling rate and with # of taps used. Unused taps can be set to 0.

The digital equalizer can be can be programmed using the following parameters:

Table 7-10. EQ{x} Configuration Programming (x= 0,1)

System Parameter Name	Size	Default	Access	Description
EQ{x}_IN_SRC_SEL	1	0	R/W	Select EQ{x} input data source. 0: EQ{x} input from DSP_IN[2x+1, 2x]. 1: EQ{x} input from FDF_OUT[2x+1, 2x].
EQ{x}_MODE_SEL	3	0	R/W	Select EQ{x} mode. 0: Single channel mode. 1: Dual channel mode. 2: Half complex mode. 3: Full complex mode. 4: Delay only mode.
EQ{x}_DEL_VAL	8	0	R/W	EQ{x} delay value. The effect of this setting is dependent on the EQ{x} mode. 0...255: Number of device clock cycles delay that is applied when EQ{x} is in a mode with a programmable delay.
EQ{x}_NUM_TAPS	8	0	R/W	Number of taps to be used by EQ{x} in a given mode. Can be any value when in single channel mode. Has to be even in dual channel mode and half complex mode. Has to be divisible by four in full complex mode. 1...192: Number of taps to be used by EQ{x}.
EQ{x}_TAPS	3072	0	R/W	Set the 192 taps of the EQ{x} block. Single channel mode: Up to 192 taps are applied to eq_input[2x]. Dual channel mode: Up to 96 taps per eq_input. First 96 taps apply to eq_input[2x]. Second 96 taps apply to eq_input[2x+1]. Half complex mode: Up to 96 taps per eq_input. First 96 taps apply to eq_input[2x]. Second 96 taps apply to eq_input[2x+1]. Full complex mode: Up to 96 taps per eq_input. First 96 taps apply to eq_input[2x]; the first 48 of those taps apply to eq_output[2x]. Second 96 taps apply to eq_input[2x+1]; the first 48 of those taps apply to eq_output[2x].

7.3.5.4 DSP Output Mux

There are several different multiplexers available at the output of the DSP prior to the DDCs.

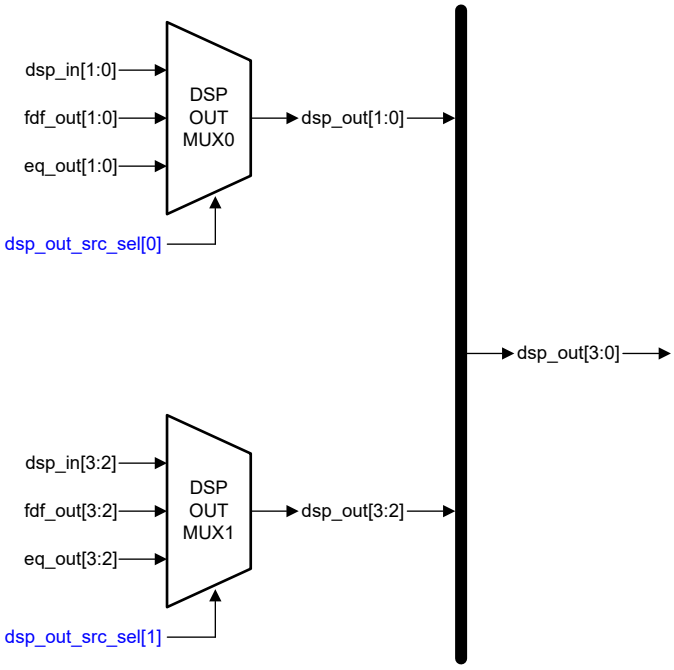


Figure 7-20. DSP Output Mux

The following parameters can be programmed:

Table 7-11. Input Selection to the DDC Programming (x = 0 or 1)

System Parameter Name	Size	Default	Access	Description
DSP_OUT_SRC_SEL{x}	2	0	R/W	Select the output data source for DSP_OUT_MUX{x} from the DSP blocks. 0: dsp_in[2x+1,2x] as output of DSP_OUT_MUX{x}. 1: fdf_out[2x+1,2x] as output of DSP_OUT_MUX{x}. 2: eq_out[2x+1,2x] as output of DSP_OUT_MUX{x}.

7.3.5.5 Digital Down Converter (DDC)

The ADC32RF7x includes 8 digital down converters (DDCs) with independent NCOs. Each DDC supports base decimation factors of 2, 3 or 5 with decimation ratios from /2 to /32768 (/3 .. /96 and /5... /80). The maximum decimation setting allowed is dependent on sampling rate, number of DDCs, sample repeat factor (only with factors of 2) and the JESD output resolution 'N' due to the 4Gbps minimum SERDES lane rate required by the device. Additionally, the final /2 stage supports programmable coefficients.

A crossbar mux is used to connect any DDC input to any ADC or the output of the 2x averaging block. The ADC32RF7x DDCs can be configured to have independent decimation factors (binary factors only).

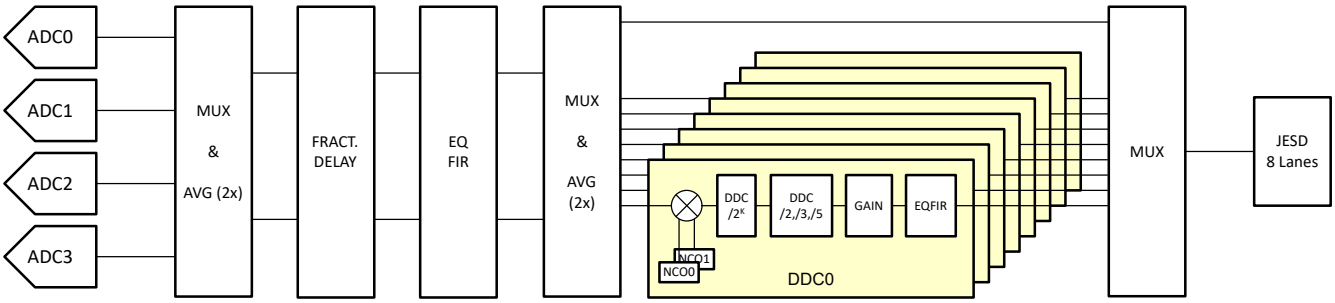


Figure 7-21. Multi-Band Decimation Filter

Real and complex decimation is supported and the passband is approximately 80% of the decimated bandwidth.

Table 7-12. Complex Decimation Setting vs Output Bandwidth

Decimation Factor	Complex Output Bandwidth per DDC	Real Output Bandwidth per DDC
N	0.8x F_S / N	0.8x F_S / (2N)

7.3.5.5.1 Decimation Filter Input

There are several different multiplexers available at the input of each of the 8x DDC as shown in Figure 7-22. Each DDC has a DDC_REAL_DATA_MUX and DDC_INPUT_DATA_TYPE_MUX. The DDC input data type is based on the ddc_mode setting.

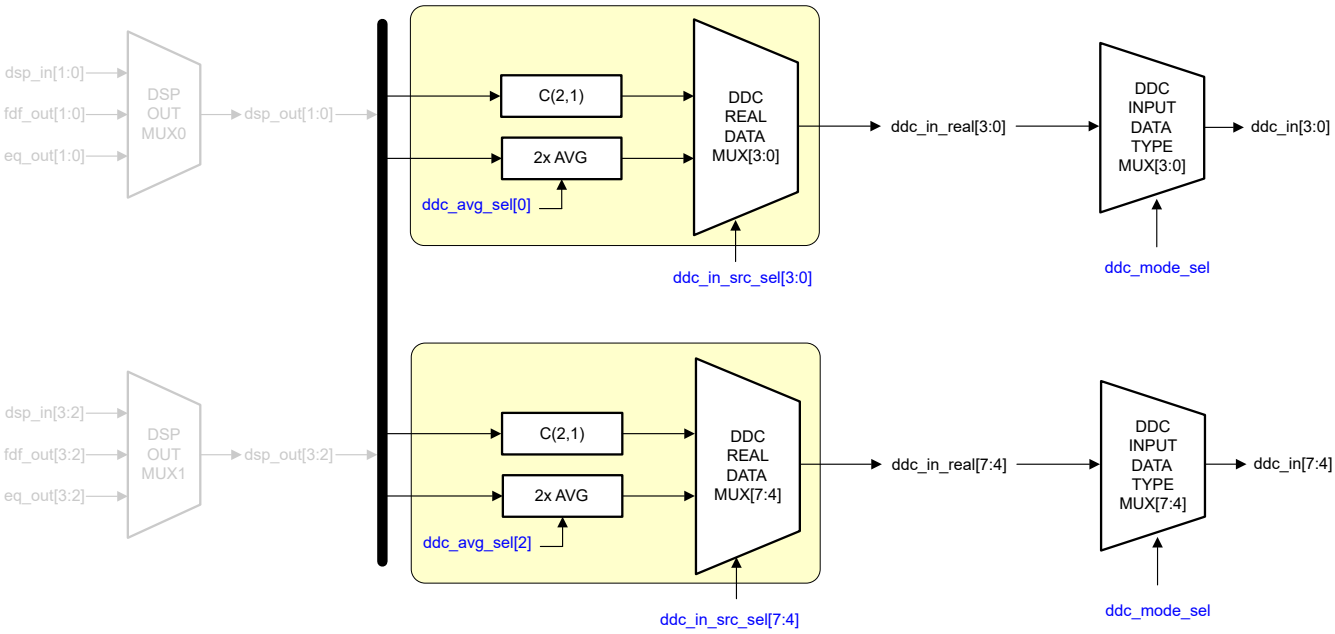


Figure 7-22. DDC Input Data Muxing

The following parameters can be programmed:

Table 7-13. Input Selection to the DDC Programming

System Parameter Name	Size	Default	Access	Description
DDC_AVG__SEL{0,2}	3	..	R/W	Select the two data streams to be averaged in the 2x AVG as a shared input for the multiplexers DDC_REAL_DATA_MUX[3:0]/[7:4]. 0: Average of dsp_out[0] and dsp_out[1]. 1: Average of dsp_out[0] and dsp_out[2]. 2: Average of dsp_out[0] and dsp_out[3]. 3: Average of dsp_out[1] and dsp_out[2]. 4: Average of dsp_out[1] and dsp_out[3]. 5: Average of dsp_out[2] and dsp_out[3].
DDC_IN_SRC_SEL{0..7}	5	..	R/W	Select the data source for DDC{0..7}. All DDC data must come exclusively from only one of the multiplexers. 0: dsp_out[0] as real input to the DDC. 1: dsp_out[1] as real input to the DDC. 2: dsp_out[2] as real input to the DDC. 3: dsp_out[3] as real input to the DDC. 4: Output of the first 2x AVG block (DDC_AVG_SEL_0/2) block as real input to the DDC. 5: Output of the second 2x AVG block (DDC_AVG_SEL_1/3) block as real input to the DDC. 6: Average of dsp_out[0], dsp_out[1], dsp_out[2], and dsp_out[3] as real input to the DDC.

Table 7-13. Input Selection to the DDC Programming (continued)

System Parameter Name	Size	Default	Access	Description
DDC_EN_CTRL	8	0	R/W	Individual DDC enable control. Each bit corresponds to one DDC where the LSB corresponds to DDC0. If the enable bit is set then the corresponding DDC is enabled. Bit 0: DDC0 power down control. Bit 1: DDC1 power down control. Bit 2: DDC2 power down control. Bit 3: DDC3 power down control. Bit 4: DDC4 power down control. Bit 5: DDC5 power down control. Bit 6: DDC6 power down control. Bit 7: DDC7 power down control.
DDC_MODE_SEL	3	0	R/W	Select the DDC mode which is shared across all DDCs. 0: Pass-through mode; The particular DDC is unused 1: Real input (from the DDC_REAL_DATA_MUX) given to the DDCs is low pass filtered and down sampled by the decimation factor. 2: Real input (from the DDC_REAL_DATA_MUX) given to the DDCs is mixed with an NCO to produce a complex output. The complex output is low pass filtered and down sampled by the decimation factor.

7.3.5.5.2 Decimation Modes

There are 2 different decimation modes supported and all 8x DDCs must be configured to the same mode:

- **Real decimation**: The real input is low pass filtered and the filter output is down sampled by the decimation factor (M). The output of the DDC block in this mode is a real signal and detailed DDC chain is shown in Figure 7-23.
- **Complex decimation with real input**: The DDC is given a real input that is mixed with an NCO to produce a complex output. The complex output is low pass filtered and down sampled by the decimation factor (M). The output of the DDC block in this mode is a complex signal and detailed DDC chain is shown in Figure 7-25.

Each DDC has an enable control signal. If the DDC is disabled, the output is zero. The following blocks are part of the DDC signal chain:

- **Decimation**: The possible decimation factors are B x 2^N where the base factor B can be 1, 3 or 5 and N can be a maximum of 15 for B = 1, 5 for B = 3 and 4 for B = 5.

  When the base factor is 3 or 5, all the DDCs must share the same decimation factor setting. However, when the base factor is 1 (decimations factors that are powers of 2), having an independent decimation factors per DDC is possible since each DDC has a samples repeater block. When each DDC is configured to a different decimation factor, the samples repeater for each DDC is adjusted so that all the DDC outputs are rate matched to highest data rate DDC. For example, if two DDCs are active and one is configured in decimation by 4 and the other in decimation by 16, the DDC configured for decimation by 16 automatically gets rate matched to the decimation by 4 rate by repeating the samples by a factor of 4. Upon successful configuration, the repeat factor can be readback for each DDC.

  Note

  Independent decimation factors are not supported when any DDC is configured for decimation by 2. When decimation by 2 is used all other DDCs must be also be set to by 2.

  Repeat Factor: The repeat factor is adjusted automatically for each DDC in cases where the effective JESD line rate is below the lower threshold of 4Gbps. The repeat factor block is not available with base factors of 3 and 5.
- **DDC_PFIR**: The ADC32RF72 has an integrated programmable FIR filter block in the decimation chain where the last stage filter is completely programmable. This feature is only available with decimation factors that are powers of 2 (B = 1). The block is referred to as the DDC_PFIR. Each DDC_PFIR has up to 96 total taps (across both inputs in complex decimation) with 17-bit resolution.
- **DDC coarse gain (G)**: The fixed digital gain can be applied to each DDC path where the gain G is an element of {0dB, 3dB, 6dB} and controllable for each DDC through the ddc_coarse_gain[7:0] signal.
- **DDC_EQ**: The DDC_EQ supports all the same modes the as the Digital DSP EQ.

  Note

  This EQ is not available for decimation factors of 2 and 3.
- **DDC_COMPLEX_GAIN**: Each DDC has a programmable complex gain. In real decimation mode, only the real part of the gain is applied. The gain is in steps of 0.1dB from 0dB to 6dB; an independent gain setting is available for the real and imaginary parts.

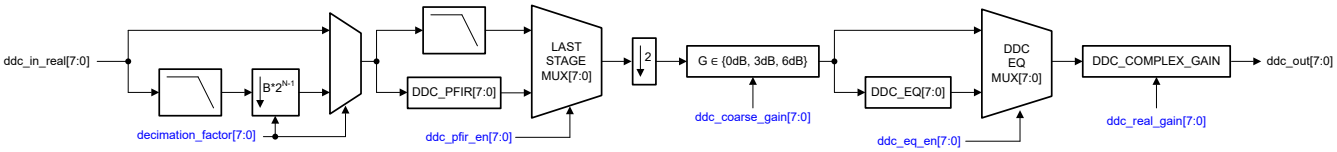


Figure 7-23. Real Decimation Signal Chain (decimation factors that are powers of 2 (B = 1))

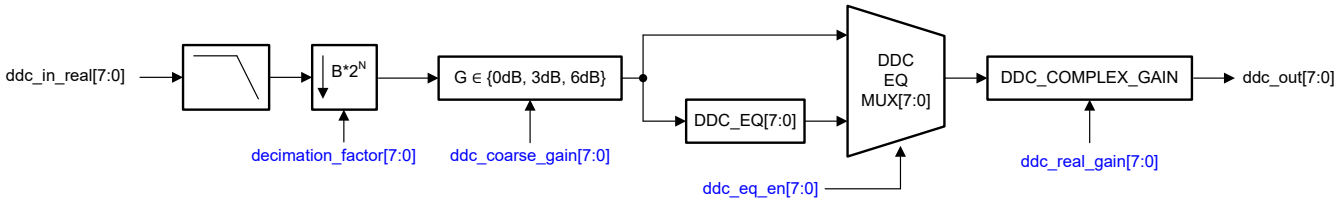


Figure 7-24. Real Decimation Signal Chain (decimation factors of 3 and 5 (B = 3, 5)

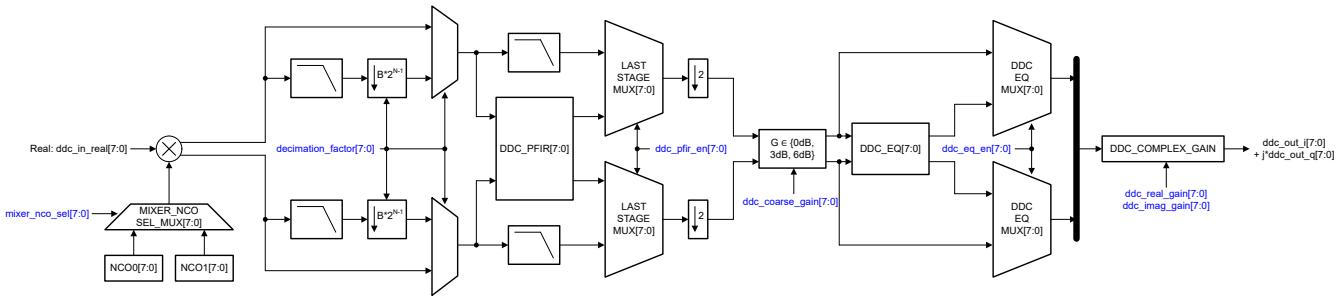


Figure 7-25. Complex Decimation Signal Chain (decimation factors of 2 (B = 1)

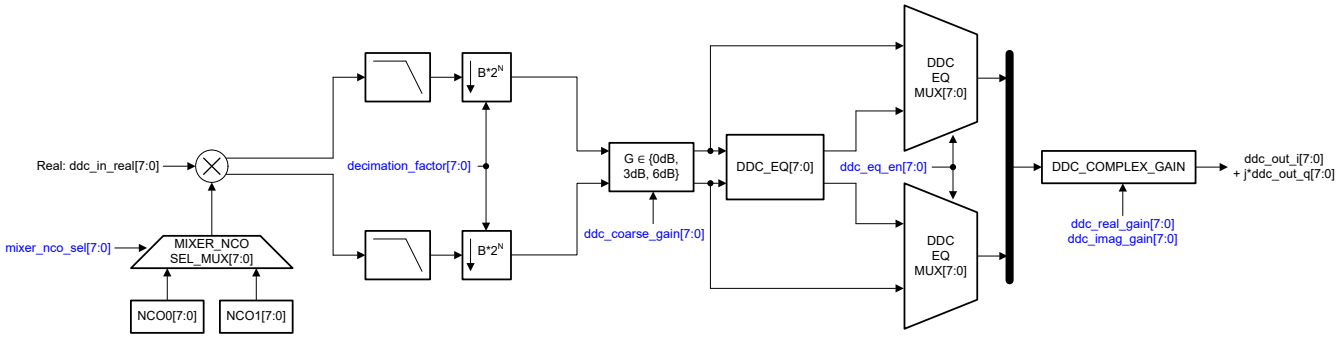


Figure 7-26. Complex Decimation Signal Chain (decimation factors of 3 and 5 (B = 3, 5)

The following parameters can be programmed:

Table 7-14. Input Selection to the DDC Programming

Function Name	Size	Default	Access	Description
DDC{0..7}_DECIMATION_FACTOR_LSB	8	1	R/W	Set bits[15:0] of the 16-bit decimation factor for the DDC. Possible decimation factors are: [2, 3, 4, 5, 6, 8, 10, 12, 16, 20, 24, 32, 40, 48, 64, 80, 96, 128, 256, 512, 1024, 2048, 4096, 8192, 16384, 32768]
DDC{0..7}_DECIMATION_FACTOR_MSB	8	0	R/W	
DDC{0..7}_REPEAT_FACTOR_LSB	8	1	R	Bits[13:0] of the 14-bit repeat factor for the DDC.
DDC{0..7}_REPEAT_FACTOR_MSB	6	0	R	
DDC{0..7}_PFIR_EN	1	0	R/W	Control the DDC_PFIR enable. 0: DDC_PFIR is disabled and a fixed decimation filter is used as the last stage filter. 1: DDC_PFIR is enabled and a programmable decimation filter is used as the last stage filter.
DDC{0..7}_PFIR_MODE_SEL	1	0	R/W	Select the DDC_PFIR mode. 0: Single channel mode. 1: Dual channel mode.
DDC{0..7}_PFIR_NUM_TAPS	7	0	R/W	Number of taps to be used by DDC_PFIR in a given mode. Can be any value when in single channel mode. Has to be even in dual channel mode. 1...96: Number of taps to be used by the DDC_PFIR.

Table 7-14. Input Selection to the DDC Programming (continued)

Function Name	Size	Default	Access	Description
DDC{0..7}_PFIR_TAPS	3072	0	R/W	Set the 96 taps of the DDC_PFIR block. Only 17 bits are written. Single channel mode: Up to 96 taps are applied to ddc_pfir_input[0]. Dual channel mode: Up to 48 taps per ddc_pfir_input. First 48 taps apply to ddc_pfir_input[0]. Second 48 taps apply to ddc_pfir_input[1].
DDC{0..7}_EQ_EN	1	0	R/W	Control the DDC_EQ enable. 0: DDC_EQ is disabled and bypassed. 1: DDC_EQ is enabled and the DDC_EQ filter is applied to the DDC output.
DDC{0..7}_EQ_MODE_SEL	3	0	R/W	Select the DDC_EQ mode. 0: Single channel mode. 1: Dual channel mode. 2: Half complex mode. 3: Full complex mode. 4: Delay only mode.
DDC{0..7}_EQ_DEL_VAL	7	0	R/W	DDC_EQ delay value. The effect of this setting is dependent on the DDC_EQ mode. 0...127: Number of device clock cycles delay that is applied when DDC_EQ is in a mode with a programmable delay.
DDC{0..7}_EQ_NUM_TAPS	7	0	R/W	Number of taps to be used by DDC_EQ in a given mode. Can be any value when in single channel mode. Has to be even in dual channel mode and half complex mode. Has to be divisible by four in full complex mode. 1...96: Number of taps to be used by DDC_EQ.
DDC{0..7}_EQ_TAPS	1536	0	R/W	Set the 96 taps of the DDC_EQ block. Single channel mode: Up to 96 taps are applied to ddc_eq_input[0]. Dual channel mode: Up to 48 taps per ddc_eq_input. First 48 taps apply to ddc_eq_input[0]. Second 48 taps apply to ddc_eq_input[1]. Half complex mode: Up to 48 taps per ddc_eq_input. First 48 taps apply to ddc_eq_input[0]. Second 48 taps apply to ddc_eq_input[1]. Full complex mode: Up to 48 taps per ddc_eq_input. First 48 taps apply to ddc_eq_input[0]; the first 24 of those taps apply to ddc_eq_output[0]. Second 48 taps apply to ddc_eq_input[1]; the first 24 of those taps apply to ddc_eq_output[0].
DDC{0..7}_COARSE_GAIN	3	0	R/W	Set a fixed digital gain in the DDC data path before the DDC_EQ. 0: 0dB digital gain. 3: 3dB digital gain. 6: 6dB digital gain (useful when using complex decimation).
DDC{0..7}_REAL_GAIN	6	0	R/W	Real part of the complex gain applied to the DDC output. The gain is in 0.1dB steps starting from to 0dB to 6dB. 0..60: Effective gain is DDC_REAL_GAIN*0.1dB
DDC{0..7}_IMAG_GAIN	6	0	R/W	Imaginary part of the complex gain applied to the DDC output (used in complex decimation modes). The gain is in 0.1dB steps starting from to 0dB to 6dB. 0..60: Effective imaginary gain is DDC_IMAG_GAIN*0.1dB

7.3.5.5.3 Decimation Filter Response

This section provides the different decimation filter responses with a normalized ADC sampling rate. The complex filter pass band is approximately 80% (−0.1dB) of the decimated bandwidth with a minimum of 85dB stop band rejection.

The decimation filter responses are normalized to the ADC sampling clock frequency F_S. One example (decimation by 4) is illustrated in Figure 7-28 and Figure 7-29. The filter responses for all other decimation filter plots are available in the product folder.

The decimation filter plots are interpreted as follows: Each figure contains the filter pass-band, transition bands and alias or stop-bands as shown in Figure 7-27. The x-axis shows the offset frequency (after the NCO frequency shift) normalized to the ADC sampling rate F_S.

For example, in the divide-by-4 complex setup, the output data rate is F_S / 4 complex with a Nyquist zone of F_S / 8 or 0.125 × F_S. The transition band (colored in blue) is centered around 0.125 × F_S and the alias transition band is centered at 0.375 × F_S. The stop-bands (colored in red), which alias on top of the pass-band, are centered at 0.25 × F_S and 0.5 × F_S. The stop-band attenuation is greater than 85dB.

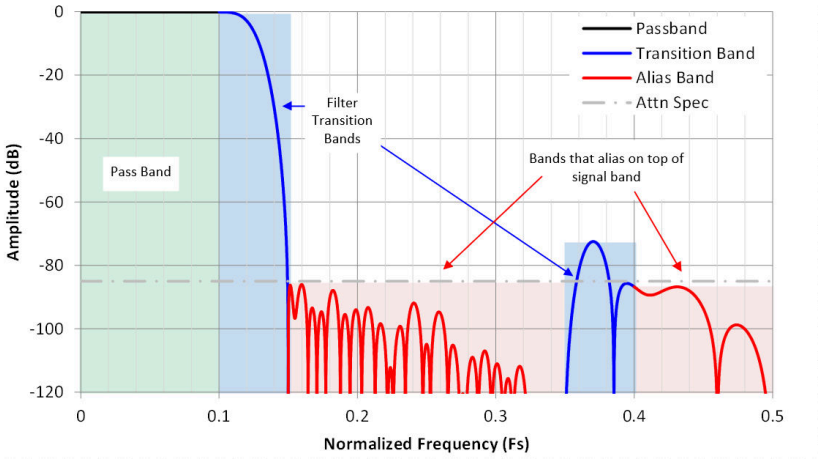


Figure 7-27. Interpretation of the Decimation Filter Plots

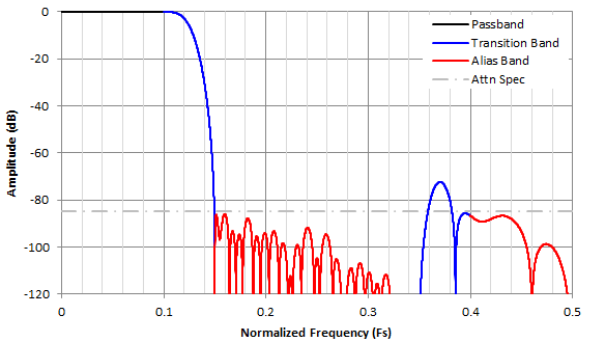


Figure 7-28. Decimation by 4 Filter Response

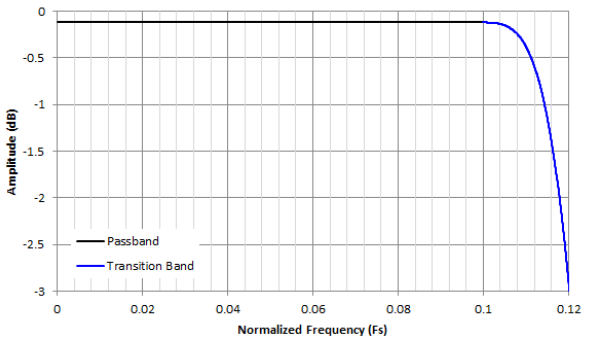


Figure 7-29. Decimation by 4 Passband Ripple Response

7.3.5.5.4 Numerically Controlled Oscillator (NCO)

FS = ADC sampling rate (MSPS)

Each digital down-converter (DDC) uses a 48-bit numerically controlled oscillator (NCO) to fine tune the frequency placement prior to the digital filtering as shown in Figure 7-30. The NCO frequency range is $-F_S/2$ to $F_S/2$ and is dictated by a frequency control word (FCW) and phase offset.

There are two different NCO frequencies for each DDC. The desired NCO frequency is programmed via SPI and can be selected using SPI or the GPIO pins. When using the GPIO pins for NCO frequency control, frequency hopping can be achieved in less than 1µs.

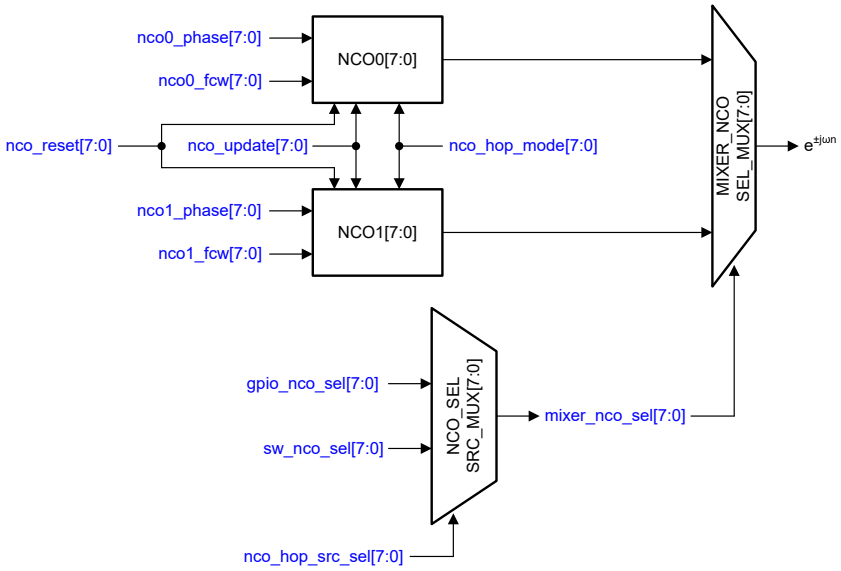


Figure 7-30. NCO block diagram with all control signals

Infinite Phase Coherent NCO: With a phase coherent NCO, all frequencies are synchronized to a single event using SYSREF. This enables an infinite amount of frequency hops without the need to reset the NCO as phase coherency is maintained between frequency hops. This is illustrated in Figure 7-31 (right). When returning to the original frequency f_1, the NCO phase appears as if the NCO had never changed frequencies.

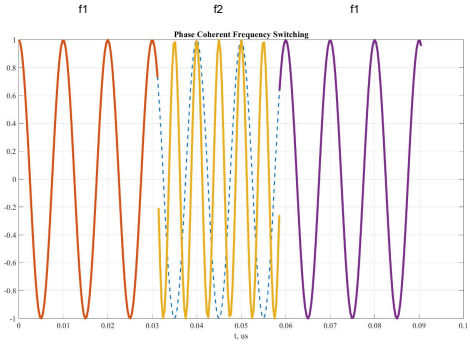


Figure 7-31. Infinite Phase Coherent NCO Frequency Switching

The oscillator generates a complex exponential sequence of: $e^{j\omega n}$ (default) or $e^{-j\omega n}$

where: frequency (ω) is specified as a signed number by the 48-bit FCW

The complex exponential sequence is multiplied with the real input from the ADC to mix the desired carrier to a frequency equal to $f_{IN} + f_{NCO}$. The NCO frequency can be tuned from $-F_S/2$ to $+F_S/2$ and is processed as a signed, 2s complement number.

The FCW setting is set by the 48-bit register value given and calculated as:

$$\text{NCO frequency (0 to + } F_S/2\text{): NCO} = f_{NCO} \times 2^{48} / F_S \quad (3)$$

$$\text{NCO frequency (-}F_S/2\text{ to 0): NCO} = (f_{NCO} + F_S) \times 2^{48} / F_S \quad (4)$$

where:

- NCO = FCW (decimal value)
- f_{NCO} = Desired NCO frequency (MHz)
- F_S = ADC sampling rate (MSPS)

7.3.5.5.4.1 NCO Update

The NCO FCW and phase can be updated dynamically. Additionally, the NCO update signal can be masked for each DDC (nco_update_mask[7:0]). The NCO update signal can be sourced from software (sw_nco_sync), or by leaking the internal SYSREF (SYSREF_INT) to update the NCOs. Updating the NCO FCW and phase is a two step process:

1. The new FCW and phase must be written
2. An nco_update signal must be issued to apply the new NCO settings

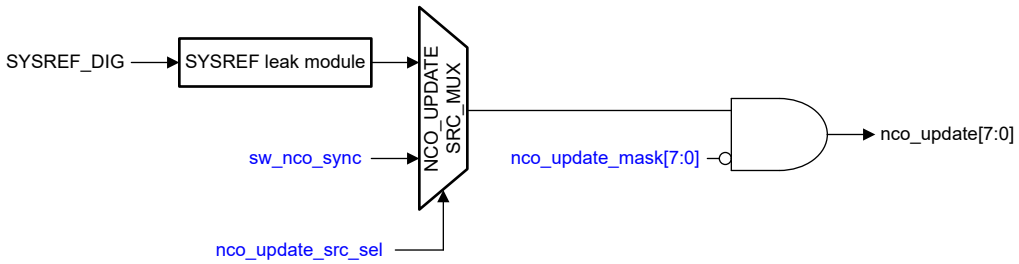


Figure 7-32. NCO Update With All Control Signals

The nco_update_mask[7:0] is used to mask the nco_update signal from specific DDCs, thereby; allowing the update of the NCO for only a subset of the DDCs. When the NCO update signal is sourced from software (sw_nco_sync), the nco_update_mask for DDC [x] and DDC[x+1], where $x \in \{0,2,4,6\}$, must be configured identically as the sw_nco_sync signal is shared for DDC [x] and DDC[x+1].

7.3.5.5.4.2 NCO RESET

The NCO phase accumulator can be reset for each NCO through an nco_reset signal. The NCO reset can be masked for each DDC (nco_reset_mask[7:0]). The NCO reset signal can be sourced from software (sw_nco_sync) or the NCOs can be armed through a GPIO to be reset on the next SYSREF edge.

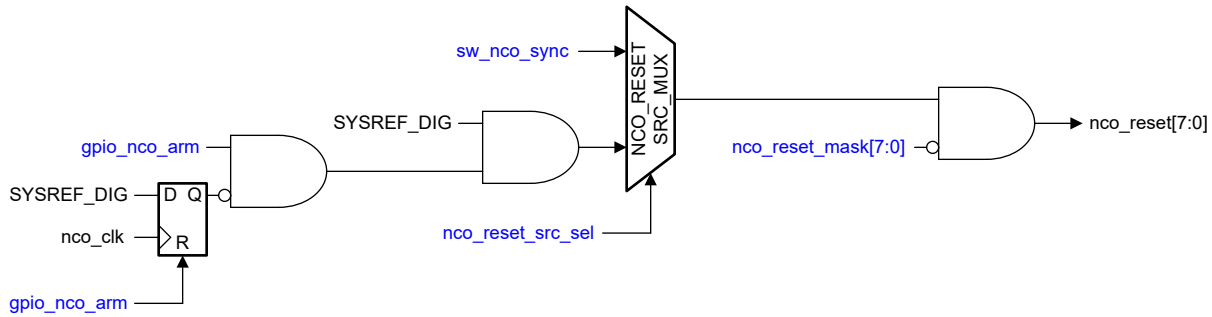


Figure 7-33. NCO RESET With All Control Signals

The gpio_nco_arm NCO reset path is used to synchronize multiple NCOs across devices from a host device. The host device can launch the gpio_nco_arm on the falling edge of the SYSREF to give the maximum time for the gpio_nco_arm signal to reach all devices prior to the next SYSREF edge.

The following registers can be programmed:

Table 7-15. Mixer and NCO Programming

System Parameter Name	Size	Default	Access	Description
DDC_NCO_UPDATE_SRC_SEL	1	0	R/W	Select the source of the NCO update signal. 0: The NCO update signal is sourced from software. 1: Leaking the internal SYSREF (SYSREF_DIG) to update the NCOs.
DDC_NCO_RESET_SRC_SEL	1	0	R/W	Select the source of the NCO reset signal. 0: The NCO reset signal is sourced from software. 1: The GPIO arm signal (gpio_nco_arm) arms the NCO module so that an NCO update signal is issued on the next rising edge of SYSREF.
DDC_NCO_UPDATE_MASK	8	0	R/W	Per DDC NCO update signal masking control. If the NCO update source is from software, DDC[x] and DDC[x+1], where x ∈ {0,2,4,6}, must be configured identically. Setting the mask bit to 1 makes sure the respective DDC NCOs are masked from the NCO update signal. Bit 0: DDC0 NCO update mask control. Bit 1: DDC1 NCO update mask control. Bit 2: DDC2 NCO update mask control. Bit 3: DDC3 NCO update mask control. Bit 4: DDC4 NCO update mask control. Bit 5: DDC5 NCO update mask control. Bit 6: DDC6 NCO update mask control. Bit 7: DDC7 NCO update mask control.
DDC_NCO_RESET_MASK	8	0	R/W	Per DDC NCO reset signal masking control. If the NCO reset source is from software, DDC[x] and DDC[x+1], where x ∈ {0,2,4,6}, must be configured identically. Setting the mask bit to 1 makes sure the respective DDC NCOs are masked from the NCO reset signal. Bit 0: DDC0 NCO update reset control. Bit 1: DDC1 NCO update reset control. Bit 2: DDC2 NCO update reset control. Bit 3: DDC3 NCO update reset control. Bit 4: DDC4 NCO update reset control. Bit 5: DDC5 NCO update reset control. Bit 6: DDC6 NCO update reset control. Bit 7: DDC7 NCO update reset control.
DDC{0..7}_NCO_HOP_SRC_SEL	1	0	R/W	Select the source of the NCO hoping signal for the DDC. 0: NCO selection (frequency hopping) through GPIO (one GPIO function per DDC). 1: NCO selection (frequency hopping) through software.
DDC{0..7}_NCO_HOP_MODE	1	0	R/W	Select the NCO mode when hopping. 0: Not used 1: Phase coherent hopping mode where the original phase of the NCOs is always maintained across hops.
DDC{0..7}_NCO{0,1}_FCW	48	0	R/W	48-bit FCW word for NCO{0,1}
DDC{0..7}_NCO{0,1}_PHASE	19	0	R/W	19-bit phase offset for NCO{0,1}

7.3.6 Digital Output Interface

The ADC32RF7x supports two different digital output data interfaces:

1. JESD204B/C: This interface uses up to 8 serial output lanes supporting data rates of up to 16Gbps/lane (JESD204B), and up to 24.75Gbps/lane (JESD204C).
2. LVDS: Not yet supported in software

7.3.6.1 JESD204B/C Interface

The ADC32RF7x uses the JESD204B/C high-speed serial interface to transfer data from the ADC to the receiving logic device. ADC32RF7x serialized lanes are capable of operating up to 24.75Gbps using JESD204C and up to 15Gbps using JESD204B. The device supports up to 2 JESD links (operated at the same lane rate) and lane options of 1,2,4 or 8 lanes. Figure 7-34 shows an internal block diagram of the JESD204 interface as well as the configuration parameters for each of the two links.

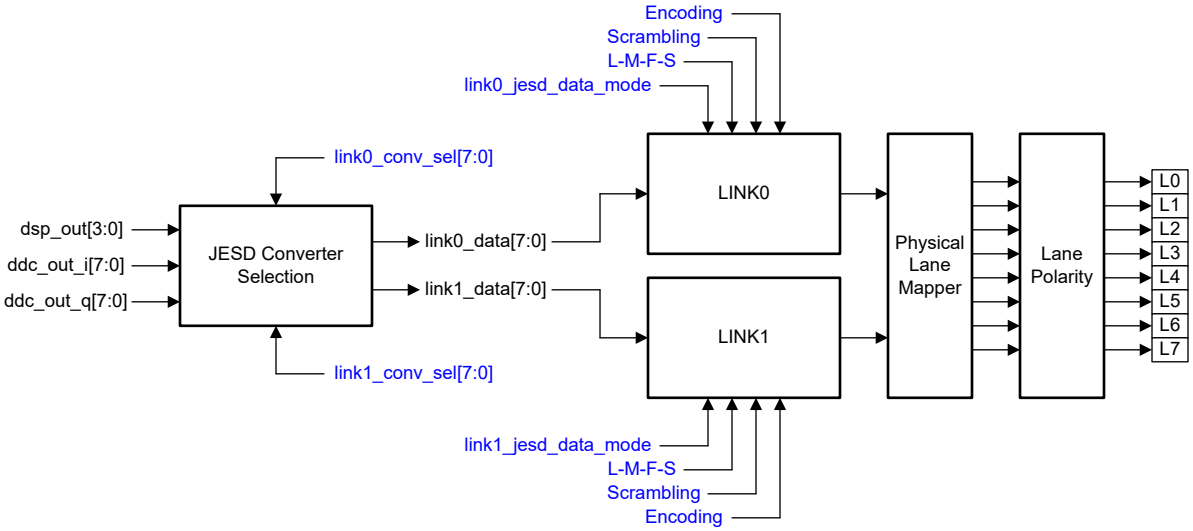


Figure 7-34. JESD204 Block Diagram

The following parameters and constraints need to be considered when configuring the JESD204B/C interface.

Range of L, M, F, S, N and N'

- L: Number of lanes: L ∈ {1,2,4,8}
- M: Number of converters: M ∈ {1,2,4,8}; for M=16 (octal band decimation), the JESD interface needs to configured to 2 links with M=8 per link
- F: Number of octets per frame: F ∈ {1,2,...,F_{max}}
- S: Number of samples per converter: S ∈ {1,2,4}
- N': Sample resolution with padding: N' = 8·L·F/(M·S), and N' ∈ {16,24,32}
- N: Sample resolution without padding: N' ∈ {16,24} and N <= N'

Constraints on F and N'

- N' = 16 => F_{max} = 64
- N' ∈ {24,32} => F_{max} = 64
- N= 32 => F must be a multiple of 4.

Constraints on Number of Lanes (L) and Lane Rate (LR)

- JESD TX lane rate LR: 4.0Gbps to 24.75Gbps
- L = 8 is only allowed for JESD TX Link 0 and not for JESD TX link 1

Constraints on Decimation Factor (D) and Repeat Factor (R)

- Sample repeat factor R = 2^p, $p \in \mathbb{N}^+$
- D <= 4: R = 1
- D%3 = 0: R = 1
- D%5 = 0: R = 1
- D > 4: D/R >= 4

Constraints on JESD TX Converter Selection

- Selected converter C ∈ {0,1,...,19}, see Table 7-16
- Converters can be presented in any order within the set above
- In addition the constraints in Table 7-17 apply.

Table 7-16. Converter Selection

CONVERTER	SELECTION NUMBER
DDC0_I	0
DDC0_Q	1
...	...
DDC7_Q	15
ADC0	16
ADC1	17

Table 7-17. Valid JESD Configurations

JESD DATA MODE	DECIMATION FACTOR D	NUMBER OF CONVERTERS M PER LINK	CONVERTERS AVAILABLE FOR SELECTION	CONVERTERS NUMBERS AVAILABLE FOR SELECTION
JESD_DATA_MODE_DSP_OUT	1 (DDC BYPASS)	1,2	ADC0, ADC1	16,17
JESD_DATA_MODE_DDC_OUT	2,3	1,2,4	DDC0_IQ, DDC1_IQ, DDC4_IQ, DDC5_IQ	0,1,2,3,8,9,10,11
	4,5	1,2,4,8	DDC0_IQ, ...DDC7_IQ	0,1,2....14,15
	8,16,32...			
	6,10,12,20,...			

The following parameters can be programmed:

Table 7-18. JESD TX Link Registers (x: 0 = LINK0, 1 = LINK1)

System Parameter Name	Size	Default	Reset	Description
LINK{x}_SCR_EN	1	0	RW	Control the JESD scrambler enable. 0: JESD scrambler is disabled. 1: JESD scrambler is enabled.
LINK{x}_JESD_TYPE	1	0	RW	Select the JESD type and must be set identically to the ENCODING setting. 0: 8b10b 1: 64b66b
LINK{x}_ENCODING	1	0	RW	Select the JESD encoding. Must be set identically to the JESD_TYPE setting. 0: 8b10b encoding. 1: 64b66b encoding.
LINK{x}_JESD_DATA_MODE	2	0	RW	Select the JESD data source. 0: DDC_OUT provided to JESD. 1: DSP_OUT provided to JESD. 2: not used 3: not used

Table 7-18. JESD TX Link Registers (x: 0 = LINK0, 1 = LINK1) (continued)

System Parameter Name	Size	Default	Reset	Description
LINK{x}_JESD_LANES	4	4	RW	Set the JESD lanes (L) parameter for the link. 0: LINK is disabled. 1: JESD L parameter set to 1. 2: JESD L parameter set to 2. 4: JESD L parameter set to 4. 8: JESD L parameter set to 8.
LINK{x}_JESD_CONVERTERS	4	2	RW	Set the JESD converters (M) parameter for the link. 0: LINK is disabled. 1: JESD M parameter set to 1. 2: JESD M parameter set to 2. 4: JESD M parameter set to 4. 8: JESD M parameter set to 8.
LINK{x}_JESD_OCTETS_PER_FRAME	7	1	RW	Set the JESD octets per frame (F) parameter for the link. The max value is for F is 64. If N' is 32 then F must be a multiple of 4. 1...64: JESD F parameter value.
LINK{x}_JESD_SAMPLES_PER_CONVERTER	3	1	RW	Set the JESD samples per converter (S) parameter for the link. 1: JESD S parameter set to 1. 2: JESD S parameter set to 2. 4: JESD S parameter set to 4.
LINK{x}_JESD_K_OR_E	8	32	RW	Set either the JESD frames per multi-frame (K) or the multi-blocks per extended multi-block (E). This field is the K parameter when 8b10b encoding is used or E when 64b66b encoding is used.
LINK{x}_CONV_SEL_{y}	5	16	RW	Select the data source of the {y} converter in the link. (y=0..7) 0: DDC0 in-phase component data. 1: DDC0 quadrature component data. 2: DDC1 in-phase component data. 3: DDC1 quadrature component data. 4: DDC2 in-phase component data. 5: DDC2 quadrature component data. 6: DDC3 in-phase component data. 7: DDC3 quadrature component data. 8: DDC4 in-phase component data. 9: DDC4 quadrature component data. 10: DDC5 in-phase component data. 11: DDC5 quadrature component data. 12: DDC6 in-phase component data. 13: DDC6 quadrature component data. 14: DDC7 in-phase component data. 15: DDC7 quadrature component data. 16: ADC0 data from DSP_OUT. 17: ADC1 data from DSP_OUT. 18: ADC2 data from DSP_OUT. 19: ADC3 data from DSP_OUT.
JESD_SYNC_N_SRC_SEL	2	0	RW	Set the SYNC_N signal source for 8b10b. 0: GPIO0 used as SYNC_N input. 2: SYNC_N is internally generated through software.

Table 7-18. JESD TX Link Registers (x: 0 = LINK0, 1 = LINK1) (continued)

System Parameter Name	Size	Default	Reset	Description
JESD_PHY_LANE{y}_DATA_SEL	3	0,1	RW	Set the physical lane data source for the lane{y}. (y = 0..7). 0: JESD logical lane 0 used as the lane data. 1: JESD logical lane 1 used as the lane data. 2: JESD logical lane 2 used as the lane data. 3: JESD logical lane 3 used as the lane data. 4: JESD logical lane 4 used as the lane data. 5: JESD logical lane 5 used as the lane data. 6: JESD logical lane 6 used as the lane data. 7: JESD logical lane 7 used as the lane data.
JESD_PHY_LANE_POLARITY_CTRL	8	0	RW	Set the individual physical lane polarity. If the bit is set, the corresponding physical lane polarity is inverted. Bit 0: JESD physical lane 0 polarity control. Bit 1: JESD physical lane 1 polarity control. Bit 2: JESD physical lane 2 polarity control. Bit 3: JESD physical lane 3 polarity control. Bit 4: JESD physical lane 4 polarity control. Bit 5: JESD physical lane 5 polarity control. Bit 6: JESD physical lane 6 polarity control. Bit 7: JESD physical lane 7 polarity control.

7.3.6.1.1 JESD204B Initial Lane Alignment (ILA)

The receiving device starts the initial lane alignment process by deasserting the $\overline{\text{SYNC}}$ signal. When a logic low state is detected on the $\overline{\text{SYNC}}$ input, the ADC starts transmitting comma characters (K28.5) to establish the code group synchronization, as shown in Figure 7-35. When synchronization is completed, the receiving device reasserts the $\overline{\text{SYNC}}$ signal and the ADC starts the initial lane alignment sequence with the next local multi-frame clock (LMFC) boundary. The ADC transmits four multi-frames, each containing K frame (K is SPI programmable). Each of the multi-frames contains the frame start and frame end symbols. The second multi-frame also contains the JESD204B link configuration data.

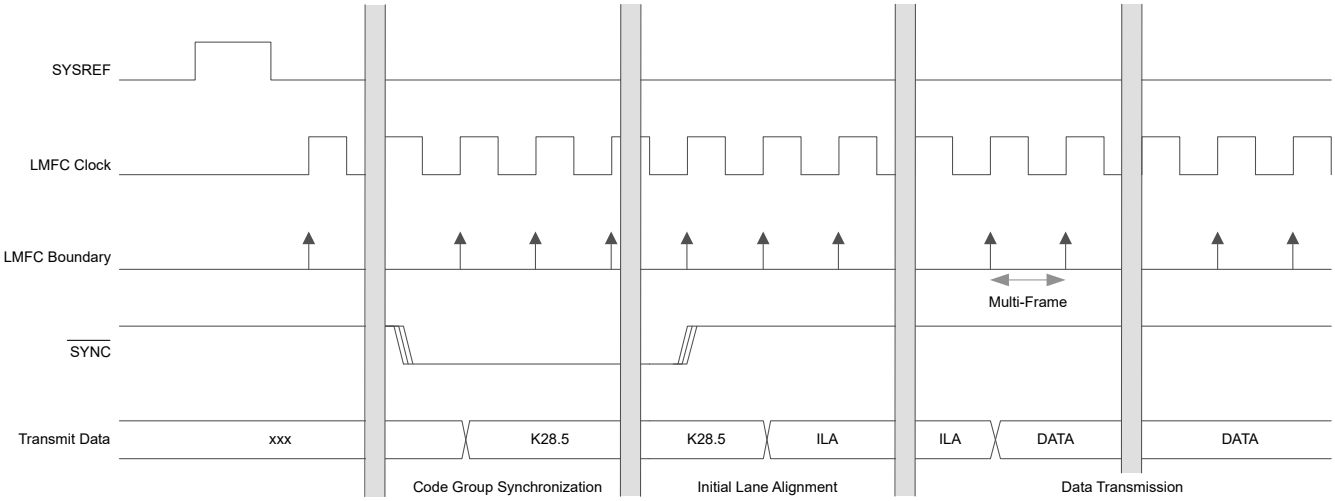


Figure 7-35. JESD204B Internal Timing Diagram

7.3.6.1.2 $\overline{\text{SYNC}}$ Signal

The $\overline{\text{SYNC}}$ signal is issued using one of two different methods:

1. Use the $\overline{\text{SYNC}}$ input pin to issue a SYNC request
2. The synchronization command is issued via SPI

7.3.6.1.3 JESD204B/C Frame Assembly

The JESD204B/C standard defines the following parameters:

- L: number of lanes per link
- M: number of converters per device
- F: number of octets per frame clock period
- S: number of samples per frame

7.3.6.1.4 JESD204B/C Frame Assembly in Bypass Mode

Table 7-19 lists the available JESD204B/C formats and corresponding valid sampling rate ranges for the ADC32RF7x. The sampling rates are limited by the minimum and maximum SERDES line rate as well as ADC sampling clock frequencies. The JESD204B/C frame assembly for the different lanes is shown in Table 7-20.

Table 7-19. JESD Mode Options: Bypass Mode

OUTPUT RESOLUTION (Bits)	L	M	F	S	JESD204B: Lane Rate (Gbps)	JESD204B RATIO [f_{SERDES}/F_S]	JESD204C: Lane Rate (Gbps)	JESD204C RATIO [f_{SERDES}/F_S]
16	8	2	1	2	F_S x 16 x 10 / 8 x M / L	5	F_S x 16 x 66 / 64 x M / L	4.125
	4	2	1	1		10		8.25
	2	2	2	1		20		16.5
	4	1	1	2		5		4.125
	2	1	1	1		10		8.25
	1	1	2	1		20		16.5

Table 7-20. Example JESD Sample Frame Assembly: Bypass Mode

OUTPUT LANE	LMFS = 8-2-1-2	LMFS = 4-2-1-1	LMFS = 2-2-2-1	LMFS = 4-1-1-2	LMFS = 2-1-1-1	LMFS = 1-1-2-1
STX0	A_0[15:8]	A_0[15:8]	A_0[15:0]	A_0[15:8]	A_0[15:8]	A_0[15:0]
STX1	A_0[7:0]	A_0[7:0]	B_0[15:0]	A_0[7:0]	A_0[7:0]	
STX2	A_1[15:8]	B_0[15:8]		A_1[15:8]		
STX3	A_1[7:0]	B_0[7:0]		A_1[7:0]		
STX4	B_0[15:8]					
STX5	B_0[7:0]					
STX6	B_1[15:8]					
STX7	B_1[7:0]					

7.3.6.1.5 JESD204B/C Frame Assembly With Real Decimation

Table 7-21 lists the available JESD204B/C interface configurations and corresponding SerDes lane rates. The boundary conditions are:

- JESD204B: lane rates from 4 (min) to 15Gbps (max)
- JESD204C: lane rates from 4 (min) to 24.75Gbps (max)

Examples of JESD204B/C frame assemblies are illustrated in Table 7-21 to Table 7-23.

Table 7-21. JESD Mode Options: Real Decimation

Output Resolution (bit)	L	M	F	S	JESD204B: Lane Rate (Gbps)	JESD204B: RATIO [$f_{SERDES}/(F_S/N)$]	JESD204C: Lane Rate (Gbps)	JESD204C: RATIO [$f_{SERDES}/(F_S/N)$]
16	4	2	1	1	F_S x 20 x M / D / L	10	F_S x 16 x 66 / 64 x M / D / L	8.25
	2	2	2	1		20		16.5
	1	2	4	1		40		33
	2	1	1	1		10		8.25
	1	1	2	1		20		16.5
24	2	2	3	1	F_S x 30 x M / D / L	30	F_S x 24 x 66 / 64 x M / D / L	24.75
	1	2	6	1		60		49.5
	1	1	3	1		30		24.75

D: Decimation setting

Table 7-22. Example JESD Frame Assembly: Real Decimation 16-bit output - Dual and Single Band

OUTPUT LANE	LMFS = 4-2-1-1	LMFS = 2-2-2-1	LMFS = 1-2-4-1		LMFS = 2-1-1-1	LMFS = 1-1-2-1
STX0	A_0 [15:8]	A_0 [15:0]	A_0 [15:0]	B_0 [15:0]	A_0 [15:8]	A_0 [15:0]
STX1	A_0 [7:0]	B_0 [15:0]			A_0 [7:0]	
STX2	B_0 [15:8]					
STX3	B_0 [7:0]					
STX4..7						

Table 7-23. Example JESD Sample Frame Assembly: Real Decimation 24-bit output - Dual and Single Band

OUTPUT LANE	LMFS = 2-2-3-1	LMFS = 1-2-6-1		LMFS = 1-1-3-1
STX0	A_0 [23:0]	A_0 [23:0]	B_0 [23:0]	A_0 [23:0]
STX1	B_0 [23:0]			
STX2..7				

7.3.6.1.6 JESD204B,C Frame Assembly With Complex Decimation

Table 7-24 lists the available JESD204B,C interface configurations and corresponding SerDes lane rates. The boundary conditions are:

- JESD204B: lane rates from 4 (min) to 15Gpbs (max)
- JESD204C: lane rates from 4 (min) to 24.75Gbps (max)

The JESD204B/C frame assemblies are shown in Table 7-25 (16-bit) and Table 7-29 (24-bit).

When using octal band DDC, two separate JESD links need to be configured because the M (# of converters per link) cannot exceed 8 as shown in Table 7-25. For example for octal band DDC using 8 JESD lanes each of the two links can be configured as LMFS = 4-8-4-1. The internal JESD output mux can be used to assign specific SerDes lanes to each link.

Table 7-24. JESD Mode Options: Complex Decimation

Output Resolution (bit)	L	M	F	S	JESD204B: Lane Rate (Gbps)	JESD204B: RATIO [$f_{SERDES}/(F_S/N)$]	JESD204C: Lane Rate (Gbps)	JESD204C: RATIO [$f_{SERDES}/(F_S/N)$]
16	8	8	2	1	$F_S \times 16 \times 10 / 8 \times M / D / L$	20	$F_S \times 16 \times 66 / 64 \times M / D / L$	16.5
	4	8	4	1		40		33
	2	8	8	1		80		66
	1	8	16	1		160		132
	8	4	1	1		10		8.25
	4	4	2	1		20		16.5
	2	4	4	1		40		33
	1	4	8	1		80		66
	8	2	1	2		5		4.125
	4	2	1	1		10		8.25
	2	2	2	1		20		16.5
	1	2	4	1		40		33
24	8	8	3	1	$F_S \times 24 \times 10 / 8 \times M / D / L$	30	$F_S \times 24 \times 66 / 64 \times M / D / L$	24.75
	4	8	6	1		60		49.5
	2	8	12	1		120		99
	1	8	24	1		240		198
	8	4	3	2		15		12.375
	4	4	3	1		30		24.75
	2	4	6	1		60		49.5
	1	4	12	1		120		99
	8	2	3	4		7.5		6.1875
	4	2	3	2		15		12.375
	2	2	3	2		30		24.75
	1	2	6	1		60		49.5

D: complex decimation setting

Table 7-25. Example JESD Frame Assembly: Complex Decimation, Octal Band, 16-bit Output
Note: the LMFS configuration is Per JESD Link

JESD LINK	OUTPUT LANE	LMFS = 4-8-4-1	LMFS = 2-8-8-1		LMFS = 1-8-16-1			
LINK0	STX0	AI_0 [15:0], AQ_0 [15:0]	AI_0 [15:0], AQ_0 [15:0]	BI_0 [15:0], BQ_0 [15:0]	AI_0 [15:0], AQ_0 [15:0]	BI_0 [15:0], BQ_0 [15:0]	CI_0 [15:0], CQ_0 [15:0]	DI_0 [15:0], DQ_0 [15:0]
	STX1	BI_0 [15:0], BQ_0 [15:0]	CI_0 [15:0], CQ_0 [15:0]	DI_0 [15:0], DQ_0 [15:0]				
	STX2	CI_0 [15:0], CQ_0 [15:0]						
	STX3	DI_0 [15:0], DQ_0 [15:0]						
LINK1	STX4	EI_0 [15:0], EQ_0 [15:0]	EI_0 [15:0], EQ_0 [15:0]	FI_0 [15:0], FQ_0 [15:0]	EI_0 [15:0], EQ_0 [15:0]	FI_0 [15:0], FQ_0 [15:0]	GI_0 [15:0], GQ_0 [15:0]	HI_0 [15:0], HQ_0 [15:0]
	STX5	FI_0 [15:0], FQ_0 [15:0]	GI_0 [15:0], GQ_0 [15:0]	HI_0 [15:0], HQ_0 [15:0]				
	STX6	GI_0 [15:0], GQ_0 [15:0]						
	STX7	HI_0 [15:0], HQ_0 [15:0]						

Table 7-26. Example JESD Frame Assembly: Complex Decimation, Quad Band, 16-bit Output

OUTPUT LANE	LMFS = 8-8-2-1	LMFS = 4-8-4-1	LMFS = 2-8-8-1		LMFS = 1-8-16-1			
STX0	AI_0 [15:0]	AI_0 [15:0], AQ_0 [15:0]	AI_0 [15:0], AQ_0 [15:0]	BI_0 [15:0], BQ_0 [15:0]	AI_0 [15:0], AQ_0 [15:0]	BI_0 [15:0], BQ_0 [15:0]	CI_0 [15:0], CQ_0 [15:0]	DI_0 [15:0], DQ_0 [15:0]
STX1	AQ_0 [15:0]	BI_0 [15:0], BQ_0 [15:0]	CI_0 [15:0], CQ_0 [15:0]	DI_0 [15:0], DQ_0 [15:0]				
STX2	BI_0 [15:0]	CI_0 [15:0], CQ_0 [15:0]						
STX3	BQ_0 [15:0]	DI_0 [15:0], DQ_0 [15:0]						
STX4	CI_0 [15:0]							
STX5	CQ_0 [15:0]							
STX6	DI_0 [15:0]							
STX7	DQ_0 [15:0]							

Table 7-27. Example JESD Frame Assembly: Complex Decimation, Dual Band, 16-bit Output

OUTPUT LANE	LMFS = 8-4-1-1	LMFS = 4-4-2-1	LMFS = 2-4-4-1		LMFS = 1-4-8-1			
STX0	AI_0 [15:8]	AI_0 [15:0]	AI_0 [15:0]	AQ_0 [15:0]	AI_0 [15:0]	AQ_0 [15:0]	BI_0 [15:0]	BQ_0 [15:0]
STX1	AI_0 [7:0]	AQ_0 [15:0]	BI_0 [15:0]	BQ_0 [15:0]				
STX2	AQ_0 [15:8]	BI_0 [15:0]						
STX3	AQ_0 [7:0]	BQ_0 [15:0]						
STX4	BI_0 [15:8]							
STX5	BI_0 [7:0]							
STX6	BQ_0 [15:8]							
STX7	BQ_0 [7:0]							

Table 7-28. Example JESD Frame Assembly: Complex Decimation, Single Band, 16-bit Output

OUTPUT LANE	LMFS = 8-2-1-2	LMFS = 4-2-1-1	LMFS = 2-2-2-1		LMFS = 1-2-4-1			
STX0	AI_0 [15:8]	AI_0 [15:8]	AI_0 [15:8]	AI_0 [7:0]	AI_0 [15:8]	AI_0 [7:0]	AQ_0 [15:8]	AQ_0 [7:0]
STX1	AI_0 [7:0]	AI_0 [7:0]	AQ_0 [15:8]	AQ_0 [7:0]				
STX2	AQ_0 [15:8]	AQ_0 [15:8]						
STX3	AQ_0 [7:0]	AQ_0 [7:0]						
STX4	AI_1 [15:8]							
STX5	AI_1 [7:0]							
STX6	AQ_1 [15:8]							
STX7	AQ_1 [7:0]							

Table 7-29. Example JESD Frame Assembly: Complex Decimation, Octal Band, 24-bit Output
Note: the LMFS configuration is Per JESD Link

JESD LINK	OUTPUT LANE	LMFS = 4-8-6-1	LMFS = 2-8-12-1		LMFS = 1-8-24-1			
LINK0	STX0	AI_0 [23:0], AQ_0 [23:0]	AI_0 [23:0], AQ_0 [23:0]	BI_0 [23:0], BQ_0 [23:0]	AI_0 [23:0], AQ_0 [23:0]	BI_0 [23:0], BQ_0 [23:0]	CI_0 [23:0], CQ_0 [23:0]	DI_0 [23:0], DQ_0 [23:0]
	STX1	BI_0 [23:0], BQ_0 [23:0]	CI_0 [23:0], CQ_0 [23:0]	DI_0 [23:0], DQ_0 [23:0]				
	STX2	CI_0 [23:0], CQ_0 [23:0]						
	STX3	DI_0 [23:0], DQ_0 [23:0]						
LINK1	STX4	EI_0 [23:0], EQ_0 [23:0]	EI_0 [23:0], EQ_0 [23:0]	FI_0 [23:0], FQ_0 [23:0]	EI_0 [23:0], EQ_0 [23:0]	FI_0 [23:0], FQ_0 [23:0]	GI_0 [23:0], GQ_0 [23:0]	HI_0 [23:0], HQ_0 [23:0]
	STX5	FI_0 [23:0], FQ_0 [23:0]	GI_0 [23:0], GQ_0 [23:0]	HI_0 [23:0], HQ_0 [23:0]				
	STX6	GI_0 [23:0], GQ_0 [23:0]						
	STX7	HI_0 [23:0], HQ_0 [23:0]						

Table 7-30. Example JESD Frame Assembly: Complex Decimation, Quad Band, 24-bit Output

OUTPUT LANE	LMFS = 8-8-3-1	LMFS = 4-8-6-1	LMFS = 2-8-12-1		LMFS = 1-8-24-1			
STX0	AI_0 [23:0]	AI_0 [23:0], AQ_0 [23:0]	AI_0 [23:0], AQ_0 [23:0]	BI_0 [23:0], BQ_0 [23:0]	AI_0 [23:0], AQ_0 [23:0]	BI_0 [23:0], BQ_0 [23:0]	CI_0 [23:0], CQ_0 [23:0]	DI_0 [23:0], DQ_0 [23:0]
STX1	AQ_0 [23:0]	BI_0 [23:0], BQ_0 [23:0]	CI_0 [23:0], CQ_0 [23:0]	DI_0 [23:0], DQ_0 [23:0]				
STX2	BI_0 [23:0]	CI_0 [23:0], CQ_0 [23:0]						
STX3	BQ_0 [23:0]	DI_0 [23:0], DQ_0 [23:0]						
STX4	CI_0 [23:0]							
STX5	CQ_0 [23:0]							
STX6	DI_0 [23:0]							
STX7	DQ_0 [23:0]							

Table 7-31. Example JESD Frame Assembly: Complex Decimation, Dual Band, 24-bit Output

OUTPUT LANE	LMFS = 8-4-3-2	LMFS = 4-4-3-1	LMFS = 2-4-6-1		LMFS = 1-4-12-1			
STX0	AI_0 [23:0]	AI_0 [23:0]	AI_0 [23:0]	AQ_0 [23:0]	AI_0 [23:0]	AQ_0 [23:0]	BI_0 [23:0]	BQ_0 [23:0]
STX1	AQ_0 [23:0]	AQ_0 [23:0]	BI_0 [23:0]	BQ_0 [23:0]				
STX2	AI_1 [23:0]	BI_0 [23:0]						
STX3	AQ_1 [23:0]	BQ_0 [23:0]						
STX4	BI_0 [23:0]							
STX5	BQ_0 [23:0]							
STX6	BI_1 [23:0]							
STX7	BQ_1 [23:0]							

Table 7-32. Example JESD Frame Assembly: Complex Decimation, Single Band, 24-bit Output

OUTPUT LANE	LMFS = 8-2-3-4	LMFS = 4-2-3-2	LMFS = 2-2-3-1	LMFS = 1-2-6-1	
STX0	AI_0 [23:0]	AI_0 [23:0]	AI_0 [23:0]	AI_0 [23:0]	AQ_0 [23:0]
STX1	AQ_0 [23:0]	AQ_0 [23:0]	AQ_0 [23:0]		
STX2	AI_1 [23:0]	AI_1 [23:0]			
STX3	AQ_1 [23:0]	AQ_1 [23:0]			
STX4	AI_2 [23:0]				
STX5	AQ_2 [23:0]				
STX6	AI_3 [23:0]				
STX7	AQ_3 [23:0]				

7.3.6.2 JESD Output Reference Clock

The ADC provides an option to output the SERDES reference clock to the FPGA (see Figure 7-36). This JESD reference clock is configured to be SerDes lane rate / (8x k) where k can be any integer between 4 and 255. This provides a high flexibility of supported reference clock frequencies.

The output clock can be configured to be single ended LVCMOS or differential LVDS. This circuit is powered down by default. If not used, the JESDCLKP/N pins is left floating.

The JESD output clock is derived directly from the internal SERDES PLL and does not provide deterministic latency.

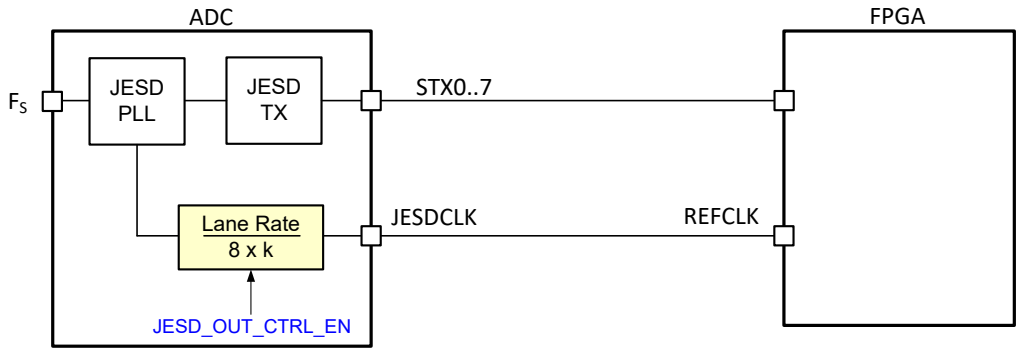


Figure 7-36. JESD reference clock output for the FPGA SERDES PLL

The JESD clock output can be can be programmed using the following parameters:

Table 7-33. JESD clock output Configuration Programming

System Parameter Name	Size	Default	Access	Description
JESD_OUT_EN_CTRL	1	0	R/W	Enable control for JESD output. 0: JESD output is disabled. 1: JESD output is enabled.
JESD_OUT_DIV0	8	0	R/W	Bits [7:0] of JESD clock output divider factor.
JESD_OUT_DIV1	8	0	R/W	Bits [12:8] of JESD clock output divider factor.

7.4 Device Functional Modes

The device has 2 different operating modes (see also Figure 7-37). Any two out of the four input channels can be selected for either operating mode.

1. Normal operation: one ADC core per input channel. This is the lowest power consumption per channel mode.
2. 2x averaging: The input signal is externally connected to 2 ADC channels. Internally the output of two ADCs is averaged for SNR improvement (best improvement = 3dB).

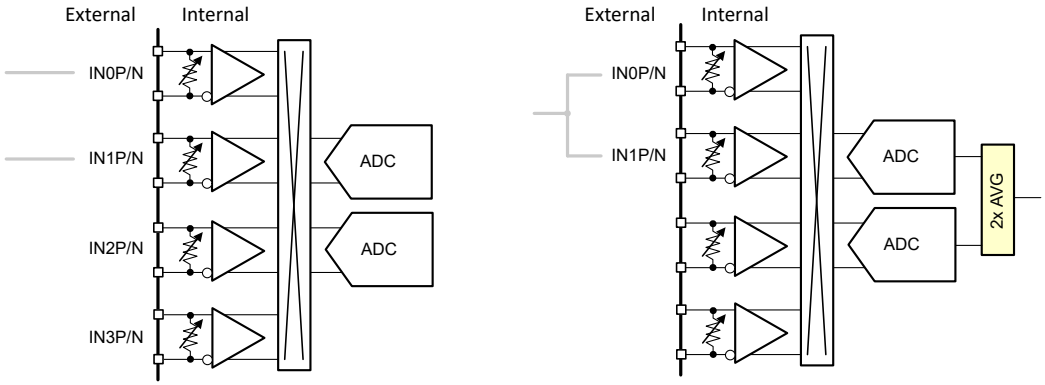


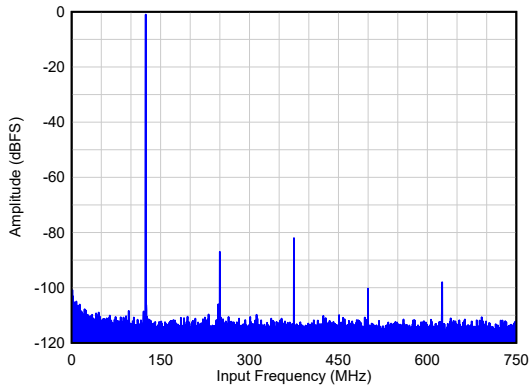
Figure 7-37. Operating modes: normal operation (left) and 2x averaging (right)

Table 7-34. Mode Comparison (typical)

Operating Mode	# of Output Channels	SNR_{flat} at F_{IN} = 125MHz, A_{IN} = −1dBFS	SNR_{flat} at F_{IN} = 125MHz, A_{IN} = −20dBFS	NSD_{flat} at F_{IN} = 125MHz, A_{IN} = −20dBFS
Normal	2	74.8dBFS	75.5dBFS	−163.6dBFS/Hz
2x Averaging	1	77.5dBFS	78.3dBFS	−166.4dBFS/Hz

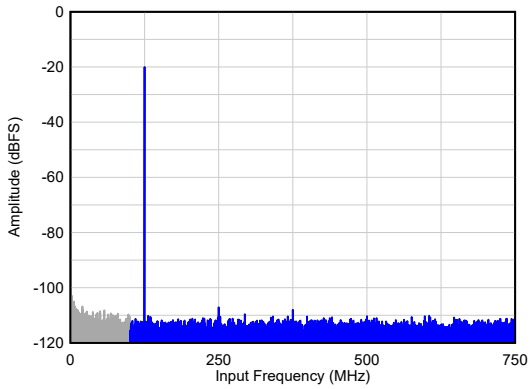
7.4.1 Device Operating Mode Comparison

Following are comparison measurements of the different operating modes for the same input signal configuration.



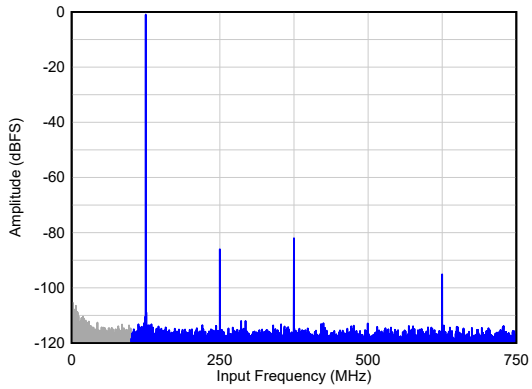
F_{IN} = 125MHz, A_{IN} = -1dBFS, SNR_{flat} = 74.8dBFS

Figure 7-38. Single tone FFT, Normal Mode



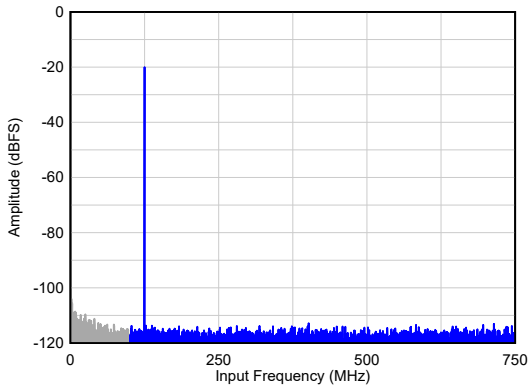
F_{IN} = 125MHz, A_{IN} = -20dBFS, SNR_{flat} = 75.5dBFS

Figure 7-39. Single tone FFT, Normal Mode



F_{IN} = 125MHz, A_{IN} = -1dBFS, SNR_{flat} = 77.5dBFS

Figure 7-40. Single tone FFT, 2x Average Mode



F_{IN} = 200MHz, A_{IN} = -20dBFS, SNR_{flat} = 78.2dBFS

Figure 7-41. Single tone FFT, 2x Average Mode

7.5 Programming

The device is primarily configured and controlled using the serial programming interface (SPI). However, there are digital features and functions available that can be configured via SPI and controlled/used via GPIO pins.

7.5.1 GPIO Control

The device has 24 GPIO pins. Four are fixed function and the remaining 20 can be configured independently for different functions using the SPI.

Table 7-35. GPIO: FIxed Functions

PIN NAME	FUNCTION	PIN #
$\overline{\text{RESET}}$	Hardware RESET	J1
SCLK	SPI SCLK	K15
SDIO	SPI DIN/DOUT	L15
SDOUT	SPI DOUT	L3
$\overline{\text{SEN}}$	SPI EN	J16
$\overline{\text{SYNC}}$	SYNC for JESD 8b/10b	J4

Table 7-36. GPIO: Configurable Functions

FUNCTION	PIN No.	No. of PINS	DESCRIPTION
NCO CONTROL	ANY	1..8	The pin selects between 2 NCO frequencies for each DDC. There are 8 DDCs and each NCO/DDC can be mapped to a specific GPIO pins. Using one GPIO pin for multiple/all DDCs is possible. Functional only when using NCOs. Low: nco_0 of each active DDC is selected. High: nco_1 of each active DDC is selected.
OVR		1	OR-ed outputs of each ADC OVR signal. Low: no ADC is in saturation. High: an ADC is in saturation.
NCO SYSREF ARM		1	The GPIO pin is used to enable resetting the NCO phase to 0 with the next SYSREF rising edge.
CALIBRATION FREEZE		1	Low: device background calibration is active. High: device background calibration is inactive.
GLOBAL POWER DOWN		1	Device global power down. Low: device is powered up. High: device is powered down.
FAST POWER DOWN		1	Device global power down. Low: device is powered up. High: device is powered down.

7.5.2 SPI Register Write

The internal registers can be programmed following these steps:

1. Drive the $\overline{SEN}$ pin low (all SPI rising and falling clock edges need to occur while $\overline{SEN}$ driven low).
2. Set the R/W bit to 0 (bit A15 of the 16-bit address).
3. Initiate a serial interface cycle by specifying the address of the register (A[14:0]) whose content is written and
4. Write the 8-bit data that are latched in on the SCLK rising edges

Figure 7-42 shows the timing requirements for the serial register write operation.

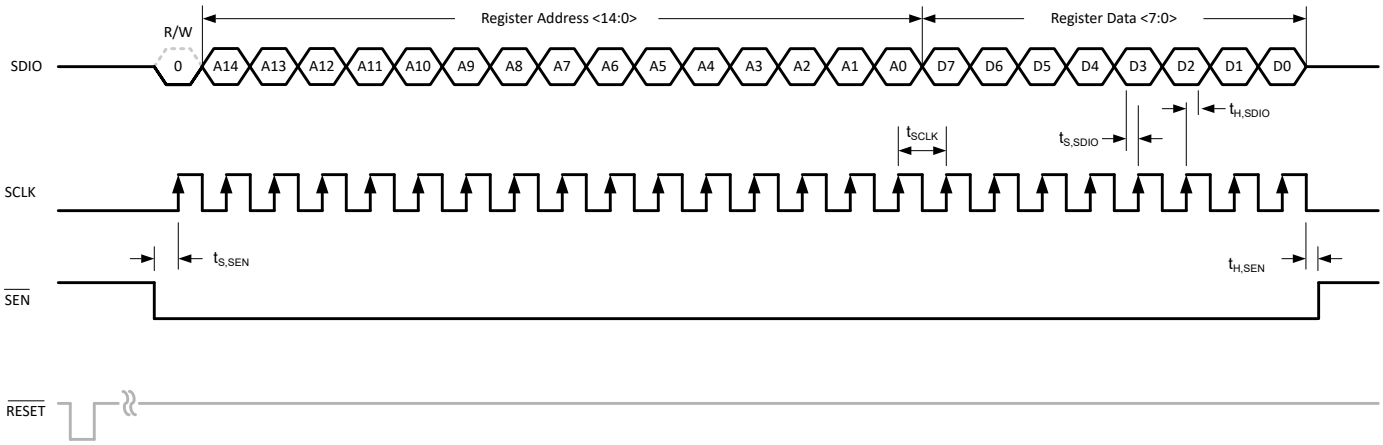


Figure 7-42. Serial Register Write Timing Diagram

7.5.3 SPI Register Read

The device includes a mode where the contents of the internal registers can be read back using the SDIO pin. This readback mode can be useful as a diagnostic check to verify the serial interface communication between the external controller and the ADC. The procedure to read the contents of the serial registers is as follows:

1. Drive the $\overline{SEN}$ pin low (all SPI rising and falling clock edges need to occur while $\overline{SEN}$ driven low).
2. Set the R/W bit (A15) to 1. This setting disables any further writes to the registers.
3. Initiate a serial interface cycle specifying the address of the register (A[14:0]) whose content must be read
4. The device launches the contents (D[7:0]) of the selected register on the SDIO pin on SCLK falling edge
5. The external controller can capture the contents on the SCLK rising edge

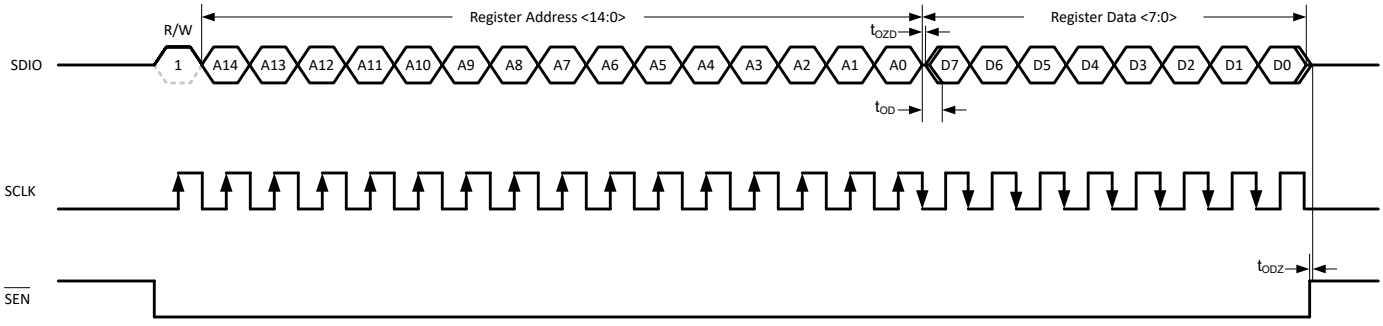


Figure 7-43. Serial Register Read Timing Diagram

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The ADC32RF72 can be used in a wide range of applications including radar, frequency and/or time domain digitizer and spectrum analyzer, test and communications equipment and software-defined radios (SDRs). The Typical Applications section describe two configurations that meet the needs of a number of these applications.

8.2 Typical Application: Spectrum Analyzer

This section demonstrates the use of ADC32RF72 as a wideband RF sampling receiver. The device is flexible and can be used as either a 2-channel receiver or as a single channel receiver with better noise floor using internal digital averaging. The ADC is driven by single-ended RF amplifiers and the conversion to differential signaling is achieved by a transformer (balun). The device includes digital down-converters (DDCs) in both dual-channel and single-channel modes to mix the desired frequency band to baseband and down-sample the data to reduce the interface rate. The block diagram for the wideband RF sampling receiver is shown in Figure 8-1 where the device is configured in single-channel mode for best noise density.

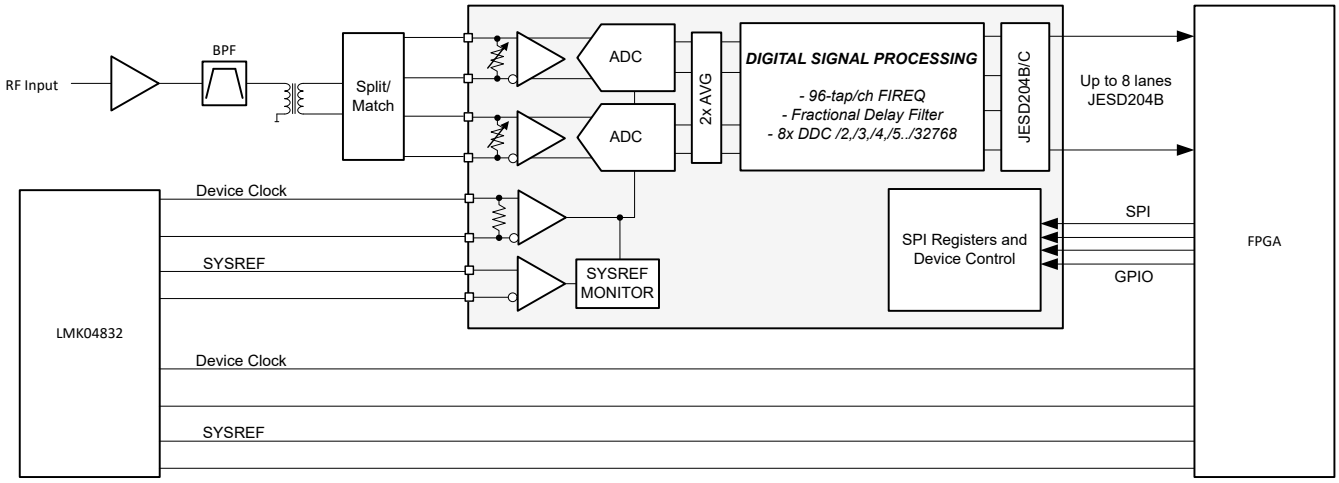


Figure 8-1. Wideband RF Sampling Receiver

8.2.1 Design Requirements

8.2.1.1 Input Signal Path: Wideband Receiver

Appropriate band limiting filters are used to reject unwanted frequencies in the receive signal path. A 1:2 (for 100Ω effective termination impedance) or a 1:1 (for 50Ω effective termination impedance) balun transformer is needed to convert the single ended RF input to differential for input to the ADC. The balun must have good amplitude (< 0.5dB) and phase balance (less than 2deg) within the frequency range of interest. A back-to-back balun configuration often times gives better SFDR performance. Table 8-1 lists several recommended baluns for different impedance ratios and frequency ranges. The S-parameters of the ADC input can be used to design the front end matching network.

Table 8-1. Recommended Baluns

PART NUMBER	MANURACTURER(1)	IMPEDANCE RATIO	AMPLITUDE BALANCE (dB)	PHASE BALANCE (°)	FREQUENCY RANGE
BAL-0003SMG	Marki Microwave	1:2	0.1	3	0.5MHz to 3GHz
TCM2-43X+	Minicircuits	1:2	0.5	7	10MHz to 4GHz
TCM2-33WX+	Minicircuits	1:2	0.7	4	10MHz to 3GHz
TC1-1-13M+	Minicircuits	1:1	0.5	2-3	10MHz to 3GHz

(1) See the Third-Party Products Disclaimer .

8.2.1.2 Clocking

The device clock inputs must be AC-coupled to the device to provide the rated performance. The clock source must have low jitter (integrated phase noise) for the ADC to meet the stated SNR performance, especially when operating at higher input frequencies. The clock signal can be filtered with a band pass filter to remove some of the broad band clock noise. The JESD204B/C data converter system (ADC and FPGA) requires additional SYSREF and device clocks. The LMK04828 or LMK04832 devices are designed to generate these clocks. Depending on the ADC clock frequency and jitter requirements. The device can also be used as a system clock synthesizer or as a device clock and SYSREF distribution device when using multiple ADC32RF72 devices in a system.

8.2.2 Detailed Design Procedure

8.2.2.1 Sampling Clock Requirements

To maximize the SNR performance of the ADC, a very low jitter (< 50fs) sampling clock is required. Figure 8-2 shows the estimated SNR performance versus input frequency versus external clock jitter. The internal ADC aperture jitter also has some dependency to the clock amplitude (gets more sensitive with higher input frequency) as shown in Figure 8-3. When using averaging or decimation, the SNR for a single ADC core must be estimated first before adding the SNR improvement from internal averaging or decimation.

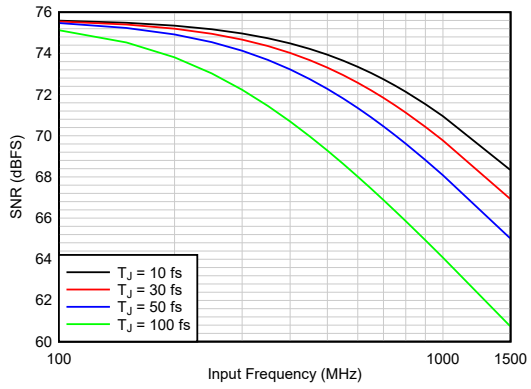


Figure 8-2. SNR vs T_{Jitter}

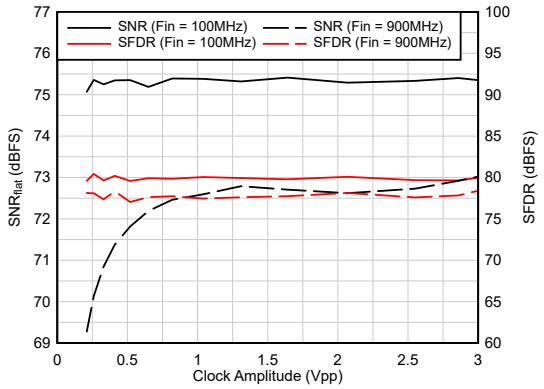


Figure 8-3. AC Performance vs Clock Amplitude

8.2.3 Application Performance Plots

The following application curves demonstrate performance with 2x internal averaging configuration. The input frequency is 900MHz and input amplitudes of -1 and -20dBFS are shown in DDC bypass mode as well as 8x complex decimation.

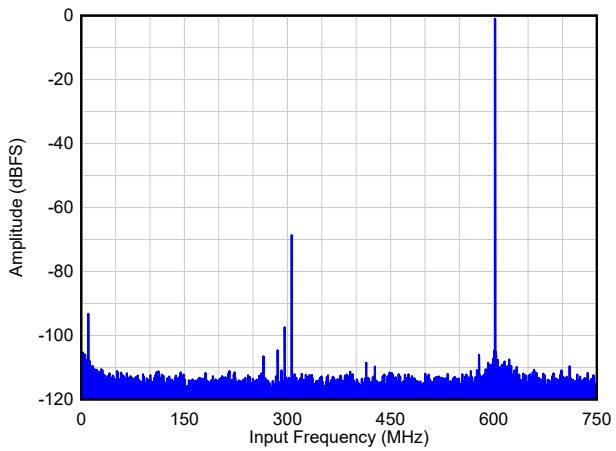


Figure 8-4. F_{IN} = 900MHz, A_{IN} = -1dBFS, 2x Averaging, DDC Bypass

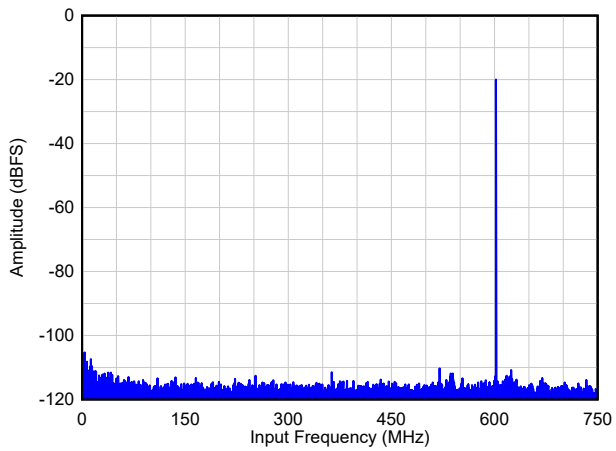


Figure 8-5. F_{IN} = 900MHz, A_{IN} = -20dBFS, 2x Averaging, DDC Bypass

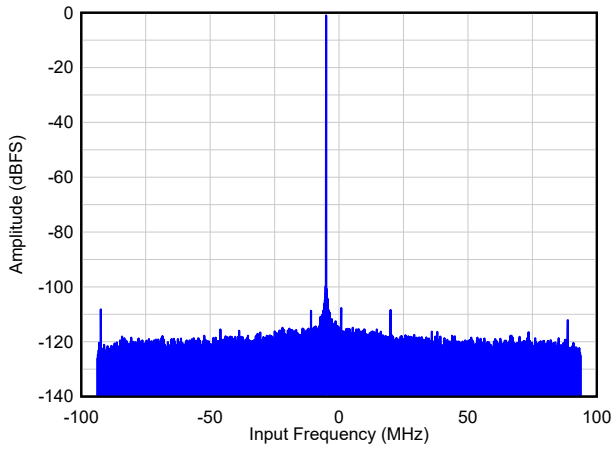


Figure 8-6. F_{IN} = 900MHz, A_{IN} = -1dBFS, 2x Averaging, 8x complex decimation

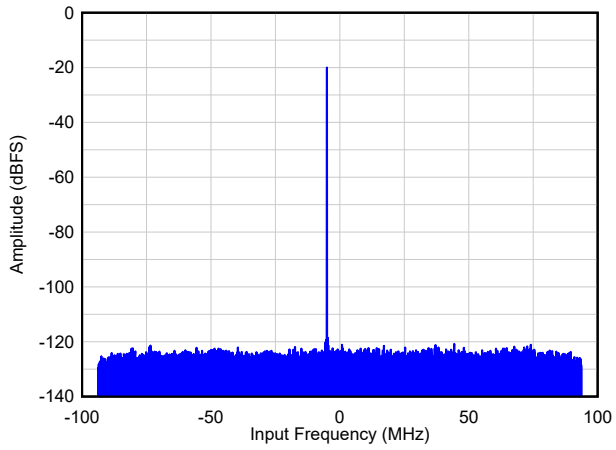


Figure 8-7. F_{IN} = 900MHz, A_{IN} = -20dBFS, 2x Averaging, 8x complex decimation

8.3 Typical Application: Time Domain Digitizer

The ADC32RF72 offers several features such as low code error rate (CER), very low noise floor and high SNR and programmable, fractional digital delay that makes the device a great fit for time domain digitizer and oscilloscope applications. The block diagram for a typical time domain sampling signal chain in Figure 8-8 with the ADC32RF72 configured in dual-channel mode with 2x internal digital averaging for best noise density.

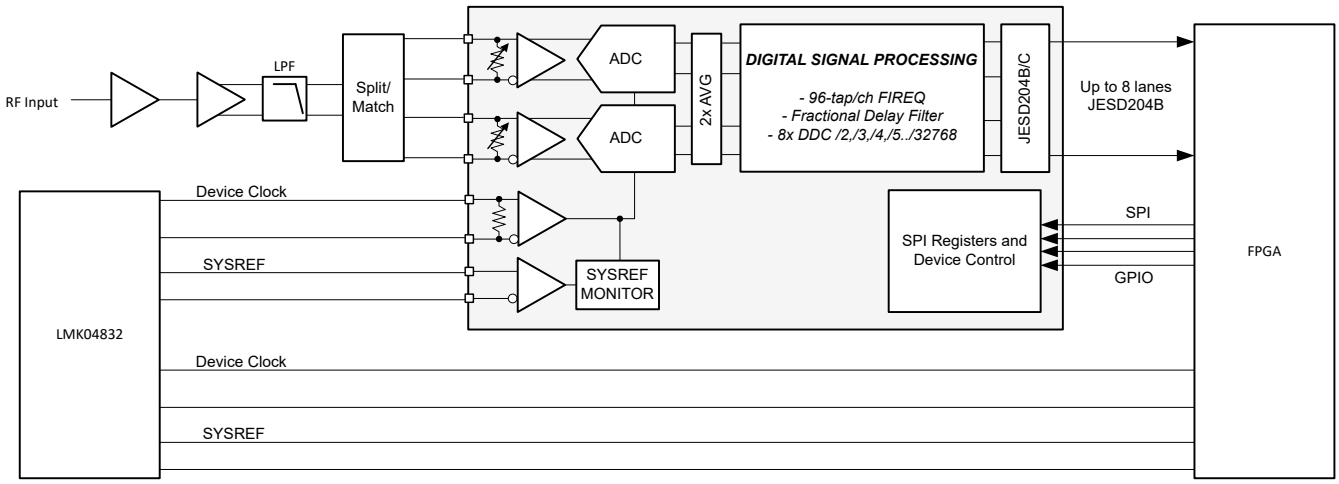


Figure 8-8. Time Domain Digitizer

8.3.1 Design Requirements

8.3.1.1 Input Signal Path: Time Domain Digitizer

Most time-domain digitizers are required to be DC-coupled to monitor DC or low-frequency signals. This requirement forces the design to use DC-coupled, fully differential amplifiers to convert from single-ended signaling at the front panel to differential signaling at the ADC. This design uses a differential amplifier. The LMH5401 amplifier has an 8GHz, gain-bandwidth product that is sufficient to support a 1GHz bandwidth digitizer. The LMH5401 has a gain of 8dB and a noise figure of 11dB.

An antialiasing, low-pass filter is positioned at the input of the ADC to limit the bandwidth of the input signal into the ADC. This amplifier also band-limits the front-end noise to prevent aliased noise from degrading the signal-to-noise ratio of the overall system. Design this filter for the maximum input signal bandwidth specified by the oscilloscope. The input bandwidth can then be reconfigured through the use of digital filters in the FPGA or ASIC to limit the oscilloscope input bandwidth to a bandwidth less than the maximum.

Table 8-2 lists a number of recommended amplifiers frequency ranges.

Table 8-2. Recommended single ended to differential amplifiers

PART NUMBER	BANDWIDTH	POWER CONSUMPTION
THS4509	1.9GHz	125mW
LMH5401	8GHz	185mW
TRF1305	7GHz	495mW

8.3.2 Application Performance Plots

The following shows a captured pulse response.

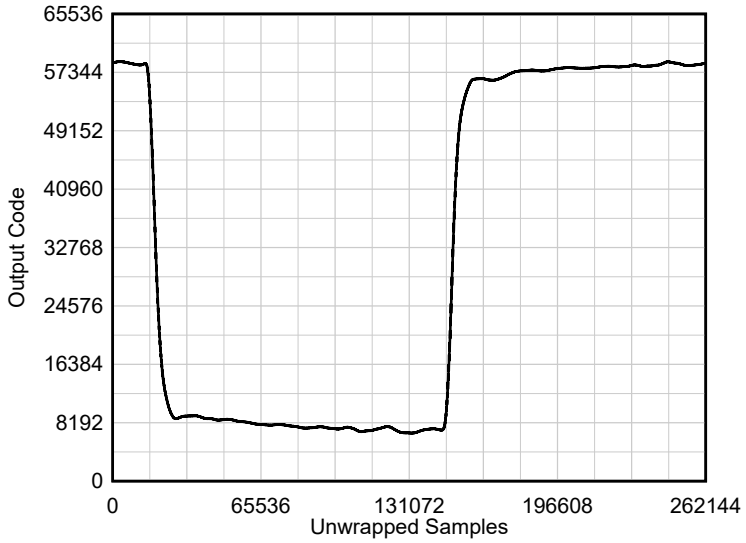


Figure 8-9. 100MHz Pulse response

8.4 Initialization Set Up

After power-up, the internal registers must be initialized to the default values through a hardware reset by applying a low pulse on the $\overline{\text{RESET}}$ pin, as shown in Figure 8-10. Any given power rail needs to reach 90% of the value before starting the next power rail.

1. Apply 0.9V DVDD09 digital power supply
2. Apply 1.2V AVDD12 and CLKVDD12 power supplies
3. Apply 1.8V power supplies (AVDD18, GPIOVDD18, DVDD18), in no specific order
4. Apply sampling clock
5. Apply hardware reset. After hardware reset is released, the default registers are loaded from internal fuses.
6. Start programming the internal registers using the SPI register writes. The internal calibration starts automatically and a register can be read back to check the status of the calibration.

For power down, the inverse sequence can be followed.

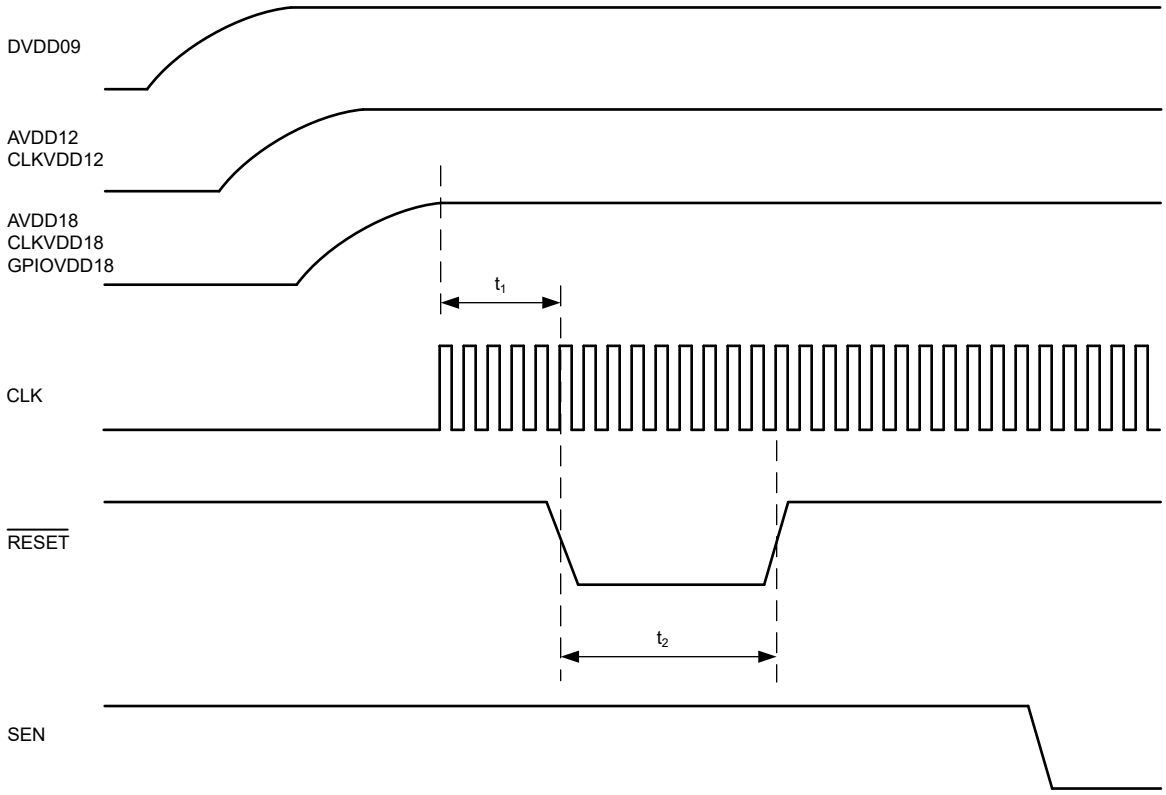


Figure 8-10. Initialization of Serial Registers After Power-Up

Table 8-3. Power Up Timing

		MIN	TYP	MAX	UNIT
t_1	Power-on delay: delay from power up to active low RESET pulse	1			us
t_2	Reset pulse width: active low RESET pulse width	100			ns

8.5 Power Supply Recommendations

The device requires 3 different power supply voltages: the internal analog circuitry operate off 1.8V and 1.2V rails while the digital logic uses a 0.9V rail. Figure 8-11 shows a typical power supply example using a switching regulator for the digital 0.9V supply and low noise LDOs for the analog supplies. The voltage regulators must be sequenced for both power up and power down as shown in Section 8.4.

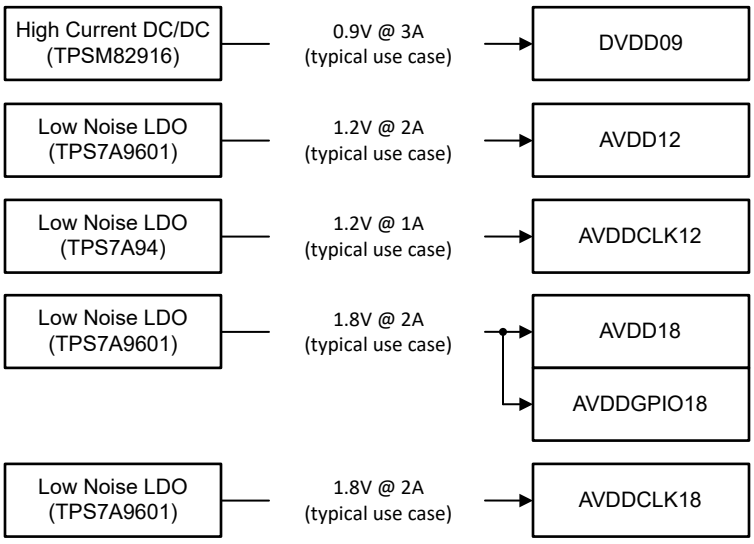


Figure 8-11. Power supply rails and regulator examples

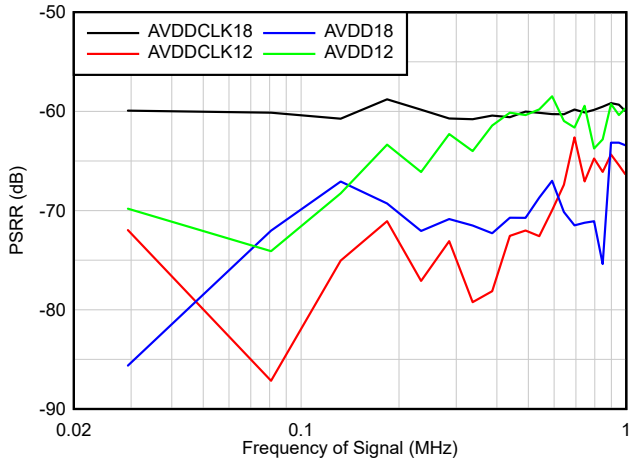


Figure 8-12. PSRR

8.6 Layout

8.6.1 Layout Guidelines

There are several critical signals which require specific care during board design:

1. Analog input and clock signals
   - Traces must be as short as possible and vias must be avoided where possible to minimize impedance discontinuities.
   - Traces must be routed using loosely coupled 100Ω differential traces.
   - Differential trace lengths must be matched as close as possible to minimize phase imbalance and HD2 degradation.
2. Digital JESD204B/C output interface
   - Traces must be routed using tightly coupled 100Ω differential traces.
3. Power and ground connections
   - Provide low resistance connection paths to all power and ground pins.
   - Use power and ground planes instead of traces.
   - Avoid narrow, isolated paths which increase the connection resistance.
   - Use a signal/ground/power circuit board stackup to maximize coupling between the ground and power plane.

8.6.2 Layout Example

The following screen shots show the top and bottom layer of the ADC32RF7x EVM.

- The input signal traces are routed as differential, tightly coupled traces on the top layer of the EVM. Care is taken to maintain symmetry between positive and negative input with matched trace length to minimize phase imbalance. Similar for the sampling clock input.
- JESD204B/C output interface lanes are routed differential and length matched on the top layer.
- Bypass caps are close to the power pins on the bottom layer.

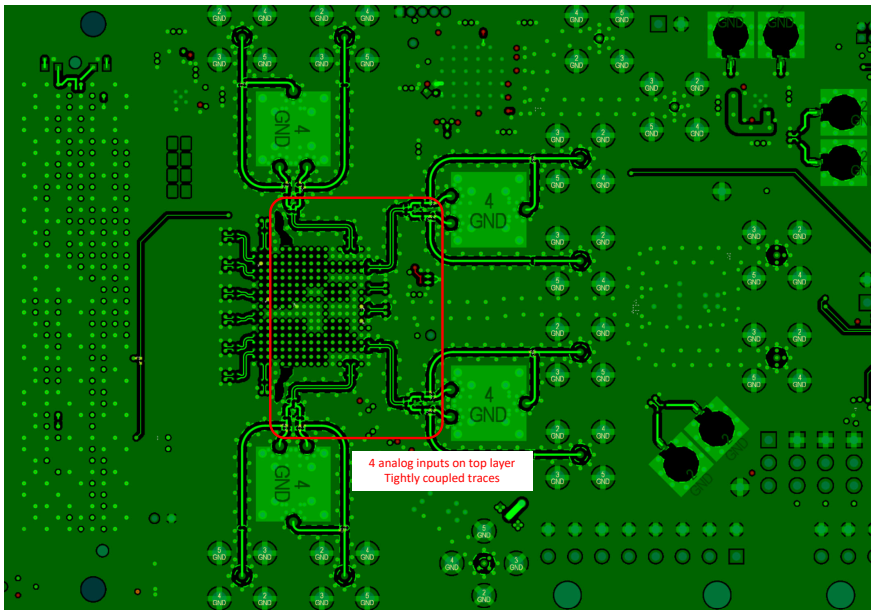


Figure 8-13. Top Layer

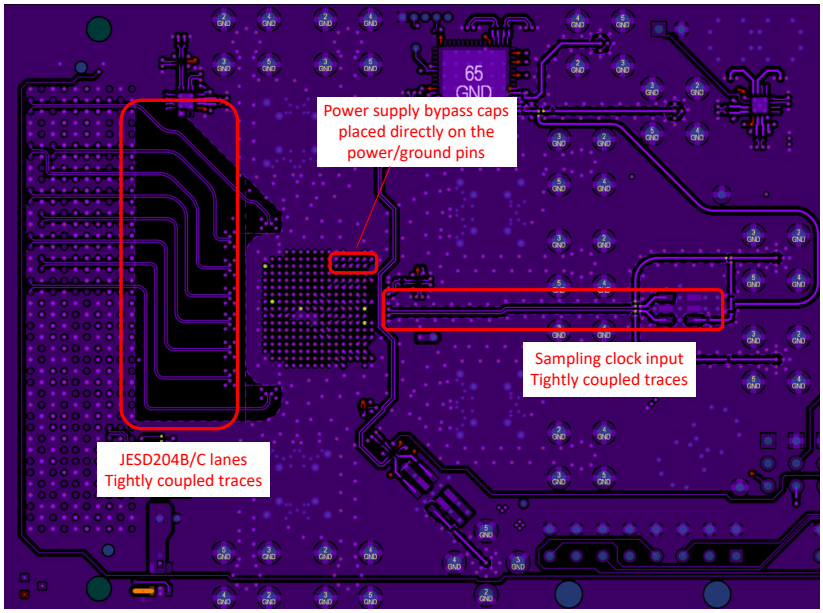


Figure 8-14. Bottom Layer

9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

9.1 Documentation Support

9.1.1 Related Documentation

- Texas Instruments, *Evaluating High-Speed, RF ADC Converter Front-end Architectures* application note

9.1.2 Third-Party Products Disclaimer

TI'S PUBLICATION OF INFORMATION REGARDING THIRD-PARTY PRODUCTS OR SERVICES DOES NOT CONSTITUTE AN ENDORSEMENT REGARDING THE SUITABILITY OF SUCH PRODUCTS OR SERVICES OR A WARRANTY, REPRESENTATION OR ENDORSEMENT OF SUCH PRODUCTS OR SERVICES, EITHER ALONE OR IN COMBINATION WITH ANY TI PRODUCT OR SERVICE.

9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

9.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.6 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
November 2025	*	Initial Release

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ADC32RF72IANH	Active	Production	FCCSP (ANH) | 289	119 | JEDEC TRAY (5+1)	Yes	Call TI | Other	Level-3-260C-168 HR	-	ADC32RF72

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

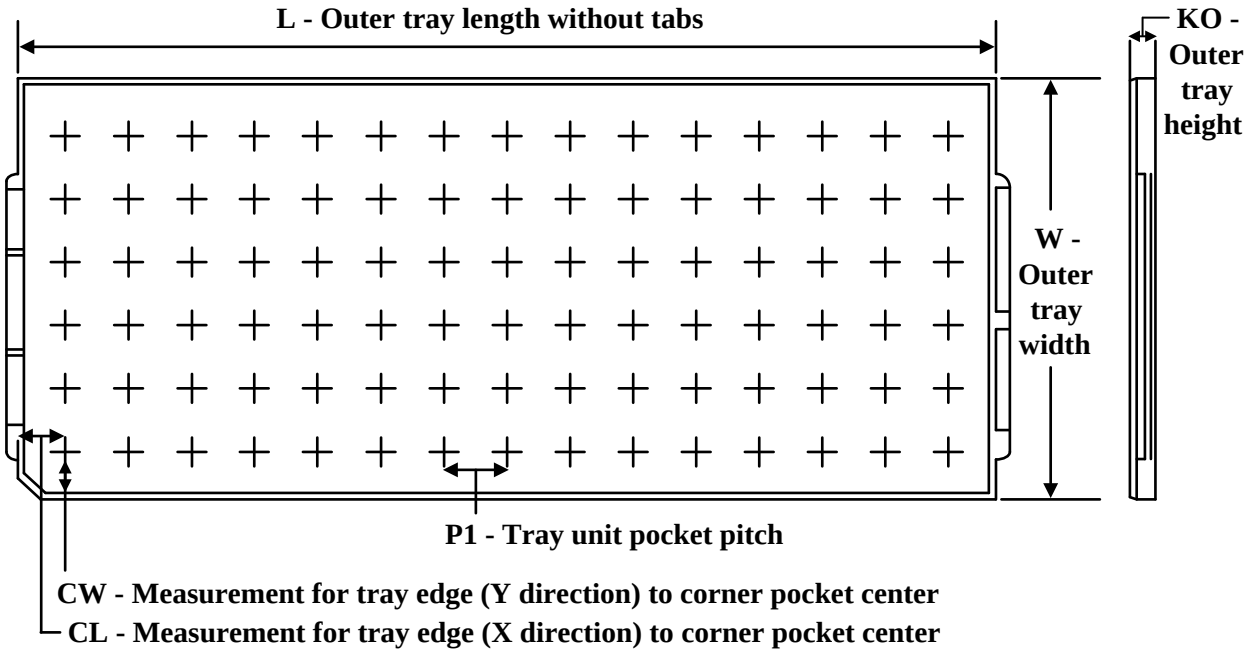
(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TRAY



Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

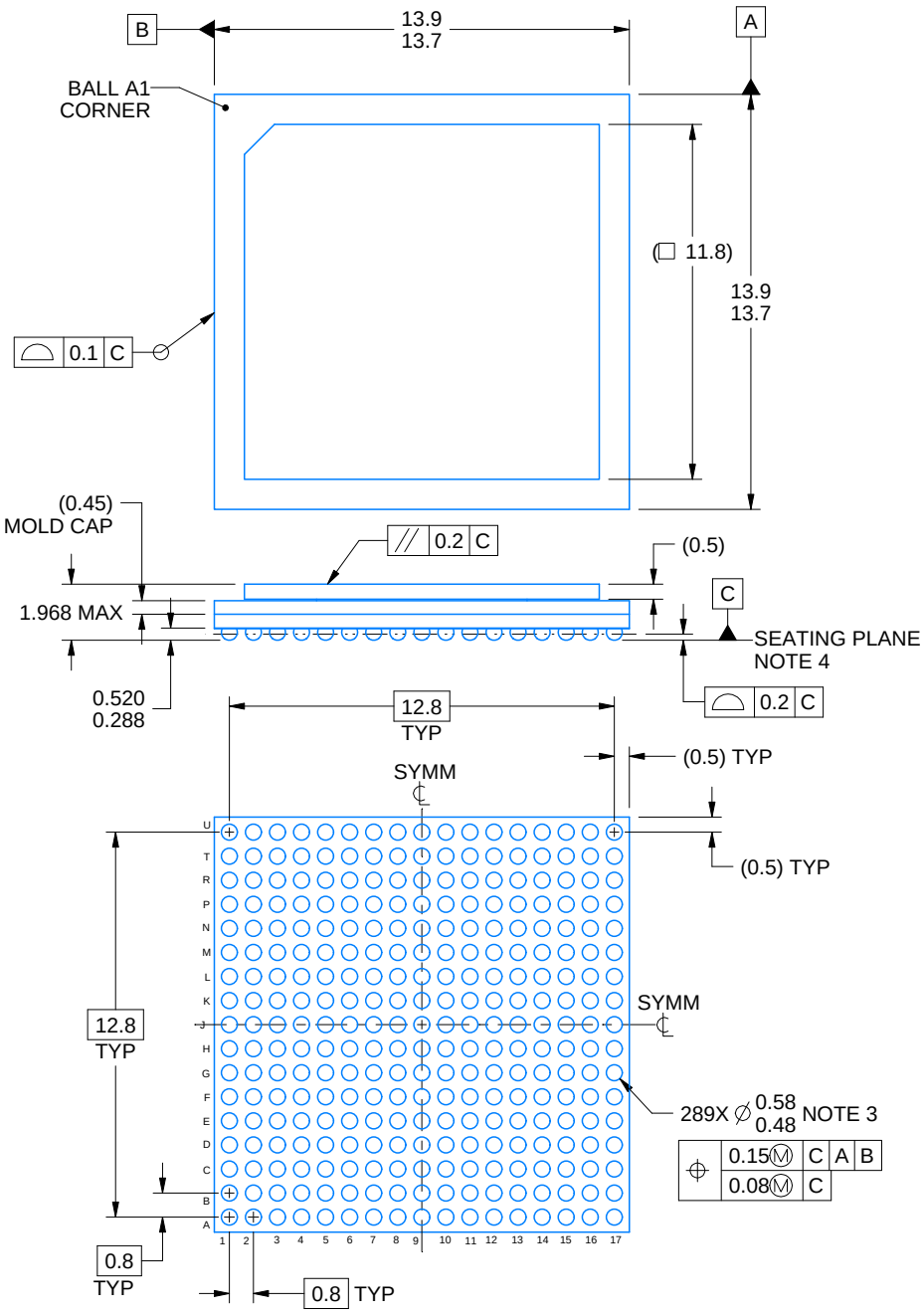
Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
ADC32RF72IANH	ANH	FCCSP	289	119	7 x 17	150	315	135.9	7620	18.1	12.7	12.9
ADC32RF72IANH	ANH	FCCSP	289	119	7 x 17	150	315	135.9	7620	18.1	12.7	12.9

PACKAGE OUTLINE

ANH0289A

FCCSP - 1.968 mm max height

BALL GRID ARRAY



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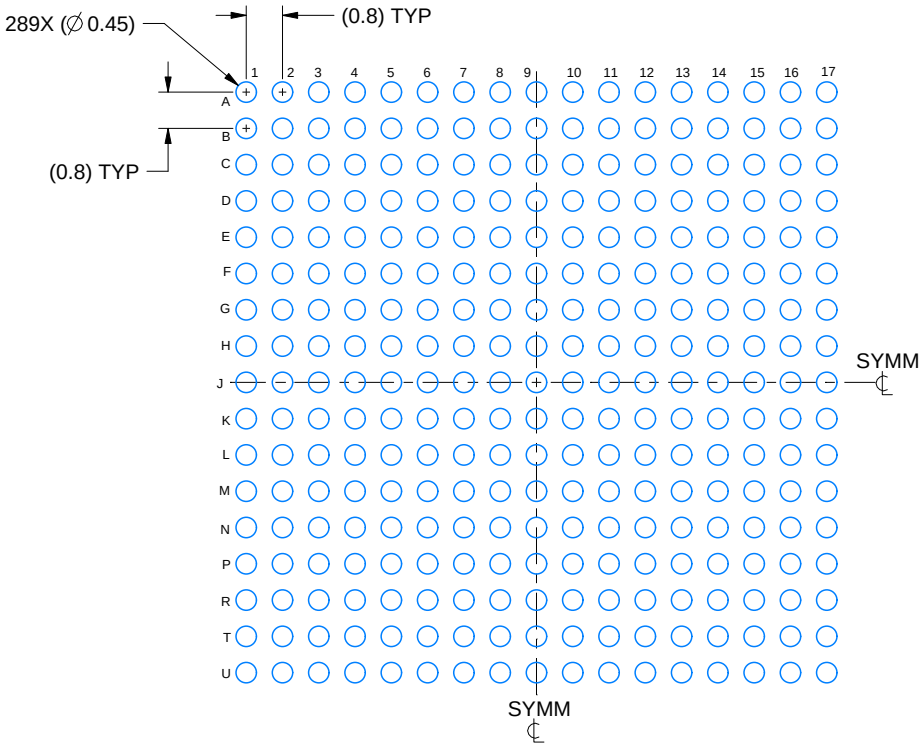
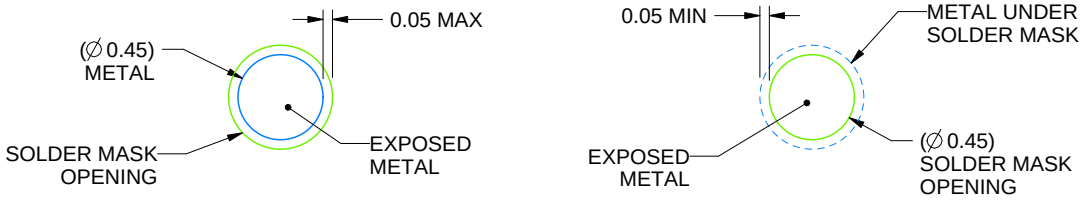
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Dimension is measured at the maximum solder ball diameter, post reflow, parallel to primary datum C.
4. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 6X

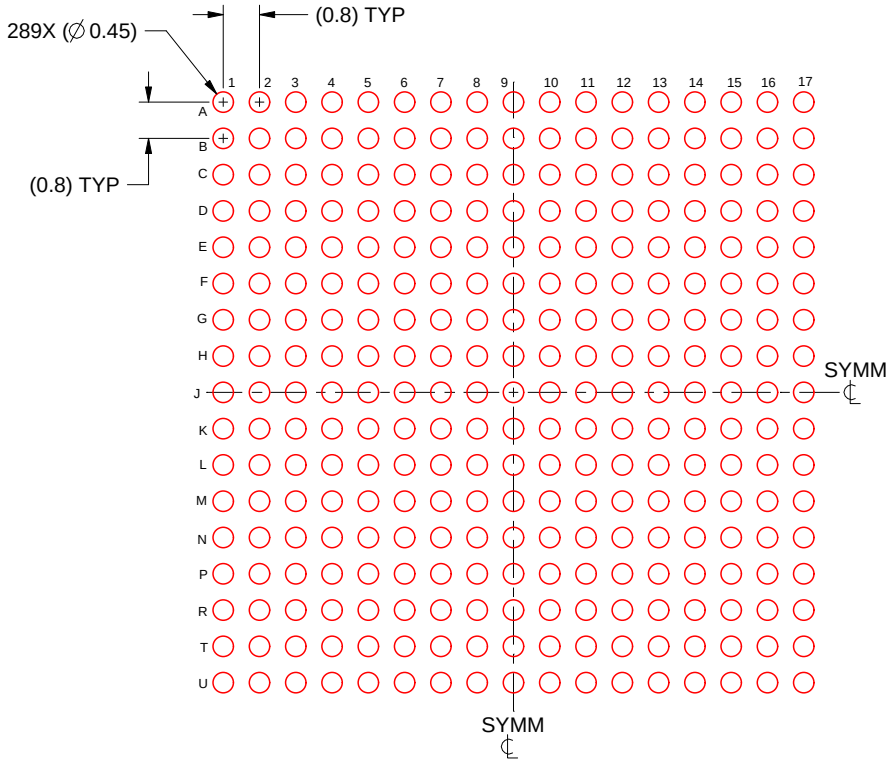


SOLDER MASK DETAILS
NOT TO SCALE

4230247/C 03/2024

NOTES: (continued)

5. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.
See Texas Instruments Literature No. SPRU811 (www.ti.com/lit/spru811).



SOLDER PASTE EXAMPLE
BASED ON 0.15 mm THICK STENCIL
SCALE: 6X

4230247/C 03/2024

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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